

Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

/!\ REMINDERS

Product Information in this Catalog

Product information in this catalog is as of October 2019. All of the contents specified herein and production status of the products listed in this catalog are subject to change without notice due to technical improvement of our products, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

Approval of Product Specifications

Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available. When using our products, please be sure to approve our product specifications or make a written agreement on the product specification with TAIYO YUDEN in advance.

Pre-Evaluation in the Actual Equipment and Conditions

Please conduct validation and verification of our products in actual conditions of mounting and operating environment before using our products.

Limited Application

1. Equipment Intended for Use

The products listed in this catalog are intended for generalpurpose and standard use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC) and other equipment specified in this catalog or the individual product specification sheets.

TAIYO YUDEN has the line-up of the products intended for use in automotive electronic equipment, telecommunications infrastructure and industrial equipment, or medical devices classified as GHTF Classes A to C (Japan Classes I to III). Therefore, when using our products for these equipment, please check available applications specified in this catalog or the individual product specification sheets and use the corresponding products.

2. Equipment Requiring Inquiry

Please be sure to contact TAIYO YUDEN for further information before using the products listed in this catalog for the following equipment (excluding intended equipment as specified in this catalog or the individual product specification sheets) which may cause loss of human life, bodily injury, serious property damage and/or serious public impact due to a failure or defect of the products and/or malfunction attributed thereto.

- (1) Transportation equipment (automotive powertrain control system, train control system, and ship control system, etc.)
- (2) Traffic signal equipment
- (3) Disaster prevention equipment, crime prevention equipment
- (4) Medical devices classified as GHTF Class C (Japan Class III)
- (5) Highly public information network equipment, dataprocessing equipment (telephone exchange, and base station, etc.)
- (6) Any other equipment requiring high levels of quality and/or reliability equal to the equipment listed above

3. Equipment Prohibited for Use

Please do not incorporate our products into the following equipment requiring extremely high levels of safety and/or reliability.

- (1) Aerospace equipment (artificial satellite, rocket, etc.)
- (2) Aviation equipment *1
- (3) Medical devices classified as GHTF Class D (Japan Class IV), implantable medical devices *2

- (4) Power generation control equipment (nuclear power, hydroelectric power, thermal power plant control system, etc.)
- (5) Undersea equipment (submarine repeating equipment, underwater work equipment, etc.)
- (6) Military equipment
- (7) Any other equipment requiring extremely high levels of safety and/or reliability equal to the equipment listed above

*Notes:

- 1. There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.
- Implantable medical devices contain not only internal unit which is implanted in a body, but also external unit which is connected to the internal unit.

4. Limitation of Liability

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment that is not intended for use by TAIYO YUDEN, or any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

Safety Design

When using our products for high safety and/or reliability-required equipment or circuits, please fully perform safety and/or reliability evaluation. In addition, please install (i) systems equipped with a protection circuit and a protection device and/or (ii) systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault for a failsafe design to ensure safety.

Intellectual Property Rights

Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.

Limited Warranty

Please note that the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a failure or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement

■ TAIYO YUDEN's Official Sales Channel

The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

Caution for Export

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

MULTILAYER CERAMIC CAPACITORS

MULTILAYER CERAMIC CAPACITORS



PARTS NUMBER

J	М	Κ	3	1	6	Δ	В	J	1	0	6	М	L	_	Т	Δ
1	2	3		4		⑤	(3)		7		8	9	10	11)	12

△=Blank space

(1)F	Rated	vol	tage

Code	Rated voltage[VDC]
Р	2.5
Α	4
J	6.3
L	10
E	16
Т	25
G	35
U	50
Н	100
Q	250
S	630
Х	2000

Code	End termination
K	Plated
S	Cu Internal Electrodes (For High Frequency)

(4)Dimension (L × W)

3End termination

4 Dimension (L × W)							
Туре	Dimensions (L×W)[mm]	EIA (inch)					
021	0.25 × 0.125	008004					
042	0.4 × 0.2	01005					
063	0.6 × 0.3	0201					
105	1.0 × 0.5	0402					
105	0.52 × 1.0 💥	0204					
107	1.6 × 0.8	0603					
107	0.8 × 1.6 💥	0306					
212	2.0 × 1.25	0805					
212	1.25 × 2.0 💥	0508					
316	3.2 × 1.6	1206					
325	3.2 × 2.5	1210					
432	4.5 × 3.2	1812					
	/						

Note : $\mbox{\ensuremath{\mbox{$\times$}}} LW$ reverse type ($\mbox{\ensuremath{\mbox{$W$}}} K)$ only

②Series name

Code	Series name
М	Multilayer ceramic capacitor
V	Multilayer ceramic capacitor for high frequency
W	LW reverse type multilayer capacitor

Code	Туре	L[mm]	W[mm]	T[mm]
Δ	ALL	Standard	Standard	Standard
	063	0.6 ± 0.05	0.3±0.05	0.3±0.05
	105	1.0±0.10	0.5±0.10	0.5±0.10
	107	1.6+0.15/-0.05	0.8+0.15/-0.05	0.8+0.15/-0.05
				0.45±0.05
Α	212	2.0+0.15/-0.05	1.25+0.15/-0.05	0.85±0.10
				1.25+0.15/-0.05
	316	3.2±0.20	1.6±0.20	0.85±0.10
	310	3.2±0.20	1.6±0.20	1.6±0.20
	325	3.2 ± 0.30	2.5±0.30	2.5±0.30
	063	0.6±0.09	0.3±0.09	0.3±0.09
	105	1.0+0.15/-0.05	0.5+0.15/-0.05	0.5+0.15/-0.05
	407	1.6+0.20/-0	0.8+0.20/-0	0.45 ± 0.05
В	107	1.0 + 0.20/ - 0	0.8 + 0.20/ - 0	0.8+0.20/-0
ь				0.45±0.05
	212	2.0+0.20/-0	1.25+0.20/-0	0.85±0.10
				1.25+0.20/-0
	316	3.2±0.30	1.6±0.30	1.6±0.30
С	105	1.0+0.20/-0	0.5+0.20/-0	0.5+0.20/-0
	063	0.6 + 0.25/- 0	0.3 + 0.25/- 0	0.3 + 0.25/ - 0
E	105	1.0+0.30/-0	0.5+0.30/-0	0.5+0.30/-0

Note: cf. STANDARD EXTERNAL DIMENSIONS

△= Blank space

6 Temperature characteristics code

■ High dielectric type (Excluding Super low distortion multilayer ceramic capacitor)

Code	Applicable standard		Temperature range[°C]	Ref. Temp.[°C]	Capacitance change	Capacitance tolerance	Tolerance code			
	JIS	В	-25~+ 85	20	±10%	±10%	K			
BJ	JIS	Ь	-25°° + 65	20	± 10%	±20%	М			
БО	EIA	X5R	-55 ~ + 85	25	±15%	±10%	K			
	EIA	ASK	_55~+ 85		土13%	±20%	М			
В7	EIA	X7R	-55~+125	25	±15%	±10%	K			
Б/	LIA A	λ/Κ	33.5 1 123	2.5	±1370	±20%	М			
C6	EIA X6S	EIA X6S	X6S	-55~+105	25	±22%	±10%	K		
				702	702	702	702	702	702	-55.4 + 105
C7	EIA	X7S	-55~+125	25	±22%	±10%	K			
C/	EIA	A X/S	-55 ~ +125	25	±22%	±20%	М			
LD(※)			55 05	0.5	1.450/	±10%	K			
	EIA X5R	EIA X5R −55~+ 85 25	25	±15%	±20%	М				

Note: X.LD Low distortion high value multilayer ceramic capacitor

∆= Blank space

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for General Electronic Equipment

■Temperature compensating type

Code	Applicable standard		Temperature range[°C]	Ref. Temp.[°C]	Capacitance change	Capacitance tolerance	Tolerance code
			_			±0.05pF	Α
						±0.1pF	В
CG	EIA	C0G	-55 ~ +125	25	0 ± 30 ppm/°C	±0.25pF	С
						±0.5pF	D
						±5%	J
	JIS	UJ		20		±0.25pF	С
UJ	JIS	UJ	-55 ~ +125	20	$-750 \pm 120 \text{ppm/}^{\circ}\text{C}$	±0.5pF	D
	EIA	U2J		25		±5%	J
UK	JIS	UK	−55~+125	20	-750+250nnm/°C	±0.255E	С
UK	EIA U2K	-55~+125	25	- 750±250ppm/°C	±0.25pF		

6 Series code

· Super low distortion multilayer ceramic capacitor

	·
Code	Series code
SD	Standard

• Medium-High Voltage Multilayer Ceramic Capacitor

Code	Series code
SD	Standard

Nominal capacitance

Code (example)	Nominal capacitance
0R5	0.5pF
010	1pF
100	10pF
101	100pF
102	1,000pF
103	10,000pF
104	0.1 <i>μ</i> F
105	1.0 <i>μ</i> F
106	10 μ F
107	100 μ F

Note: R=Decimal point

8Capacitance tolerance

Code	Capacitance tolerance
Α	±0.05pF
В	±0.1pF
С	±0.25pF
D	±0.5pF
F	±1pF
G	±2%
J	±5%
K	±10%
М	±20%
Z	+80/-20%

Thickness

Code	Thickness[mm]
K	0.125
Н	0.13
E	0.18
С	0.2
D	0.2
Р	0.2
Т	0.3
K	0.45(107type or more)
V	0.5
W	0.5
Α	0.8
D	0.85(212type or more)
F	1.15
G	1.25
L	1.6
N	1.9
Υ	2.0 max
М	2.5

10Special code

Code	Special code
_	Standard

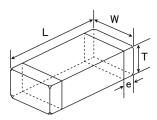
11)Packaging

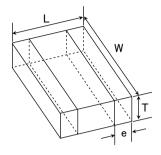
Packaging
ϕ 178mm Taping (2mm pitch)
ϕ 178mm Taping (4mm pitch)
\$\phi\$178mm Taping (4mm pitch, 1000 pcs/reel)
325 type (Thickness code M)
\$\phi\$178mm Taping (2mm pitch)105type only
(Thickness code E,H)
ϕ 178mm Taping(1mm pitch)021/042type only

12Internal code

UZINCENIAI COUE	
Code	Internal code
Δ	Standard

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LW reverse type

T/ FIA \		D	imension [mm]				
Type(EIA)	L	W	Т	*1	е		
☐MK021 (008004)	0.25±0.013	0.125±0.013	0.125±0.013	K	0.0675±0.0275		
□VS021 (008004)	0.25±0.013	0.125±0.013	0.125±0.013	K	0.0675±0.0275		
□MK042(01005)	0.4±0.02	0.2±0.02	0.2±0.02	С	0.1±0.03		
□MK042(01003)	0.4±0.02	0.2±0.02	0.2±0.02	D	0.1±0.03		
□VS042 (01005)	0.4±0.02	0.2±0.02	0.2±0.02	С	0.1±0.03		
DMK000(0001)	0.01.000	0.01.000	0.0.1.0.00	Р	0.15 0.05		
□MK063(0201)	0.6±0.03	0.3±0.03	0.3±0.03	Т	0.15±0.05		
			0.13±0.02	Н			
			0.18±0.02	Е			
☐MK105(0402)	1.0±0.05	0.5 ± 0.05	0.2 ± 0.02	С	0.25±0.10		
			0.3±0.03	Р			
			0.5±0.05	٧			
□VK105(0402)	1.0±0.05	0.5±0.05	0.5±0.05	W	0.25±0.10		
□WK105(0204)※	0.52±0.05	1.0±0.05	0.3 ± 0.05	Р	0.18±0.08		
□MK107(0603)	1.6±0.10	0.8±0.10	0.45±0.05	K	0.35±0.25		
LIMK107(0003)	1.0±0.10	0.8±0.10	0.8±0.10	Α	0.35±0.25		
□WK107(0306)※	0.8±0.10	1.6±0.10	0.5±0.05	٧	0.25±0.15		
			0.45±0.05	K			
□MK212(0805)	2.0±0.10	1.25±0.10	0.85±0.10	D	0.5 ± 0.25		
			1.25±0.10	G			
□WK212(0508)※	1.25±0.15	2.0±0.15	0.85±0.10	D	0.3±0.2		
			0.85 ± 0.10	D			
□MK316(1206)	3.2±0.15	1.6±0.15	1.15±0.10	F	0.5 + 0.35 / -0.25		
			1.6±0.20	L			
			0.85±0.10	D			
			1.15±0.10	F			
□MK325(1210)	3.2 ± 0.30	2.5±0.20	1.9±0.20	N	0.6 ± 0.3		
			1.9+0.1/-0.2	Υ			
			2.5±0.20	М			
□MK432(1812)	4.5 ± 0.40	2.2.4.0.20	2.0+0/-0.30	Υ	0.6±0.4		
LINK432 (1812)	4.5±0.40	3.2±0.30	2.5±0.20	М	0.9±0.6		

Note: ※. LW reverse type, *1.Thickness code

STANDARD QUANTITY

т	EIA (inch)	Dime	nsion	Standard qu	uantity[pcs]
Туре	EIA (Inch)	[mm]	Code	Paper tape	Embossed tape
021	008004	0.125	K	_	50000
040	042 01005	0.2	С		40000
042	01005	0.2	D	_	40000
063	0201	0.3	P	15000	
003	0201	0.3	Т	15000	_
		0.13	Н	_	20000
		0.18	Е	_	15000
	0400	0.2	С	20000	_
105	0402	0.3	Р	15000	_
		0.5	V		
		0.5	W	10000	_
	0204 ※	0.30	P		
	0602	0.45	K	4000	
107	0003	0.8	Α	4000	_
	0306 ※	0.50	V	_	4000
		0.45	K	4000	
212	0603 0306	0.85	D	4000	_
212	Ī	1.25	G	-	3000
	0508 ※	0.85	D	4000	_
		0.85	D	4000	_
316	1206	1.15	F	_	3000
	ſ	1.6	L,	-	2000
		0.85	D		
		1.15	F		
325	1210	1210 1.9 N 2.0 max Y] _	2000
		2.5	М	_	1000
432	1812	2.0 max	Υ	_	1000
432	1812	2.5	М	_	500

Note : ※.LW Reverse type(□WK)

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CERAMIC CAPACITORS

- All the Multilayer Ceramic Capacitors of the catalog lineup are RoHS Compliant.
- Capacitance tolerance code is applied to [] of part number.

Note)

- *1 We may provide X7R/X7S for some items according to the individual specification.
- *2 The exchange of individual specification is necessary depending on the application and circuit condition. Please contact TAIYO YUDEN sales channels.
- *3 The size standard should look at @Dimension, @Dimension tolerance, and @Thickness, and STANDARD EXTERNAL DIMENSIONS.

Multilayer Ceramic Capacitors (High dielectric type)

●021TYPE

[Temperature Characteristic BJ : $X5R(-55 \sim +85^{\circ}C)$] 0.125mm thickness(K)

Part number 1 Part num	Part number 2	Rated voltage	Temperature Capacitance characteristics [F]		Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Part number 1	Part number 2	[V]			[F]	[%]	[%]	Rated voltage x %	Thickness [mm]	W:Wave
EMK021 BJ221[K-W				X5R	220 p	±10, ±20	10	150	0.125±0.013	R
EMK021 BJ471[K-W		16		X5R	470 p	±10, ±20	10	150	0.125±0.013	R
EMK021 BJ102[]K-W				X5R	1000 p	±10, ±20	10	150	0.125±0.013	R
JMK021 BJ222 K-W				X5R	2200 p	±10, ±20	10	150	0.125±0.013	R
JMK021 BJ472[K-W		6.3		X5R	4700 p	±10, ±20	10	150	0.125±0.013	R
JMK021 BJ103∏K-W				X5R	0.01 μ	±10, ±20	10	150	0.125±0.013	R
AMK021 BJ223MK-W		4		X5R	0.022 μ	±20	10	150	0.125±0.013	R

●042TYPE

Temperature Charac	teristic BJ : B(-2	5 ~ +85℃),	/X5R(-	-55 ~ +	·85°C)] 0.2	2mm thickness(C)				
		Rated voltage	Temperature		Capacitance	Capacitance tolerance	tan δ	HTLT	#2	Soldering
Part number 1	Part number 2	[V]	charact		[F]	[%]	Fo / 7	Rated voltage x %	Thickness*3 [mm]	R:Reflow
EMK042 BJ101∏C-W			1	X5R	100 p	±10, ±20	5	200	0.2±0.02	W:Wave R
EMK042 BJ151∏C-W		1		X5R	150 p	±10, ±20 ±10. ±20	5	200	0.2±0.02	R
EMK042 BJ151 C-W		-		X5R X5R	220 p	±10, ±20 ±10. ±20	5	200	0.2±0.02 0.2±0.02	R
				X5R X5R		*	5			
EMK042 BJ331 C-W		4			330 p	±10, ±20	5	200	0.2±0.02	R
EMK042 BJ471 C-W				X5R	470 p	±10, ±20	5	200	0.2±0.02	R
EMK042 BJ681 C-W				X5R	680 p	±10, ±20		200	0.2±0.02	R
EMK042 BJ102 C-W		16	В	X5R	1000 p	±10, ±20	5	200	0.2±0.02	R
EMK042 BJ152 C-W				X5R	1500 p	±10, ±20	10	150	0.2 ± 0.02	R
EMK042 BJ222 C-W				X5R	2200 p	±10, ±20	10	150	0.2 ± 0.02	R
EMK042 BJ332 C-W]		X5R	3300 p	±10, ±20	10	150	0.2 ± 0.02	R
EMK042 BJ472 C-W]		X5R	4700 p	±10, ±20	10	150	0.2 ± 0.02	R
EMK042 BJ682 C-W]		X5R	6800 p	±10, ±20	10	150	0.2 ± 0.02	R
EMK042 BJ103[]C-W				X5R	0.01 μ	±10, ±20	10	150	0.2 ± 0.02	R
LMK042 BJ101[]C-W				X5R*1	100 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 BJ151∏C-W]		X5R*1	150 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 BJ221∏C-W				X5R*1	220 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 BJ331∏C-W				X5R*1	330 р	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 BJ471∏C-W				X5R*1	470 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 BJ681∏C-W				X5R*1	680 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 BJ102[]C-W		10	В	X5R*1	1000 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 BJ152[]C-W				X5R	1500 p	±10, ±20	10	150	0.2 ± 0.02	R
LMK042 BJ222 C-W				X5R	2200 p	±10, ±20	10	150	0.2 ± 0.02	R
LMK042 BJ332∏C-W				X5R	3300 р	±10, ±20	10	150	0.2 ± 0.02	R
LMK042 BJ472∏C-W]		X5R	4700 p	±10, ±20	10	150	0.2 ± 0.02	R
LMK042 BJ682∏C-W]		X5R	6800 p	±10, ±20	10	150	0.2 ± 0.02	R
LMK042 BJ103∏C-W]		X5R	0.01 μ	±10, ±20	10	150	0.2 ± 0.02	R
JMK042 BJ152∏C-W				X5R*1	1500 p	±10, ±20	10	150	0.2 ± 0.02	R
JMK042 BJ222∏C-W		1		X5R*1	2200 p	±10, ±20	10	150	0.2 ± 0.02	R
JMK042 BJ332∏C-W		1		X5R*1	3300 р	±10, ±20	10	150	0.2 ± 0.02	R
JMK042 BJ472∏C-W				X5R*1	4700 p	±10, ±20	10	150	0.2 ± 0.02	R
JMK042 BJ682∏C-W		6.3		X5R*1	6800 p	±10, ±20	10	150	0.2 ± 0.02	R
JMK042 BJ103∏C-W		1		X5R*1	0.01 μ	±10, ±20	10	150	0.2±0.02	R
JMK042 BJ223∏C-W		1		X5R	0.022 μ	±10, ±20	10	150	0.2±0.02	R
JMK042 BJ473 C-W		1		X5R	0.047 μ	±10, ±20	10	150	0.2±0.02	R
JMK042 BJ104□C-W		1		X5R	0.1 μ	±10, ±20	10	150	0.2±0.02	R
AMK042 BJ473[]C-W		t		X5R	0.047 μ	±10, ±20	10	150	0.2±0.02	R
AMK042 BJ104∏C-W		4		X5R	0.1 μ	±10, ±20	10	150	0.2±0.02	R
				,,,,,,	υ μ	,			5.E = 5.5E	

Temperature Charac	cteristic B7 : X7R(-	-55 ~ +125	´C)】 0.2mm th	ickness(C)					
Part number 1 Part	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Fart number 1	Fart number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Inickness [mm]	W:Wave
EMK042 B7101 C-W			X7R	100 p	±10, ±20	5	200	0.2 ± 0.02	R
EMK042 B7151 C-W			X7R	150 p	±10, ±20	5	200	0.2 ± 0.02	R
EMK042 B7221 C-W			X7R	220 p	±10, ±20	5	200	0.2 ± 0.02	R
EMK042 B7331 ☐ C-W		16	X7R	330 p	±10, ±20	5	200	0.2 ± 0.02	R
EMK042 B7471 C-W			X7R	470 p	±10, ±20	5	200	0.2 ± 0.02	R
EMK042 B7681 ☐ C-W			X7R	680 p	±10, ±20	5	200	0.2 ± 0.02	R
EMK042 B7102[]C-W			X7R	1000 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 B7101 ☐ C-W			X7R	100 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 B7151 C-W			X7R	150 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 B7221 ☐ C-W			X7R	220 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 B7331 ☐ C-W		10	X7R	330 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 B7471 ☐ C-W			X7R	470 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 B7681 ☐ C-W			X7R	680 p	±10, ±20	5	200	0.2 ± 0.02	R
LMK042 B7102[]C-W			X7R	1000 p	±10, ±20	5	200	0.2 ± 0.02	R

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●063TYPE

[Temperature Characteristic BJ : $B(-25 \sim +85^{\circ}C)/X5R(-55 \sim +85^{\circ}C)$] 0.3mm thickness(P)

		Rated voltage	Temperature		Capacitance	Capacitance tolerance	tan δ	HTLT	**	Soldering
Part number 1	Part number 2	[V]		teristics	[F]	[%]	[%]	Rated voltage x %	Thickness*3 [mm]	R:Reflow W:Wave
UMK063 BJ101[]P-F			В	X5R*1	100 p	±10, ±20	3.5	200	0.3±0.03	R
UMK063 BJ151[]P-F			В	X5R*1	150 p	±10, ±20	3.5	200	0.3±0.03	R
UMK063 BJ221 P-F		1	В	X5R*1	220 p	±10, ±20	3.5	200	0.3±0.03	R
UMK063 BJ331∏P-F		1	В	X5R*1	330 p	±10, ±20	3.5	200	0.3±0.03	R
UMK063 BJ471[P-F		1	В	X5R*1	470 p	±10, ±20	3.5	200	0.3±0.03	R
UMK063 BJ681∏P-F		1	В	X5R*1	g 086	±10, ±20	3.5	200	0.3±0.03	R
UMK063 BJ102∏P-F		50	В	X5R*1	q 0001	±10, ±20	3.5	200	0.3±0.03	R
UMK063 BJ152∏P-F		1	В	X5R	1500 p	±10, ±20	5	200	0.3±0.03	R
UMK063 BJ222∏P-F		1	В	X5R	2200 p	±10, ±20	5	200	0.3±0.03	R
UMK063 BJ332∏P-F		1	В	X5R	3300 p	±10, ±20	5	200	0.3±0.03	R
UMK063 BJ472∏P-F		1	В	X5R	4700 p	±10, ±20	5	200	0.3±0.03	R
UMK063 BJ682∏P-F		1	В	X5R	6800 p	±10, ±20	5	200	0.3±0.03	R
UMK063 BJ103[]P-F			В	X5R	0.01 μ	±10, ±20	5	200	0.3±0.03	R
GMK063 BJ104∏P-F		35		X5R	0.1 μ	±10, ±20	10	150	0.3 ± 0.03	R
TMK063 BJ152[]P-F			В	X5R	1500 p	±10, ±20	5	200	0.3 ± 0.03	R
TMK063 BJ222∏P-F		1	В	X5R	2200 p	±10, ±20	5	200	0.3±0.03	R
TMK063 BJ332 P-F		1	В	X5R	3300 p	±10, ±20	5	200	0.3±0.03	R
TMK063 BJ472[]P-F		25	В	X5R	4700 p	±10, ±20	5	200	0.3±0.03	R
TMK063 BJ682[]P-F		25	В	X5R	6800 p	±10, ±20	5	200	0.3±0.03	R
TMK063 BJ103[]P-F			В	X5R	0.01 μ	±10, ±20	5	200	0.3 ± 0.03	R
TMK063 BJ223[]P-F			В	X5R	0.022 μ	±10, ±20	7.5	200	0.3 ± 0.03	R
TMK063ABJ104∏P-F				X5R	0.1 μ	±10, ±20	10	150	0.3 ± 0.05	R
EMK063 BJ152[]P-F			В	X5R*1	1500 p	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 BJ222 P-F			В	X5R*1	2200 p	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 BJ332∏P-F			В	X5R*1	3300 p	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 BJ472[]P-F			В	X5R*1	4700 p	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 BJ682[P-F			В	X5R*1	6800 p	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 BJ103[]P-F			В	X5R*1	0.01 μ	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 BJ153[P-F		16		X5R	0.015 μ	±10, ±20	7.5	200	0.3 ± 0.03	R
EMK063 BJ223[P-F		10	В	X5R	0.022 μ	±10, ±20	7.5	200	0.3 ± 0.03	R
EMK063 BJ333∏P-F				X5R	0.033 μ	±10, ±20	7.5	150	0.3 ± 0.03	R
EMK063 BJ473[]P-F				X5R	0.047 μ	±10, ±20	7.5	150	0.3 ± 0.03	R
EMK063 BJ683∏P-F				X5R	0.068 μ	±10, ±20	10	150	0.3 ± 0.03	R
EMK063 BJ104[]P-F				X5R	0.1 μ	±10, ±20	10	150	0.3 ± 0.03	R
EMK063 BJ224[]P-F		」		X5R	0.22 μ	±10, ±20	10	150	0.3 ± 0.03	R
EMK063BBJ474[]PLF				X5R	0.47 μ	±10, ±20	10	150	0.3 ± 0.09	R
LMK063 BJ223∏P-F			В	X5R	0.022 μ	±10, ±20	7.5	150	0.3 ± 0.03	R
LMK063 BJ333∏P-F				X5R	0.033 μ	±10, ±20	7.5	150	0.3 ± 0.03	R
LMK063 BJ473∏P-F				X5R	0.047 μ	±10, ±20	7.5	150	0.3 ± 0.03	R
LMK063 BJ683∏P-F		10		X5R	0.068 μ	±10, ±20	10	150	0.3 ± 0.03	R
LMK063 BJ104□P-F				X5R	0.1 μ	±10, ±20	10	150	0.3 ± 0.03	R
LMK063 BJ224□P-F		」		X5R	0.22 μ	±10, ±20	10	150	0.3 ± 0.03	R
LMK063BBJ474 PLF		_		X5R	0.47 μ	±10, ±20	10	150	0.3±0.09	R
LMK063BBJ105MPLF		<u> </u>		X5R	1 μ	±20	10	150	0.3±0.09	R
JMK063 BJ104∏P-F		4 ,		X5R	0.1 μ	±10, ±20	10	150	0.3 ± 0.03	R
JMK063 BJ224□P-F		4 ,		X5R	0.22 μ	±10, ±20	10	150	0.3 ± 0.03	R
JMK063 BJ334MP-F		6.3		X5R	0.33 μ	±20	10	150	0.3 ± 0.03	R
JMK063 BJ474[P-F		_		X5R	0.47 μ	±10, ±20	10	150	0.3±0.03	R
JMK063ABJ105∏P-F		 		X5R	1 μ	±10, ±20	10	150	0.3±0.05	R
PMK063EBJ475MP-F		2.5		X5R	4.7 μ	±20	10	150	0.3+0.25/-0	R

[Temperature Characteristic C6 : $X6S(-55 \sim +105^{\circ}C)$] 0.3mm thickness(P)

Li emperature Griarat	ceristic Co . Aus (=	-33.5 + 103	C/1 0.31	mm tri	ickness (F)					
Part number 1 Part number 2	Davit woundhau 2	Rated voltage	Temperature Capacita		Capacitance	itance Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
	Part number 2	[V]	character	istics	[F]	[%]	[%]	Rated voltage x %	I hickness [mm]	W:Wave
TMK063 C6104[]P-F		25		X6S	0.1 μ	±10, ±20	10	150	0.3 ± 0.03	R
EMK063AC6104[]P-F		16		X6S	0.1 μ	±10, ±20	10	150	0.3 ± 0.05	R
LMK063 C6104[P-F				X6S	0.1 μ	±10, ±20	10	150	0.3 ± 0.03	R
LMK063 C6224[]P-F		10		X6S	0.22 μ	±10, ±20	10	150	0.3 ± 0.03	R
LMK063BC6474[]PLF				X6S	0.47 μ	±10, ±20	10	150	0.3 ± 0.09	R
JMK063 C6104[]P-F				X6S	0.1 μ	±10, ±20	10	150	0.3 ± 0.03	R
JMK063 C6224[]P-F		6.3		X6S	0.22 μ	±10, ±20	10	150	0.3 ± 0.03	R
JMK063BC6474∏P-F		0.5		X6S	0.47 μ	±10, ±20	10	150	0.3 ± 0.09	R
JMK063BC6105MP-F				X6S	1 μ	±20	10	150	0.3 ± 0.09	R
AMK063 C6474 ☐P-F		4		X6S	0.47 μ	±10, ±20	10	150	0.3±0.03	R
AMK063AC6105∏P-F		4		X6S	1 μ	±10, ±20	10	150	0.3±0.05	R

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MULTILAYER CERAMIC CAPACITORS

[Temperature Characteristic B7 : $X7R(-55 \sim +125^{\circ}C)$] 0.3mm thickness(P)

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	tan δ	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Part number I	Part number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Thickness [mm]	W:Wave
UMK063 B7101[P-F			X7R	100 p	±10, ±20	3.5	200	0.3 ± 0.03	R
UMK063 B7151[P-F			X7R	150 p	±10, ±20	3.5	200	0.3 ± 0.03	R
UMK063 B7221 P−F			X7R	220 p	±10, ±20	3.5	200	0.3 ± 0.03	R
UMK063 B7331 P−F		50	X7R	330 p	±10, ±20	3.5	200	0.3 ± 0.03	R
UMK063 B7471 P-F			X7R	470 p	±10, ±20	3.5	200	0.3 ± 0.03	R
UMK063 B7681∏P-F			X7R	680 p	±10, ±20	3.5	200	0.3 ± 0.03	R
UMK063 B7102[]P-F			X7R	1000 p	±10, ±20	3.5	200	0.3 ± 0.03	R
TMK063 B7152[]P-F			X7R	1500 p	±10, ±20	5	200	0.3 ± 0.03	R
TMK063 B7222[]P-F			X7R	2200 p	±10, ±20	5	200	0.3 ± 0.03	R
TMK063 B7332[]P-F		25	X7R	3300 p	±10, ±20	5	200	0.3 ± 0.03	R
TMK063 B7472[]P-F		20	X7R	4700 p	±10, ±20	5	200	0.3 ± 0.03	R
TMK063 B7682[]P-F			X7R	6800 p	±10, ±20	5	200	0.3 ± 0.03	R
TMK063 B7103[]P-F			X7R	0.01 μ	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 B7152[]P-F			X7R	1500 p	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 B7222[]P-F			X7R	2200 p	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 B7332[P-F			X7R	3300 p	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 B7472[]P-F		16	X7R	4700 p	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 B7682[]P-F			X7R	6800 p	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 B7103[]P-F			X7R	0.01 μ	±10, ±20	5	200	0.3 ± 0.03	R
EMK063 B7223∏P-F			X7R	0.022 μ	±10, ±20	7.5	150	0.3 ± 0.03	R

105TYPE

[Temperature Characteristic BJ : $B(-25 \sim +85^{\circ}C)/X5R(-55 \sim +85^{\circ}C)$] 0.5mm thickness(V)

Tremperature Onara	CLETISTIC DO . D \ Z	J- 1 00 C/,	/ NJIN(30 1	00 0/1 0.	JIIIII CIIICKIIESS (V)				
Part number 1	Part number 2	Rated voltage	Temp	erature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Part number 1	Fart Humber 2	[V]	charac	teristics	[F]	[%]	[%]	Rated voltage x %	Inickness [mm]	W:Wave
UMK105 BJ223 V-F				X5R	0.022 μ	±10, ±20	5	200	0.5±0.05	R
UMK105 BJ473[]V-F				X5R	0.047 μ	±10, ±20	5	200	0.5±0.05	R
UMK105 BJ104∏V-F		50		X5R	0.1 μ	±10, ±20	10	150	0.5 ± 0.05	R
UMK105 BJ224 UV-F		30		X5R	0.22 μ	±10, ±20	10	150	0.5±0.05	R
UMK105ABJ474∏V-F				X5R	0.47 μ	±10, ±20	10	150	0.5±0.10	R
UMK105CBJ105MV-F				X5R	1 μ	±20	10	150	0.5+0.20/-0	R
GMK105 BJ104□V-F		35	В	X5R	0.1 μ	±10, ±20	5	150	0.5±0.05	R
GMK105ABJ105∏V-F		35		X5R	1 μ	±10, ±20	10	150	0.5±0.10	R
TMK105 BJ153[]V-F			В	X5R*1	0.015 μ	±10, ±20	3.5	200	0.5±0.05	R
TMK105 BJ223[]V-F			В	X5R*1	0.022 μ	±10, ±20	3.5	200	0.5±0.05	R
TMK105 BJ333[]V-F			В	X5R*1	0.033 μ	±10, ±20	3.5	150	0.5±0.05	R
TMK105 BJ473[]V-F			В	X5R*1	0.047 μ	±10, ±20	3.5	150	0.5±0.05	R
TMK105 BJ104[]V-F		25	В	X5R	0.1 μ	±10, ±20	5	150	0.5±0.05	R
TMK105 BJ224[]V-F				X5R	0.22 μ	±10, ±20	10	200	0.5±0.05	R
TMK105ABJ474□V-F				X5R	0.47 μ	±10, ±20	10	200	0.5±0.10	R
TMK105 BJ105[]V-F				X5R	1 μ	±10, ±20	10	150	0.5±0.05	R
TMK105CBJ225∏V-F				X5R	2.2 μ	±10, ±20	10	150	0.5+0.20/-0	R
EMK105 BJ224[]V-F			В	X5R	0.22 μ	±10, ±20	5	150	0.5±0.05	R
EMK105ABJ474[]V-F		16		X5R	0.47 μ	±10, ±20	10	200	0.5±0.10	R
EMK105 BJ105 U-F		10		X5R	1 μ	±10, ±20	10	150	0.5±0.05	R
EMK105ABJ225[]V-F				X5R	2.2 μ	±10, ±20	10	150	0.5±0.10	R
LMK105 BJ225[]V-F		10		X5R	2.2 μ	±10, ±20	10	150	0.5±0.05	R
LMK105BBJ475MVLF		10		X5R	4.7 μ	±20	10	150	0.5+0.15/-0.05	R
JMK105 BJ225[]V-F		6.3		X5R	2.2 μ	±10, ±20	10	150	0.5±0.05	R
JMK105BBJ475MV-F	JMK105 BJ475MV-FD	0.3		X5R	4.7 μ	±20	10	150	0.5+0.15/-0.05	R
AMK105EBJ226MV-F		4		X5R	22 μ	±20	20	150	0.5+0.30/-0	R

[Temperature Characteristic BJ : B(-25~+85°C)/X5R(-55~+85°C)] 0.3mm thickness(P)

Part number 1	Part number 2	Rated voltage	Temperature Capacitance characteristics [F]		Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Part number 1	Part number 2	[V]			[F]	[%]	[%]	Rated voltage x %	Inickness [mm]	W:Wave
UMK105 BJ104[]P-F		50		X5R	0.1 μ	±10, ±20	10	150	0.3 ± 0.03	R
TMK105 BJ103[]P-F			В	X5R	0.01 μ	±10, ±20	5	150	0.3 ± 0.03	R
TMK105 BJ104[]P-F		25		X5R	0.1 μ	±10, ±20	10	150	0.3 ± 0.03	R
TMK105 BJ224[]P-F		25		X5R	0.22 μ	±10, ±20	10	150	0.3 ± 0.03	R
TMK105 BJ474[]P-F				X5R	0.47 μ	±10, ±20	10	150	0.3 ± 0.03	R
EMK105 BJ474[P-F		16		X5R	0.47 μ	±10, ±20	10	150	0.3 ± 0.03	R
LMK105 BJ105[]PLF		10		X5R	1 μ	±10, ±20	10	150	0.3 ± 0.03	R
JMK105 BJ105[]P-F		6.3		X5R	1 μ	±10, ±20	10	150	0.3 ± 0.03	R
AMK105 BJ225MP-F		4		X5R	2.2 μ	±20	10	150	0.3 ± 0.03	R

[Temperature Characteristic BJ : $X5R(-55 \sim +85^{\circ}C)$] 0.2mm thickness(C)

Part number 1	Part number 2	Rated voltage [V]	Tempe characte		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
LMK105 BJ104[]C-F		10		X5R	0.1 μ	±10, ±20	10	150	0.2±0.02	R
JMK105 BJ224[]C-F				X5R	0.22 μ	±10, ±20	10	150	0.2±0.02	R
JMK105 BJ474∏C-F		6.3		X5R	0.47 μ	±10, ±20	10	150	0.2 ± 0.02	R
JMK105 BJ105MC-F				X5R	1 μ	±20	10	150	0.2 ± 0.02	R

[Temperature Characteristic BJ : $X5R(-55 \sim +85^{\circ}C)$] 0.18mm thickness(E)

Tremperature Orial accernistic Bo : XSTV											
Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave		
LMK105 BJ104□E-R		10	X5R	0.1 μ	±10, ±20	10	150	0.18±0.02	R		
JMK105 BJ224∏E-R		6.3	X5R	0.22 μ	±10, ±20	10	150	0.18±0.02	R		
JMK105 BJ474∏E-R		0.3	X5R	0.47 μ	±10, ±20	10	150	0.18±0.02	R		
AMK105 BJ105ME-R		4	X5R	1 μ	±20	10	150	0.18±0.02	R		

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[Temperature Characteristic BJ: $X5R(-55 \sim +85^{\circ}C)$] 0.13mm thickness(H)

Part number 1	Part number 2	Rated voltage [V]	Temperatur characteristi		Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
LMK105 BJ104MH-R		10	X5	R 0.1 μ	±20	10	150	0.13 ± 0.02	R
JMK105 BJ224MH-R		6.3	X5	R 0.22 μ	±20	10	150	0.13±0.02	R
AMK105 BJ474MH-R		4	X5	R 0.47 μ	±20	10	150	0.13 ± 0.02	R

[Temperature Characteristic C6: $X6S(-55 \sim +105^{\circ}C)$] 0.5mm thickness(V)

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Fart number 1	Fart Humber 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Inickness [mm]	W:Wave
GMK105CC6105MV-F		35	X6S	1 μ	±20	10	150	0.5+0.20/-0	R
TMK105AC6105[]V-F		25	X6S	1 μ	±10, ±20	10	150	0.5±0.10	R
EMK105 C6105[]V-F		16	X6S	1 μ	±10, ±20	10	150	0.5±0.05	R
EMK105CC6225MV-F		10	X6S	2.2 μ	±20	10	150	0.5+0.20/-0	R
LMK105 C6105[]V-F		10	X6S	1 μ	±10, ±20	10	200	0.5±0.05	R
LMK105AC6225MV-F		10	X6S	2.2 μ	±20	10	150	0.5±0.10	R
JMK105 C6105 U-F			X6S	1 μ	±10, ±20	10	150	0.5±0.05	R
JMK105 C6225MV-F		6.3	X6S	2.2 μ	±20	10	150	0.5±0.05	R
JMK105BC6475MV-F			X6S	4.7 μ	±20	10	150	0.5+0.15/-0.05	R
AMK105BC6475MV-F		4	X6S	4.7 μ	±20	10	200	0.5+0.15/-0.05	R

[Temperature Characteristic B7 : $X7R(-55\sim +125^{\circ}C)$] 0.5mm thickness(V)

Temperature Charac	cteristic B7 : X7R(-	-55~+125`	C) 1 0.5mm	thickness(V)					
Part number 1	Part number 2	Rated voltage	Temperature	Capacitance		tan δ	HTLT	Thickness*3 [mm]	Soldering R:Reflow
r are number r	Ture number 2	[V]	characteristic	[F]	[%]	[%]	Rated voltage x %	Thickness [illin]	W:Wave
UMK105 B7152□V-F			X7F	1500 p	±10, ±20	2.5	200	0.5±0.05	R
UMK105 B7222 UV-F			X7F	2200 p	±10, ±20	2.5	200	0.5±0.05	R
UMK105 B7332 UV-F			X7F	3300 p	±10, ±20	2.5	200	0.5±0.05	R
UMK105 B7472 UV-F			X7F	4700 p	±10, ±20	2.5	150	0.5 ± 0.05	R
UMK105 B7682□V-F		50	X7F	6800 p	±10, ±20	2.5	150	0.5 ± 0.05	R
UMK105 B7103□V-F			X7F	0.01 μ	±10, ±20	3.5	150	0.5 ± 0.05	R
UMK105 B7223 UV-FR			X7F	0.022 μ	±10, ±20	10	200	0.5 ± 0.05	R
UMK105 B7473□V-FR			X7F	0.047 μ	±10, ±20	10	200	0.5 ± 0.05	R
UMK105 B7104□V-FR			X7F	0.1 μ	±10, ±20	10	150	0.5 ± 0.05	R
TMK105 B7223 V-F			X7F	0.022 μ	±10, ±20	3.5	150	0.5 ± 0.05	R
TMK105 B7473 V-F		25	X7F	0.047 μ	±10, ±20	3.5	150	0.5 ± 0.05	R
TMK105 B7104[]V-FR		23	X7F	0.1 μ	±10, ±20	10	200	0.5 ± 0.05	R
TMK105 B7224[]V-FR			X7F	0.22 μ	±10, ±20	10	150	0.5 ± 0.05	R
EMK105 B7223[]V-F			X7F	0.022 μ	±10, ±20	3.5	200	0.5 ± 0.05	R
EMK105 B7473[]V-F		16	X7F	0.047 μ	±10, ±20	3.5	200	0.5 ± 0.05	R
EMK105 B7104[]V-F		10	X7F	0.1 μ	±10, ±20	5	150	0.5 ± 0.05	R
EMK105 B7224[]V-FR			X7F	0.22 μ	±10, ±20	10	150	0.5 ± 0.05	R
LMK105 B7224[]V-FR		10	X7F	0.22 μ	±10, ±20	10	150	0.5 ± 0.05	R
LMK105 B7474[]V-F		10	X7F	0.47 μ	±10, ±20	10	150	0.5 ± 0.05	R
JMK105 B7224[]V-F		6.3	X7F	0.22 μ	±10, ±20	5	150	0.5 ± 0.05	R
JMK105 B7474[]V-F		0.3	X7F	0.47 μ	±10, ±20	10	150	0.5 ± 0.05	R

●107TYPE

[Temperature Characteristic BJ : $B(-25\sim+85^{\circ}C)/X5R(-55\sim+85^{\circ}C)$] 0.8mm thickness(A)

Part number 1 Part n	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	tan δ	HTLT	Thickness*3 [mm]	Soldering R:Reflow
T di t Hamber 1	Tare number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	THICKNESS [HIII]	W:Wave
UMK107ABJ474[]A-T	UMK107 BJ474[]A-TD		X5R	0.47 μ	±10, ±20	10	150	0.8+0.15/-0.05	R
UMK107 BJ105∏A-T		50	X5R	1 μ	±10, ±20	10	150	0.8±0.10	R
UMK107BBJ225∏A-T			X5R	2.2 μ	±10, ±20	10	150	0.8+0.20/-0	R
GMK107BBJ475[]A-T		35	X5R	4.7 μ	±10, ±20	10	150	0.8+0.20/-0	R
TMK107ABJ225∏A-T	TMK107 BJ225∏A-TD		X5R	2.2 μ	±10, ±20	10	150	0.8+0.15/-0.05	R
TMK107BBJ475[]A-T		25	X5R	4.7 μ	±10, ±20	10	150	0.8+0.20/-0	R
TMK107BBJ106MA-T			X5R	10 μ	±20	10	150	0.8+0.20/-0	R
EMK107ABJ475∏A-T	EMK107 BJ475[]A-TD	16	X5R	4.7 μ	±10, ±20	10	150	0.8+0.15/-0.05	R
EMK107BBJ106MA-T		10	X5R	10 μ	±20	10	150	0.8+0.20/-0	R
LMK107BBJ106□ALT	LMK107 BJ106 ☐ALTD	10	X5R	10 μ	±10, ±20	10	150	0.8+0.20/-0	R
LMK107BBJ226MA-T		10	X5R	22 μ	±20	10	150	0.8+0.20/-0	R
JMK107ABJ106∏A-T	JMK107 BJ106∏A-T		X5R	10 μ	±10, ±20	10	150	0.8+0.15/-0.05	R
JMK107BBJ226MA-T		6.3	X5R	22 μ	±20	10	150	0.8+0.20/-0	R
JMK107BBJ476MA-RE			X5R	47 μ	±20	15	150	0.8+0.20/-0	R
AMK107BBJ476MA-RE		4	X5R	47 μ	±20	20	150	0.8+0.20/-0	R

【Temperature Characteristic BJ: X5R(−55~+85°C)】 0.45mm thickness(K)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
TMK107 BJ105[]K-T		25	X5R	1 μ	±10, ±20	10	150	0.45 ± 0.05	R
EMK107 BJ105[]K-T		16	X5R	1 μ	±10, ±20	10	150	0.45 ± 0.05	R
EMK107BBJ225[K-T		10	X5R	2.2 μ	±10, ±20	10	150	0.45 ± 0.05	R
LMK107 BJ105∏K-T			X5R	1 μ	±10, ±20	10	150	0.45 ± 0.05	R
LMK107 BJ225∏K-T		10	X5R	2.2 μ	±10, ±20	10	150	0.45 ± 0.05	R
LMK107BBJ475MKLT	LMK107 BJ475MKLTD		X5R	4.7 μ	±20	10	150	0.45 ± 0.05	R
JMK107 BJ105∏K-T			X5R	1 μ	±10, ±20	10	150	0.45 ± 0.05	R
JMK107 BJ225∏K-T		6.3	X5R	2.2 μ	±10, ±20	10	150	0.45 ± 0.05	R
JMK107 BJ475MK-T		0.5	X5R	4.7 μ	±20	10	150	0.45 ± 0.05	R
JMK107BBJ106MK-TT			X5R	10 μ	±20	10	150	0.45 ± 0.05	R
AMK107BBJ106MK-T*2		4	X5R	10 μ	±20	10	150	0.45 ± 0.05	R

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[Temperature Characteristic C6 : X6S($-55\sim+105^{\circ}$ C)] 0.8mm thickness(A)

B		Rated voltage	Temperature	Capacitance	Capacitance tolerance	tan δ	HTLT	+2 5 3	Soldering
Part number 1	Part number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Thickness*3 [mm]	R:Reflow W:Wave
TMK107BC6225[]A-T		25	X6S	2.2 μ	±10, ±20	10	150	0.8+0.20/-0	R
EMK107 C6105∏A-T			X6S	1 μ	±10, ±20	5	150	0.8±0.10	R
EMK107BC6225[]A-T		16	X6S	2.2 μ	±10, ±20	10	150	0.8+0.20/-0	R
EMK107BC6475[]A-T		10	X6S	4.7 μ	±10, ±20	10	150	0.8+0.20/-0	R
EMK107BC6106MA-T			X6S	10 μ	±20	10	150	0.8+0.20/-0	R
LMK107 C6105∏A-T			X6S	1 μ	±10, ±20	5	150	0.8±0.10	R
LMK107AC6475[]A-T		10	X6S	4.7 μ	±10, ±20	10	150	0.8+0.15/-0.05	R
LMK107BC6106MA-T			X6S	10 μ	±20	10	150	0.8+0.20/-0	R
JMK107 C6475∏A-T			X6S	4.7 μ	±10, ±20	10	150	0.8±0.10	R
JMK107BC6106MA-T		6.3	X6S	10 μ	±20	10	150	0.8+0.20/-0	R
JMK107BC6226MA-T			X6S	22 μ	±20	10	150	0.8+0.20/-0	R
AMK107BC6226MA-T		4	X6S	22 μ	±20	10	150	0.8+0.20/-0	R

[Temperature Characteristic B7 : $X7R(-55\sim+125^{\circ}C)$] 0.8mm thickness(A)

Part number 1 Part number 2	Rated voltage		Capacitance		$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow	
Part number 1	Part number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Thickness [mm]	W:Wave
UMK107 B7224[]A-TR			X7R	0.22 μ	±10, ±20	10	150	0.8±0.10	R
UMK107 B7474[]A-TR		50	X7R	0.47 μ	±10, ±20	10	150	0.8±0.10	R
UMK107AB7105[]A-T			X7R	1 μ	±10, ±20	10	150	0.8+0.15/-0.05	R
TMK107 B7474[]A-TR		25	X7R	0.47 μ	±10, ±20	10	150	0.8±0.10	R
TMK107 B7105[]A-T		23	X7R	1 μ	±10, ±20	10	150	0.8±0.10	R
EMK107 B7474[]A-T			X7R	0.47 μ	±10, ±20	3.5	150	0.8±0.10	R
EMK107 B7105[]A-T		16	X7R	1 μ	±10, ±20	5	150	0.8±0.10	R
EMK107BB7225[]A-T			X7R	2.2 μ	±10, ±20	10	150	0.8+0.20/-0	R
LMK107 B7225∏A-TR		10	X7R	2.2 μ	±10, ±20	10	150	0.8±0.10	R
JMK107 B7225∏A-TR		6.3	X7R	2.2 μ	±10, ±20	10	200	0.8±0.10	R
JMK107BB7475[]A-T		0.3	X7R	4.7 μ	±10, ±20	10	150	0.8+0.20/-0	R

212TYPE

[Temperature Characteristic BJ : B($-25\sim+85^{\circ}$ C)/X5R($-55\sim+85^{\circ}$ C)] 1.25mm thickness(G)

Part number 1	Part number 2	Rated voltage [V]	Tempe charact	erature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
UMK212BBJ475[]G-T		50		X5R	4.7 μ	±10, ±20	10	150	1.25+0.20/-0	R
GMK212BBJ106[]G-T		35		X5R	10 μ	±10, ±20	10	150	1.25+0.20/-0	R
TMK212ABJ475[]G-T	TMK212 BJ475[]G-T			X5R	4.7 μ	±10, ±20	10	150	1.25+0.15/-0.05	R
TMK212BBJ106MG-T		25		X5R	10 μ	±20	10	150	1.25+0.20/-0	R
TMK212BBJ226MG-TT				X5R	22 μ	±20	10	150	1.25+0.20/-0	R
EMK212ABJ106∏G-T	EMK212 BJ106 G-T	16		X5R	10 μ	±10, ±20	10	150	1.25+0.15/-0.05	R
EMK212BBJ226MG-T		10		X5R	22 μ	±20	10	150	1.25+0.20/-0	R
LMK212BBJ476MG-T		10		X5R	47 μ	±20	10	150	1.25+0.20/-0	R
JMK212BBJ476MG-T	JMK212 BJ476MG-T	6.3		X5R	47 μ	±20	10	150	1.25+0.20/-0	R
JMK212BBJ107MG-TE		0.3		X5R	100 μ	±20	20	150	1.25+0.20/-0	R
AMK212BBJ107MG-TE		4		X5R	100 μ	±20	20	150	1.25+0.20/-0	R
PMK212BBJ107MG-T		2.5		X5R	100 μ	±20	10	150	1.25+0.20/-0	R

[Temperature Characteristic BJ : $B(-25 \sim +85 ^{\circ}C)/X5R(-55 \sim +85 ^{\circ}C)$] 0.85mm thickness (D)

I emperature Chara	cteristic BJ : B (- 2	5~+85°C)/	/X5R(-	-55 ~ +	·85°C)] 0.8	Somm thickness(D)				
Part number 1	Part number 2	Rated voltage	Tempe		Capacitance	Capacitance tolerance	tan δ	HTLT	Thickness*3 [mm]	Soldering R:Reflow
T di C Hamber 1	T die Hamber 2	[V]	charact	eristics	[F]	[%]	[%]	Rated voltage x %	THICKIESS [HIII]	W:Wave
UMK212ABJ105[]D-T	UMK212 BJ105[]D-TD	50		X5R	1 μ	±10, ±20	10	150	0.85±0.10	R
UMK212BBJ225[]D-T		50		X5R	2.2 μ	±10, ±20	10	150	0.85±0.10	R
GMK212BBJ475[]D-T		35		X5R	4.7 μ	±10, ±20	10	150	0.85±0.10	R
TMK212 BJ474[]D-T			В	X5R	0.47 μ	±10, ±20	3.5	200	0.85±0.10	R
TMK212 BJ105□D-T] [В	X5R	1 μ	±10, ±20	5	200	0.85±0.10	R
TMK212ABJ225[]D-T	TMK212 BJ225 D-T	25		X5R	2.2 μ	±10, ±20	5	150	0.85±0.10	R
TMK212BBJ475 D-T	TMK212 BJ475∏D-TD			X5R	4.7 μ	±10, ±20	10	150	0.85±0.10	R
TMK212BBJ106[]D-T				X5R	10 μ	±10, ±20	10	150	0.85±0.10	R
EMK212 BJ105[]D-T			В	X5R*1	1 μ	±10, ±20	5	200	0.85 ± 0.10	R
EMK212ABJ225□D-T	EMK212 BJ225[]D-T	16		X5R*1	2.2 μ	±10, ±20	5	200	0.85 ± 0.10	R
EMK212 BJ475□D-T		10		X5R	4.7 μ	±10, ±20	10	150	0.85±0.10	R
EMK212ABJ106□D-T	EMK212 BJ106∏D-TD			X5R	10 μ	±10, ±20	10	150	0.85±0.10	R
LMK212 BJ105□D-T			В	X5R*1	1 μ	±10, ±20	3.5	200	0.85 ± 0.10	R
LMK212 BJ225□D-T		10		X5R*1	2.2 μ	±10, ±20	5	200	0.85 ± 0.10	R
LMK212ABJ106□D-T	LMK212 BJ106 D-T	10		X5R	10 μ	±10, ±20	10	150	0.85±0.10	R
LMK212BBJ226MD-T				X5R	22 μ	±20	10	150	0.85±0.10	R
JMK212ABJ106□D-T	JMK212 BJ106[]D-T	6.3		X5R	10 μ	±10, ±20	10	200	0.85±0.10	R
JMK212ABJ226MD-T	JMK212 BJ226MD-T	0.3		X5R	22 μ	±20	10	150	0.85±0.10	R
AMK212BBJ476MD-T		4		X5R	47 μ	±20	10	150	0.85±0.10	R

[Temperature Characteristic C6: X6S(-55~+105°C)] 1.25mm thickness(G)

L romporacaro oriara	Soldering													
Part number 1	Part number 2	Rated voltage		Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow					
Fart number 1	Fart number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Inickness [mm]	W:Wave					
TMK212BC6106[]G-T		25	X6S	10 μ	±10, ±20	10	150	1.25+0.20/-0	R					
EMK212BC6226MG-TT		16	X6S	22 μ	±20	10	150	1.25+0.20/-0	R					
LMK212BC6226MG-T		10	X6S	22 μ	±20	10	150	1.25+0.20/-0	R					
JMK212BC6226MG-T		6.3	X6S	22 μ	±20	10	150	1.25+0.20/-0	R					
JMK212BC6476MG-T		0.3	X6S	47 μ	±20	10	150	1.25+0.20/-0	R					
AMK212BC6476MG-T		4	X6S	47 μ	±20	10	150	1.25+0.20/-0	R					
AMK212BC6107MG-TE		4	X6S	100 μ	±20	20	150	1.25+0.20/-0	R					

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[Temperature Characteristic C6 : $X6S(-55\sim+105^{\circ}C)$] 0.85mm thickness(D)

Part number 1	Part number 2	Rated voltage [V]	erature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
LMK212AC6106□D-T		10	X6S	10 μ	±10, ±20	10	150	0.85 ± 0.10	R
AMK212BC6226MD-T		4	X6S	22 μ	±20	10	150	0.85 ± 0.10	R

[Temperature Characteristic B7 : X7R(-55~+125°C)] 1.25mm thickness(G)

Don't word out 1	Don't words on 0	Rated voltage	Temper	ature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	*3 5 3	Soldering
Part number 1	Part number 2	[V]	characte	ristics	[F]	[%]	[%]	Rated voltage x %	Thickness*3 [mm]	R:Reflow W:Wave
UMK212 B7224 G-T				X7R	0.22 μ	±10, ±20	3.5	150	1.25±0.10	R/W
UMK212 B7474[]G-T		50		X7R	0.47 μ	±10, ±20	3.5	150	1.25±0.10	R/W
UMK212 B7105∏G-T		30		X7R	1 μ	±10, ±20	10	150	1.25±0.10	R/W
UMK212BB7225[]G-T				X7R	2.2 μ	±10, ±20	10	150	1.25+0.20/-0	R
GMK212 B7105[]G-T		35		X7R	1 μ	±10, ±20	3.5	150	1.25±0.10	R/W
TMK212 B7225 ☐G-TR		25		X7R	2.2 μ	±10, ±20	10	150	1.25±0.10	R
TMK212AB7475∏G-T	TMK212 B7475[]G-T	25		X7R	4.7 μ	±10, ±20	10	150	1.25+0.15/-0.05	R
EMK212 B7475∏G-T		16		X7R	4.7 μ	±10, ±20	10	150	1.25±0.10	R
EMK212BB7106MG-T		10		X7R	10 μ	±20	10	150	1.25+0.20/-0	R
LMK212AB7106∏G-T	LMK212 B7106 G-TD	10		X7R	10 μ	±10, ±20	10	150	1.25+0.15/-0.05	R
JMK212AB7106[]G-T	JMK212 B7106[]G-T	6.3		X7R	10 μ	±10, ±20	10	150	1.25+0.15/-0.05	R

【Temperature Characteristic B7: X7R(−55~+125°C)】 0.85mm thickness(D)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristic		Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
UMK212AB7104□D-T			X7	θ 0.1 μ	±10, ±20	10	150	0.85 ± 0.10	R
UMK212AB7224[]D-T		50	X7	0.22 μ	±10, ±20	10	150	0.85±0.10	R
UMK212AB7474[]D-T		30	X7	0.47 μ	±10, ±20	10	150	0.85 ± 0.10	R
UMK212AB7105□D-T			X7	1 μ	±10, ±20	10	150	0.85 ± 0.10	R
TMK212AB7225[]D-TR		25	X7	2.2 μ	±10, ±20	10	150	0.85 ± 0.10	R
EMK212 B7474[]D-T			X7	0.47 μ	±10, ±20	3.5	200	0.85 ± 0.10	R/W
EMK212 B7105[]D-T		16	X7	1 μ	±10, ±20	5	200	0.85 ± 0.10	R
EMK212AB7225[]D-T	EMK212 B7225[]D-T		X7	2.2 μ	±10, ±20	5	150	0.85 ± 0.10	R
LMK212 B7105[]D-T			X7	1 μ	±10, ±20	3.5	200	0.85 ± 0.10	R
LMK212AB7225[]D-T	LMK212 B7225 D-T	10	X7	2.2 μ	±10, ±20	5	200	0.85 ± 0.10	R
LMK212AB7475[]D-TR	LMK212 B7475[]D-TR		X7	R 4.7 μ	±10, ±20	10	150	0.85±0.10	R

316TYPE

[Temperature Characteristic BJ : $B(-25 \sim +85^{\circ}C)/X5R(-55 \sim +85^{\circ}C)$] 1.6mm thickness(L)

Part number 1	Part number 2	Rated voltage	Tempe	rature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Fart number 1	Fart number 2	[V]	charact	eristics	[F]	[%]	[%]	Rated voltage x %	Thickness [mm]	W:Wave
UMK316 BJ475[]L-T		50		X5R	4.7 μ	±10, ±20	10	150	1.6±0.20	R
UMK316BBJ106□L-T		50		X5R	10 μ	±10, ±20	10	150	1.6±0.30	R
TMK316BBJ226ML-T		25		X5R	22 μ	±20	10	150	1.6±0.30	R
EMK316BBJ476ML-T		16		X5R	47 μ	±20	10	150	1.6±0.30	R
LMK316ABJ476ML-T	LMK316 BJ476ML-T	10		X5R	47 μ	±20	10	150	1.6±0.20	R
JMK316ABJ107ML-T	JMK316 BJ107ML-T	6.3		X5R	100 μ	±20	10	150	1.6±0.20	R
AMK316ABJ107ML-T	AMK316 BJ107ML-T	4		X5R	100 μ	±20	10	150	1.6±0.20	R
AMK316BBJ157ML-T		4		X5R	150 μ	±20	10	150	1.6±0.30	R
PMK316BBJ227ML-T		2.5		X5R	220 μ	±20	10	150	1.6±0.30	R

Temperature Characteristic BJ : B(-25~+85°C)/X5R(-55~+85°C) 1 0.85mm thickness(D)

Tremperature Griara	Cteristic Do . D (2	0 100 0//	, XOIT	00 I	00 0/1 0.0	John Chickness (D)				
Part number 1	Part number 2	Rated voltage	Tempe	erature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
i ai ciidiibei i	T at Chamber 2	[V]	charact	eristics	[F]	[%]	[%]	Rated voltage x %	inickness [mm]	W:Wave
UMK316 BJ105[]D-T			В	X5R	1 μ	±10, ±20	3.5	150	0.85±0.10	R
UMK316 BJ225[]D-T		50	В	X5R	2.2 μ	±10, ±20	3.5	150	0.85±0.10	R
UMK316ABJ475[]D-T	UMK316 BJ475[]D-T			X5R	4.7 μ	±10, ±20	10	150	0.85±0.10	R
TMK316 BJ105□D-T			В	X5R	1 μ	±10, ±20	3.5	200	0.85±0.10	R
TMK316 BJ225□D-T		25	В	X5R	2.2 μ	±10, ±20	3.5	150	0.85±0.10	R
TMK316 BJ475□D-T		25		X5R	4.7 μ	±10, ±20	5	150	0.85±0.10	R
TMK316ABJ106[]D-T	TMK316 BJ106[]D-TD			X5R	10 μ	±10, ±20	10	150	0.85±0.10	R
EMK316 BJ225[]D-T			В	X5R	2.2 μ	±10, ±20	3.5	200	0.85±0.10	R
EMK316 BJ475[]D-T		16	В	X5R	4.7 μ	±10, ±20	5	200	0.85 ± 0.10	R
EMK316 BJ106[]D-T		10		X5R	10 μ	±10, ±20	10	150	0.85±0.10	R
EMK316ABJ226MD-T	EMK316 BJ226MD-T			X5R	22 μ	±20	10	150	0.85 ± 0.10	R
LMK316 BJ475□D-T			В	X5R	4.7 μ	±10, ±20	5	200	0.85±0.10	R
LMK316 BJ106□D-T		10		X5R	10 μ	±10, ±20	10	200	0.85±0.10	R
LMK316ABJ226MD-T	LMK316 BJ226MD-T			X5R	22 μ	±20	10	150	0.85±0.10	R
JMK316 BJ106[]D-T				X5R	10 μ	±10, ±20	10	200	0.85±0.10	R
JMK316ABJ226MD-T	JMK316 BJ226MD-T	6.3		X5R	22 μ	±20	10	150	0.85±0.10	R
JMK316ABJ476MD-T	JMK316 BJ476MD-T			X5R	47 μ	±20	10	150	0.85±0.10	R

[Temperature Characteristic C6 : $X6S(-55 \sim +105^{\circ}C)$] 1.6mm thickness(L)

Part number 1	Part number 2	Rated voltage		erature	Capacitance	Capacitance tolerance	tan δ	HTLT	Thickness*3 [mm]	Soldering R:Reflow
T di C Hamber 1	T di C Hamboi 2	[V]	charact	eristics	[F]	[%]	[%]	Rated voltage x %	THICKHESS [HIII]	W:Wave
EMK316BC6226ML-T		16		X6S	22 μ	±20	10	150	1.6±0.30	R
LMK316BC6476ML-T		10		X6S	47 μ	±20	10	150	1.6±0.30	R
JMK316AC6476ML-T		6.3		X6S	47 μ	±20	10	150	1.6±0.20	R
AMK316AC6476ML-T		4		X6S	47 μ	±20	10	200	1.6±0.20	R
AMK316AC6107ML-T		4		X6S	100 μ	±20	10	150	1.6±0.20	R

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[Temperature Characteristic C7 : X7S($-55\sim+125^{\circ}$ C)] 1.6mm thickness(L)

Part number 1	Part number 2	Rated voltage [V]	Tempe charact		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
AMK316AC7476ML-T		4		X7S	47 μ	±20	10	150	1.6±0.20	R

[Temperature Characteristic B7 : $X7R(-55 \sim +125^{\circ}C)$] 1.6mm thickness(L)

Part number 1	Part number 2	Rated voltage		erature	Capacitance	Capacitance tolerance	tan δ	HTLT	Thickness*3 [mm]	Soldering R:Reflow
T all triumber T	T all Humber 2	[V]	charact	eristics	[F]	[%]	[%]	Rated voltage x %	Triickness [mm]	W:Wave
UMK316 B7225□L-T		50		X7R	2.2 μ	±10, ±20	10	150	1.6±0.20	R
UMK316AB7475□L-T	UMK316 B7475[]L-T	30		X7R	4.7 μ	±10, ±20	10	150	1.6±0.20	R
GMK316AB7106[]L-TR		35		X7R	10 μ	±10, ±20	10	150	1.6±0.20	R
TMK316AB7475□L-T	TMK316 B7475[]L-T	25		X7R	4.7 μ	±10, ±20	10	200	1.6±0.20	R
TMK316AB7106□L-T	TMK316 B7106[]L-TD	23		X7R	10 μ	±10, ±20	10	150	1.6±0.20	R
EMK316 B7475 L-T				X7R	4.7 μ	±10, ±20	5	200	1.6±0.20	R
EMK316AB7106[]L-T	EMK316 B7106□L-TD	16		X7R	10 μ	±10, ±20	10	200	1.6±0.20	R
EMK316BB7226ML-T				X7R	22 μ	±20	10	150	1.6±0.30	R
LMK316AB7106[]L-T	LMK316 B7106[]L-TD	10		X7R	10 μ	±10, ±20	10	200	1.6±0.20	R
LMK316AB7226 L-TR	LMK316 B7226[]L-TD	10		X7R	22 μ	±10, ±20	10	150	1.6±0.20	R

[Temperature Characteristic B7 : X7R($-55\sim+125^{\circ}$ C)] 0.85mm thickness(D)

Part number 1	Part number 2	Rated voltage	Tempe	rature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
i ai ciidiilbei i	I al Citalliber 2	[V]	characte	eristics	[F]	[%]	[%]	Rated voltage x %	THICKNESS [IIIII]	W:Wave
UMK316 B7225[]D-T		50		X7R	2.2 μ	±10, ±20	10	150	0.85±0.10	R
TMK316AB7475∏D-T		25		X7R	4.7 μ	±10, ±20	10	150	0.85 ± 0.10	R
LMK316AB7106MD-T		10		X7R	10 μ	±20	10	150	0.85±0.10	R

●325TYPE

[Temperature Characteristic BJ : B($-25 \sim +85 ^{\circ} C$)/X5R($-55 \sim +85 ^{\circ} C$)] 2.5mm thickness(M)

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	tan δ	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Part number 1	Part number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Inickness [mm]	W:Wave
UMK325 BJ106[]M-P		50	X5R	10 μ	±10, ±20	5	150	2.5±0.20	R
GMK325 BJ226MM-P		35	X5R	22 μ	±20	5	150	2.5±0.20	R
TMK325ABJ476MM-P		25	X5R	47 μ	±20	10	150	2.5±0.30	R
EMK325ABJ107MM-P		16	X5R	100 μ	±20	10	150	2.5 ± 0.30	R
LMK325 BJ476MM-P		10	X5R	47 μ	±20	10	150	2.5±0.20	R
LMK325ABJ107MM-P	LMK325 BJ107MM-P	10	X5R	100 μ	±20	10	150	2.5±0.30	R
JMK325ABJ157MM-P			X5R	150 μ	±20	10	150	2.5±0.30	R
JMK325ABJ227MM-P		6.3	X5R	220 μ	±20	10	150	2.5±0.30	R
JMK325ABJ337MM-PE			X5R	330 μ	±20	10	150	2.5±0.30	R
AMK325ABJ157MM-P			X5R	150 μ	±20	10	150	2.5±0.30	R
AMK325ABJ227MM-P		4	X5R	220 μ	±20	10	150	2.5±0.30	R
AMK325ABJ337MM-P			X5R	330 μ	±20	10	150	2.5±0.30	R

[Temperature Characteristic BJ : B($-25\sim+85^{\circ}$ C)/X5R($-55\sim+85^{\circ}$ C)] 1.9mm thickness(Y,N)

Part number 1	Part number 2	Rated voltage	Tempe	erature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
T at C Humber 1	Tart Humber 2	[V]	charact	eristics	[F]	[%]	[%]	Rated voltage x %	Thickness [min]	W:Wave
UMK325 BJ475□N-T		50		X5R	4.7 μ	±10, ±20	10	150	1.9 ± 0.20	R
GMK325 BJ225□N-T			В	X5R	2.2 μ	±10, ±20	3.5	200	1.9 ± 0.20	R
GMK325 BJ475□N-T		35		X5R	4.7 μ	±10, ±20	10	150	1.9 ± 0.20	R
GMK325 BJ106□N-T				X5R	10 μ	±10, ±20	5	150	1.9 ± 0.20	R
TMK325 BJ335MN-T			В	X5R*1	3.3 μ	±20	3.5	200	1.9 ± 0.20	R
TMK325 BJ475[]N-T		25	В	X5R*1	4.7 μ	±10, ±20	3.5	200	1.9 ± 0.20	R
TMK325 BJ106[]N-T			В	X5R	10 μ	±10, ±20	5	200	1.9±0.20	R
EMK325 BJ475∏N-T			В	X5R*1	4.7 μ	±10, ±20	3.5	200	1.9 ± 0.20	R
EMK325 BJ106∏N-T		16		X5R	10 μ	±10, ±20	3.5	200	1.9 ± 0.20	R
EMK325 BJ476MY-T				X5R	47 μ	±20	10	150	1.9+0.1/-0.2	R
LMK325 BJ226MY-T		10	В	X5R	22 μ	±20	5	150	1.9+0.1/-0.2	R
LMK325 BJ106□N-T		10		X5R	10 μ	±10, ±20	3.5	200	1.9 ± 0.20	R
JMK325 BJ226MY-T			В	X5R	22 μ	±20	5	200	1.9+0.1/-0.2	R
JMK325 BJ107MY-T		6.3		X5R	100 μ	±20	10	150	1.9+0.1/-0.2	R
JMK325 BJ476MN-T			,	X5R	47 μ	±20	10	150	1.9±0.20	R

[Temperature Characteristic BJ : $B(-25 \sim +85^{\circ}C)/X5R(-55 \sim +85^{\circ}C)$] 0.85mm thickness(D)

Part number 1	Part number 2	Rated voltage [V]	Temper characte		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
TMK325 BJ106[]D-T		25		X5R	10 μ	±10, ±20	5	150	0.85 ± 0.10	R
EMK325 BJ106[]D-T		16		X5R	10 μ	±10, ±20	5	150	0.85 ± 0.10	R
EMK325 BJ226MD-T		10		X5R	22 μ	±20	10	150	0.85 ± 0.10	R
LMK325 BJ335[]D-T			В	X5R	3.3 μ	±10, ±20	3.5	200	0.85 ± 0.10	R
LMK325 BJ475[]D-T		10	В	X5R	4.7 μ	±10, ±20	5	200	0.85 ± 0.10	R
LMK325 BJ106[]D-T				X5R	10 μ	±10, ±20	5	150	0.85±0.10	R

[Temperature Characteristic C6 : $X6S(-55\sim+105^{\circ}C)$] 2.5mm thickness(M)

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Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Fart number 1	Fart Humber 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Inickness [mm]	W:Wave
EMK325AC6476MM-P		16	X6S	47 μ	±20	10	150	2.5±0.30	R
LMK325AC6107MM-P		10	X6S	100 μ	±20	10	150	2.5±0.30	R
AMK325AC6157MM-P			X6S	150 μ	±20	10	150	2.5±0.30	R
AMK325AC6227MM-P		4	X6S	220 μ	±20	10	150	2.5±0.30	R
AMK325AC6337MM-PE			X6S	330 μ	±20	10	150	2.5±0.30	R
PMK325AC6337MM-P		2.5	X6S	330 μ	±20	10	150	2.5±0.30	R

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[Temperature Characteristic C7 : X7S(-55~+125°C)] 2.5mm thickness(M)

Part number 1	Part number 2	Rated voltage [V]	Tempe charact	erature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
JMK325AC7107MM-P		6.3		X7S	100 μ	±20	10	150	2.5±0.30	R

[Temperature Characteristic B7 : $X7R(-55 \sim +125^{\circ}C)$] 2.5mm thickness(M)

	Part number 1	Part number 2	Rated voltage [V]	Tempe charact	erature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
U	MK325 B7335∏M-P				X7R	3.3 μ	±10, ±20	3.5	200	2.5±0.20	R
U	MK325 B7475∏M-P		50		X7R	4.7 μ	±10, ±20	5	150	2.5±0.20	R
U	MK325AB7106[]M-P				X7R	10 μ	±10, ±20	10	150	2.5±0.30	R
Т	MK325AB7106[]M-P		25		X7R	10 μ	±10, ±20	10	200	2.5±0.30	R
Т	MK325 B7226∏M-PR		23		X7R	22 μ	±10, ±20	10	150	2.5±0.20	R
Е	MK325 B7226∏M-PR		16		X7R	22 μ	±10, ±20	10	150	2.5±0.20	R
L	MK325 B7476∏M-PR		10		X7R	47 μ	±10, ±20	10	150	2.5±0.20	R
J	MK325 B7476∏M-PR		6.3		X7R	47 μ	±10, ±20	10	200	2.5±0.20	R

[Temperature Characteristic B7 : $X7R(-55 \sim +125^{\circ}C)$] 1.9mm thickness(N)

Part number 1	Part number 2	Rated voltage	Temperat	ture	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Fart number 1	Fart number 2	[V]	characteri	stics	[F]	[%]	[%]	Rated voltage x %	Inickness [mm]	W:Wave
UMK325 B7475□N-TR		50		X7R	4.7 μ	±10, ±20	10	150	1.9±0.20	R
TMK325 B7335∏N-T				X7R	3.3 μ	±10, ±20	3.5	200	1.9±0.20	R
TMK325 B7475[]N-T		25		X7R	4.7 μ	±10, ±20	3.5	150	1.9±0.20	R
TMK325 B7106∏N-TR				X7R	10 μ	±10, ±20	10	150	1.9±0.20	R
EMK325 B7475[]N-T		16		X7R	4.7 μ	±10, ±20	3.5	200	1.9±0.20	R
EMK325 B7106□N-T		10		X7R	10 μ	±10, ±20	3.5	150	1.9±0.20	R
LMK325 B7106□N-T		10		X7R	10 μ	±10, ±20	3.5	200	1.9±0.20	R

432TYPE

[Temperature Characteristic BJ : $X5R(-55 \sim +85^{\circ}C)$] 2.5mm thickness(M)

	Part number 1	Part number 2	Rated voltage [V]	rature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
AMK4	32 BJ477MM-T		4	X5R	470 μ	±20	10	150	2.5±0.20	R

[Temperature Characteristic C6 : $X6S(-55 \sim +105^{\circ}C)$] 2.5mm thickness(M)

Ī	Part number 1	Part number 2	Rated voltage [V]	erature teristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
PI	MK432 C6477MM-T		2.5	X6S	470 μ	±20	10	150	2.5±0.20	R

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Multilayer Ceramic Capacitors (Temperature compensating type)

021TYPE

[Temperature Characteristic CG : $CG/C0G(-55\sim+125^{\circ}C)$] 0.125mm thickness(K)

Part number 1	Part number 2	Rated voltage [V]	Temp	erature teristics	Capacitance [F]	Capacitance tolerance	Q (at 1MHz) min	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
TMK021 CG010∏K-W			CG	C0G	1 p	±0.1pF, ±0.25pF	420	200	0.125±0.013	R
TMK021 CG1R1□K-W			CG	C0G	1.1 p	±0.1pF, ±0.25pF	422	200	0.125±0.013	R
TMK021 CG1R2 K-W			CG	C0G	1.2 p	±0.1pF, ±0.25pF	424	200	0.125±0.013	R
TMK021 CG1R3 K-W TMK021 CG1R4 K-W			CG	C0G C0G	1.3 p	±0.1pF, ±0.25pF	426 428	200	0.125±0.013 0.125±0.013	R
TMK021 CG1R4[]K-W		•	CG	COG	1.4 p 1.5 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	428	200	0.125±0.013	R R
TMK021 CG1R6 K-W		1	CG	COG	1.6 p	±0.1pF, ±0.25pF	432	200	0.125±0.013	R
TMK021 CG1R7□K-W		1	CG	C0G	1.7 p	±0.1pF, ±0.25pF	434	200	0.125±0.013	R
TMK021 CG1R8□K-W			CG	C0G	1.8 p	±0.1pF, ±0.25pF	436	200	0.125±0.013	R
TMK021 CG1R9□K-W			CG	C0G	1.9 p	$\pm 0.1 pF$, $\pm 0.25 pF$	438	200	0.125±0.013	R
TMK021 CG020∏K-W TMK021 CG2R1∏K-W			CG	COG	2 p	±0.1pF, ±0.25pF	440	200 200	0.125±0.013	R R
TMK021 CG2R1 K-W		•	CG	C0G C0G	2.1 p 2.2 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	442 444	200	0.125±0.013 0.125±0.013	R
TMK021 CG2R3[K-W		1	CG	COG	2.2 p	±0.1pF, ±0.25pF	446	200	0.125±0.013	R
TMK021 CG2R4[K-W			CG	COG	2.4 p	±0.1pF, ±0.25pF	448	200	0.125±0.013	R
TMK021 CG2R5□K-W			CG	C0G	2.5 p	±0.1pF, ±0.25pF	450	200	0.125±0.013	R
TMK021 CG2R6□K-W			CG	C0G	2.6 p	$\pm 0.1 pF$, $\pm 0.25 pF$	452	200	0.125±0.013	R
TMK021 CG2R7[K-W			CG	C0G	2.7 p	±0.1pF, ±0.25pF	454	200	0.125±0.013	R
TMK021 CG2R8[K-W			CG	COG	2.8 p	±0.1pF, ±0.25pF	456 458	200	0.125±0.013	R
TMK021 CG2R9∏K-W TMK021 CG030∏K-W		•	CG	C0G C0G	2.9 p 3 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	460	200 200	0.125±0.013 0.125±0.013	R R
TMK021 CG3R1 K-W		1	CG	COG	3.1 p	±0.1pF, ±0.25pF	462	200	0.125±0.013	R
TMK021 CG3R2[K-W			CG	COG	3.2 p	±0.1pF, ±0.25pF	464	200	0.125±0.013	R
TMK021 CG3R3∏K-W			CG	C0G	3.3 p	±0.1pF, ±0.25pF	466	200	0.125±0.013	R
TMK021 CG3R4□K-W			CG	C0G	3.4 p	±0.1pF, ±0.25pF	468	200	0.125±0.013	R
TMK021 CG3R5∏K-W			CG	C0G	3.5 p	±0.1pF, ±0.25pF	470	200	0.125±0.013	R
TMK021 CG3R6[K-W			CG	COG	3.6 p	±0.1pF, ±0.25pF	472	200	0.125±0.013	R
TMK021 CG3R7[K-W TMK021 CG3R8[K-W		•	CG	C0G C0G	3.7 p 3.8 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	474 476	200 200	0.125±0.013 0.125±0.013	R R
TMK021 CG3R9[K-W		1	CG	COG	3.9 p	±0.1pF, ±0.25pF	478	200	0.125±0.013	R
TMK021 CG040[K-W			CG	COG	4 p	±0.1pF, ±0.25pF	480	200	0.125±0.013	R
TMK021 CG4R1□K-W			CG	C0G	4.1 p	±0.1pF, ±0.25pF	482	200	0.125±0.013	R
TMK021 CG4R2[K-W			CG	C0G	4.2 p	$\pm 0.1 pF$, $\pm 0.25 pF$	484	200	0.125±0.013	R
TMK021 CG4R3 K-W			CG	C0G	4.3 p	±0.1pF, ±0.25pF	486	200	0.125±0.013	R
TMK021 CG4R4[K-W			CG	COG	4.4 p	±0.1pF, ±0.25pF	488	200	0.125±0.013	R
TMK021 CG4R5∏K-W TMK021 CG4R6∏K-W		•	CG	C0G C0G	4.5 p 4.6 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	490 492	200	0.125±0.013 0.125±0.013	R R
TMK021 CG4R7[K-W			CG	COG	4.0 p	±0.1pF, ±0.25pF	494	200	0.125±0.013	R
TMK021 CG4R8[K-W		1	CG	COG	4.8 p	±0.1pF, ±0.25pF	496	200	0.125±0.013	R
TMK021 CG4R9∏K-W		1	CG	C0G	4.9 p	±0.1pF, ±0.25pF	498	200	0.125±0.013	R
TMK021 CG050[K-W			CG	C0G	5 p	±0.1pF, ±0.25pF	500	200	0.125±0.013	R
TMK021 CG5R1 K-W			CG	C0G	5.1 p	±0.25pF, ±0.5pF	502	200	0.125±0.013	R
TMK021 CG5R2[K-W		25	CG	C0G C0G	5.2 p	±0.25pF, ±0.5pF	504	200	0.125±0.013	R R
TMK021 CG5R3[K-W TMK021 CG5R4[K-W		•	CG	COG	5.3 p 5.4 p	±0.25pF, ±0.5pF ±0.25pF, ±0.5pF	506 508	200 200	0.125±0.013 0.125±0.013	R
TMK021 CG5R5[K-W			CG	COG	5.5 p	±0.25pF, ±0.5pF	510	200	0.125±0.013	R
TMK021 CG5R6□K-W		1	CG	COG	5.6 p	±0.25pF, ±0.5pF	512	200	0.125±0.013	R
TMK021 CG5R7□K-W		1	CG	C0G	5.7 p	±0.25pF, ±0.5pF	514	200	0.125±0.013	R
TMK021 CG5R8□K-W			CG	C0G	5.8 p	$\pm 0.25 pF$, $\pm 0.5 pF$	516	200	0.125±0.013	R
TMK021 CG5R9[K-W			CG	C0G	5.9 p	±0.25pF, ±0.5pF	518	200	0.125±0.013	R
TMK021 CG060[K-W			CG	COG	6 p	±0.25pF, ±0.5pF	520	200	0.125±0.013	R
TMK021 CG6R1□K-W TMK021 CG6R2□K-W		•	CG	C0G C0G	6.1 p 6.2 p	±0.25pF, ±0.5pF ±0.25pF, ±0.5pF	522 524	200 200	0.125±0.013 0.125±0.013	R R
TMK021 CG6R3 K-W			CG	COG	6.3 p	±0.25pF, ±0.5pF	526	200	0.125±0.013	R
TMK021 CG6R4[K-W			CG	COG	6.4 p	±0.25pF, ±0.5pF	528	200	0.125±0.013	R
TMK021 CG6R5□K-W			CG	C0G	6.5 p	±0.25pF, ±0.5pF	530	200	0.125±0.013	R
TMK021 CG6R6□K-W			CG	C0G	6.6 p	$\pm 0.25 pF$, $\pm 0.5 pF$	532	200	0.125±0.013	R
TMK021 CG6R7∏K-W			CG	C0G	6.7 p	$\pm 0.25 pF, \pm 0.5 pF$	534	200	0.125±0.013	R
TMK021 CG6R8 K-W			CG	COG	6.8 p	±0.25pF, ±0.5pF	536	200	0.125±0.013	R
TMK021 CG6R9∏K-W TMK021 CG070∏K-W		•	CG	C0G C0G	6.9 p 7 p	±0.25pF, ±0.5pF ±0.25pF, ±0.5pF	538 540	200	0.125±0.013 0.125±0.013	R R
TMK021 CG070 K-W		1	CG	COG	7.1 p	±0.25pF, ±0.5pF	542	200	0.125±0.013	R
TMK021 CG7R2[K-W		1	CG	COG	7.1 p	±0.25pF, ±0.5pF	544	200	0.125±0.013	R
TMK021 CG7R3[K-W			CG	C0G	7.3 p	±0.25pF, ±0.5pF	546	200	0.125±0.013	R
TMK021 CG7R4[K-W]	CG	C0G	7.4 p	±0.25pF, ±0.5pF	548	200	0.125±0.013	R
TMK021 CG7R5[K-W			CG	C0G	7.5 p	$\pm 0.25 pF, \pm 0.5 pF$	550	200	0.125±0.013	R
TMK021 CG7R6[K-W			CG	COG	7.6 p	±0.25pF, ±0.5pF	552	200	0.125±0.013	R
TMK021 CG7R7∏K-W TMK021 CG7R8∏K-W			CG	C0G C0G	7.7 p 7.8 p	±0.25pF, ±0.5pF ±0.25pF, ±0.5pF	554 556	200 200	0.125±0.013 0.125±0.013	R R
TMK021 CG7R9[K-W		•	CG	COG	7.6 p	±0.25pF, ±0.5pF	558	200	0.125±0.013	R
TMK021 CG080[K-W		1	CG	COG	8 p	±0.25pF, ±0.5pF	560	200	0.125±0.013	R
TMK021 CG8R1∏K-W]	CG	COG	8.1 p	±0.25pF, ±0.5pF	562	200	0.125±0.013	R
TMK021 CG8R2[K-W			CG	C0G	8.2 p	±0.25pF, ±0.5pF	564	200	0.125±0.013	R
TMK021 CG8R3[K-W]	CG	C0G	8.3 p	±0.25pF, ±0.5pF	566	200	0.125±0.013	R
TMK021 CG8R4[K-W			CG	C0G	8.4 p	±0.25pF, ±0.5pF	568	200	0.125±0.013	R
TMK021 CG8R5[K-W			CG	C0G	8.5 p	±0.25pF, ±0.5pF	570	200	0.125±0.013	R
TMK021 CG8R6 K-W TMK021 CG8R7 K-W			CG	COG	8.6 p	±0.25pF, ±0.5pF	572 574	200	0.125±0.013	R
TMK021 CG8R7[K-W		1	CG	C0G C0G	8.7 p 8.8 p	±0.25pF, ±0.5pF ±0.25pF, ±0.5pF	574	200	0.125±0.013 0.125±0.013	R R
TMK021 CG8R9[K-W			CG	COG	8.9 p	±0.25pF, ±0.5pF	578	200	0.125±0.013	R
TMK021 CG090[K-W		1	CG	COG	9 p	±0.25pF, ±0.5pF	580	200	0.125±0.013	R
TMK021 CG9R1∏K-W]	CG	C0G	9.1 p	±0.25pF, ±0.5pF	582	200	0.125±0.013	R
TMK021 CG9R2[K-W			CG	C0G	9.2 p	±0.25pF, ±0.5pF	584	200	0.125±0.013	R
TMK021 CG9R3[K-W			CG	COG	9.3 p	±0.25pF, ±0.5pF	586	200	0.125±0.013	R
TMK021 CG9R4[K-W	<u> </u>	I	CG	C0G	9.4 p	±0.25pF, ±0.5pF	588	200	0.125±0.013	R

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Part number 1	Part number 2	Rated voltage		erature	Capacitance	Capacitance tolerance	Q (at 1MHz)	HTLT	Thickness*3 [mm]	Soldering R:Reflow
		[V]	charact	eristics	[F]			Rated voltage x %	THIORIESS [IIIII]	W:Wave
TMK021 CG9R5∏K-W			CG	COG	9.5 p	±0.25pF, ±0.5pF	590	200	0.125±0.013	R
TMK021 CG9R6∏K-W			CG	COG	9.6 p	±0.25pF, ±0.5pF	592	200	0.125±0.013	R
TMK021 CG9R7∏K-W			CG	COG	9.7 p	$\pm 0.25 pF, \pm 0.5 pF$	594	200	0.125±0.013	R
TMK021 CG9R8[K-W			CG	COG	9.8 p	$\pm 0.25 pF, \pm 0.5 pF$	596	200	0.125±0.013	R
TMK021 CG9R9∏K-W			CG	COG	9.9 p	$\pm 0.25 pF, \pm 0.5 pF$	598	200	0.125±0.013	R
TMK021 CG100DK-W		25	CG	COG	10 p	±0.5pF	600	200	0.125±0.013	R
TMK021 CG120JK-W			CG	C0G	12 p	±5%	640	200	0.125±0.013	R
TMK021 CG150JK-W			CG	C0G	15 p	±5%	700	200	0.125±0.013	R
TMK021 CG180JK-W			CG	C0G	18 p	±5%	760	200	0.125±0.013	R
TMK021 CG220JK-W			CG	COG	22 p	±5%	840	200	0.125±0.013	R
TMK021 CG270JK-W			CG	COG	27 p	±5%	940	200	0.125±0.013	R
EMK021 CG330JK-W			CG	COG	33 p	±5%	1000	150	0.125±0.013	R
EMK021 CG390JK-W		16	CG	COG	39 p	±5%	1000	150	0.125±0.013	R
EMK021 CG470JK-W		10	CG	COG	47 p	±5%	1000	150	0.125±0.013	R
EMK021 CG560JK-W			CG	COG	56 p	±5%	1000	150	0.125±0.013	R
LMK021 CG680JK-W			CG	COG	68 p	±5%	1000	200	0.125±0.013	R
LMK021 CG820JK-W		10	CG	COG	82 p	±5%	1000	200	0.125±0.013	R
LMK021 CG101JK-W			CG	COG	100 p	±5%	1000	200	0.125±0.013	R

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					nm thicknes		Q	UTLT		Soldering
Part number 1	Part number 2	Rated voltage [V]	Tempe charact		Capacitance [F]	Capacitance tolerance	(at 1MHz)	HTLT	Thickness*3 [mm]	R:Reflow
		[4]					min	Rated voltage x %		W:Wave
TMK042 CG010 D-W		_	CG	COG	1 p	±0.05pF, ±0.1pF, ±0.25pF	420	200	0.2±0.02	R
TMK042 CG1R1[D-W		_	CG	COG	1.1 p	±0.05pF, ±0.1pF, ±0.25pF	422	200	0.2±0.02	R
TMK042 CG1R2[]D-W		_	CG	COG	1.2 p	±0.05pF, ±0.1pF, ±0.25pF	424	200	0.2±0.02	R
TMK042 CG1R3∏D-W TMK042 CG1R4∏D-W		-	CG CG	C0G C0G	1.3 p 1.4 p	±0.05pF, ±0.1pF, ±0.25pF ±0.05pF, ±0.1pF, ±0.25pF	426 428	200 200	0.2±0.02 0.2±0.02	R R
TMK042 CG1R4UD-W		-	CG	COG	1.4 p 1.5 p	±0.05pF, ±0.1pF, ±0.25pF ±0.05pF, ±0.1pF, ±0.25pF	428	200	0.2±0.02 0.2±0.02	R
TMK042 CG1R5[]D-W		-	CG	COG	1.5 p	±0.05pF, ±0.1pF, ±0.25pF ±0.05pF, ±0.1pF, ±0.25pF	430	200	0.2±0.02 0.2±0.02	R
TMK042 CG1R0[]D-W		-	CG	COG	1.0 p	±0.05pF, ±0.1pF, ±0.25pF	434	200	0.2±0.02 0.2±0.02	R
TMK042 CG1R7[]D-W		-	CG	COG		± 0.05 pF, ± 0.1 pF, ± 0.25 pF ± 0.05 pF, ± 0.1 pF, ± 0.25 pF	434	200	0.2±0.02 0.2±0.02	R
TMK042 CG1R8[]D-W		-	CG	COG	1.8 p 1.9 p	$\pm 0.05pF$, $\pm 0.1pF$, $\pm 0.25pF$	438	200	0.2±0.02 0.2±0.02	R
TMK042 CG1K9DD-W		-	CG	COG	1.9 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	440	200	0.2±0.02	R
TMK042 CG2R1[]D-W		-	CG	COG	2.1 p	±0.05pF, ±0.1pF, ±0.25pF	442	200	0.2±0.02 0.2±0.02	R
TMK042 CG2R1 D-W		=	CG	COG	2.1 p	±0.05pF, ±0.1pF, ±0.25pF	444	200	0.2±0.02	R
TMK042 CG2R3∏D-W		=	CG	COG	2.2 p	±0.05pF, ±0.1pF, ±0.25pF	446	200	0.2±0.02	R
TMK042 CG2R4 D-W		-	CG	COG	2.4 p	±0.05pF, ±0.1pF, ±0.25pF	448	200	0.2±0.02	R
TMK042 CG2R5 D-W		-	CG	COG	2.5 p	±0.05pF, ±0.1pF, ±0.25pF	450	200	0.2±0.02	R
TMK042 CG2R6 D-W		=	CG	COG	2.6 p	±0.05pF, ±0.1pF, ±0.25pF	452	200	0.2±0.02	R
TMK042 CG2R7 D-W		-	CG	COG	2.7 p	±0.05pF, ±0.1pF, ±0.25pF	454	200	0.2±0.02	R
TMK042 CG2R8[]D-W		╡ !	CG	COG	2.7 p	±0.05pF, ±0.1pF, ±0.25pF	456	200	0.2±0.02	R
TMK042 CG2R9[]D-W		╡	CG	COG	2.0 p	±0.05pF, ±0.1pF, ±0.25pF	458	200	0.2±0.02	R
TMK042 CG030 D-W		┪ !	CG	COG	2.9 p	±0.05pF, ±0.1pF, ±0.25pF	460	200	0.2±0.02	R
TMK042 CG3R1 D-W		┪ !	CG	COG	3.1 p	±0.1pF, ±0.25pF	462	200	0.2±0.02	R
TMK042 CG3R2∏D-W		┪ !	CG	COG	3.2 p	±0.1pF, ±0.25pF	464	200	0.2±0.02	R
TMK042 CG3R3[D-W			CG	COG	3.3 p	±0.1pF, ±0.25pF	466	200	0.2±0.02	R
TMK042 CG3R4D-W			CG	COG	3.4 p	±0.1pF, ±0.25pF	468	200	0.2±0.02	R
TMK042 CG3R5□D-W			CG	COG	3.5 p	±0.1pF, ±0.25pF	470	200	0.2±0.02	R
TMK042 CG3R6□D-W			CG	COG	3.6 p	±0.1pF, ±0.25pF	472	200	0.2±0.02	R
TMK042 CG3R7□D-W			CG	COG	3.7 p	±0.1pF, ±0.25pF	474	200	0.2±0.02	R
TMK042 CG3R8[]D-W			CG	COG	3.8 p	±0.1pF, ±0.25pF	476	200	0.2±0.02	R
TMK042 CG3R9∏D-W			CG	COG	3.9 p	±0.1pF, ±0.25pF	478	200	0.2±0.02	R
TMK042 CG040[D-W			CG	COG	4 p	±0.1pF, ±0.25pF	480	200	0.2±0.02	R
TMK042 CG4R1□D-W			CG	COG	4.1 p	±0.1pF, ±0.25pF	482	200	0.2±0.02	R
TMK042 CG4R2∏D-W		25	CG	COG	4.2 p	±0.1pF, ±0.25pF	484	200	0.2 ± 0.02	R
TMK042 CG4R3[D-W			CG	COG	4.3 p	±0.1pF, ±0.25pF	486	200	0.2 ± 0.02	R
TMK042 CG4R4[]D-W			CG	COG	4.4 p	±0.1pF, ±0.25pF	488	200	0.2 ± 0.02	R
TMK042 CG4R5∏D-W			CG	COG	4.5 p	±0.1pF, ±0.25pF	490	200	0.2±0.02	R
TMK042 CG4R6∏D-W			CG	COG	4.6 p	±0.1pF, ±0.25pF	492	200	0.2±0.02	R
TMK042 CG4R7∏D-W			CG	COG	4.7 p	±0.1pF, ±0.25pF	494	200	0.2 ± 0.02	R
TMK042 CG4R8[]D-W			CG	C0G	4.8 p	±0.1pF, ±0.25pF	496	200	0.2±0.02	R
TMK042 CG4R9∏D-W			CG	COG	4.9 p	±0.1pF, ±0.25pF	498	200	0.2 ± 0.02	R
TMK042 CG050∏D-W			CG	C0G	5 p	±0.1pF, ±0.25pF	500	200	0.2 ± 0.02	R
TMK042 CG5R1∏D-W			CG	C0G	5.1 p	±0.1pF, ±0.25pF, ±0.5pF	502	200	0.2 ± 0.02	R
TMK042 CG5R2[]D-W			CG	C0G	5.2 p	±0.1pF, ±0.25pF, ±0.5pF	504	200	0.2 ± 0.02	R
TMK042 CG5R3∏D-W			CG	C0G	5.3 p	±0.1pF, ±0.25pF, ±0.5pF	506	200	0.2 ± 0.02	R
TMK042 CG5R4∏D-W		_	CG	C0G	5.4 p	±0.1pF, ±0.25pF, ±0.5pF	508	200	0.2 ± 0.02	R
TMK042 CG5R5[]D-W		」	CG	C0G	5.5 p	±0.1pF, ±0.25pF, ±0.5pF	510	200	0.2 ± 0.02	R
TMK042 CG5R6∏D-W		_	CG	C0G	5.6 p	±0.1pF, ±0.25pF, ±0.5pF	512	200	0.2±0.02	R
TMK042 CG5R7[]D-W		」	CG	C0G	5.7 p	±0.1pF, ±0.25pF, ±0.5pF	514	200	0.2 ± 0.02	R
TMK042 CG5R8[]D-W		」	CG	C0G	5.8 p	±0.1pF, ±0.25pF, ±0.5pF	516	200	0.2±0.02	R
TMK042 CG5R9[D-W		」	CG	C0G	5.9 p	±0.1pF, ±0.25pF, ±0.5pF	518	200	0.2 ± 0.02	R
TMK042 CG060∏D-W		」	CG	C0G	6 p	±0.1pF, ±0.25pF, ±0.5pF	520	200	0.2 ± 0.02	R
TMK042 CG6R1∏D-W		⊣	CG	C0G	6.1 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	522	200	0.2 ± 0.02	R
TMK042 CG6R2[]D-W		」	CG	C0G	6.2 p	±0.1pF, ±0.25pF, ±0.5pF	524	200	0.2 ± 0.02	R
TMK042 CG6R3∏D-W			CG	C0G	6.3 p	$\pm 0.1 pF$, $\pm 0.25 pF$, $\pm 0.5 pF$	526	200	0.2 ± 0.02	R
TMK042 CG6R4[]D-W		」	CG	C0G	6.4 p	±0.1pF, ±0.25pF, ±0.5pF	528	200	0.2±0.02	R
TMK042 CG6R5[]D-W		」	CG	C0G	6.5 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	530	200	0.2 ± 0.02	R
TMK042 CG6R6[]D-W		⊣	CG	C0G	6.6 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	532	200	0.2 ± 0.02	R
TMK042 CG6R7[]D-W		_	CG	C0G	6.7 p	±0.1pF, ±0.25pF, ±0.5pF	534	200	0.2±0.02	R
TMK042 CG6R8[]D-W			CG	C0G	6.8 p	±0.1pF, ±0.25pF, ±0.5pF	536	200	0.2 ± 0.02	R
TMK042 CG6R9∏D-W		_	CG	C0G	6.9 p	±0.1pF, ±0.25pF, ±0.5pF	538	200	0.2±0.02	R
TMK042 CG070[]D-W			CG	C0G	7 p	±0.1pF, ±0.25pF, ±0.5pF	540	200	0.2 ± 0.02	R
TMK042 CG7R1∏D-W			CG	C0G	7.1 p	±0.1pF, ±0.25pF, ±0.5pF	542	200	0.2 ± 0.02	R
TMK042 CG7R2∏D-W			CG	C0G	7.2 p	±0.1pF, ±0.25pF, ±0.5pF	544	200	0.2 ± 0.02	R
TMK042 CG7R3∏D-W			CG	COG	7.3 p	±0.1pF, ±0.25pF, ±0.5pF	546	200	0.2 ± 0.02	R

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Part number 1	Part number 2	Rated voltage		erature	Capacitance	Capacitance tolerance	Q (at 1MHz)	HTLT	Thickness*3 [mm]	Soldering R:Reflow
		[V]	charact	eristics	[F]		min	Rated voltage x %	THIORICOS [HIII]	W:Wave
TMK042 CG7R4∏D-W			CG	COG	7.4 p	±0.1pF, ±0.25pF, ±0.5pF	548	200	0.2±0.02	R
TMK042 CG7R5∏D-W			CG	COG	7.5 p	±0.1pF, ±0.25pF, ±0.5pF	550	200	0.2±0.02	R
TMK042 CG7R6□D-W		1	CG	COG	7.6 p	±0.1pF, ±0.25pF, ±0.5pF	552	200	0.2 ± 0.02	R
TMK042 CG7R7∏D-W		1	CG	COG	7.7 p	±0.1pF, ±0.25pF, ±0.5pF	554	200	0.2 ± 0.02	R
TMK042 CG7R8□D-W		1	CG	COG	7.8 p	±0.1pF, ±0.25pF, ±0.5pF	556	200	0.2 ± 0.02	R
TMK042 CG7R9∏D-W		1	CG	COG	7.9 p	±0.1pF, ±0.25pF, ±0.5pF	558	200	0.2 ± 0.02	R
TMK042 CG080∏D-W			CG	COG	8 p	±0.1pF, ±0.25pF, ±0.5pF	560	200	0.2±0.02	R
TMK042 CG8R1□D-W			CG	COG	8.1 p	±0.1pF, ±0.25pF, ±0.5pF	562	200	0.2 ± 0.02	R
TMK042 CG8R2□D-W			CG	COG	8.2 p	±0.1pF, ±0.25pF, ±0.5pF	564	200	0.2 ± 0.02	R
TMK042 CG8R3∏D-W			CG	COG	8.3 p	±0.1pF, ±0.25pF, ±0.5pF	566	200	0.2 ± 0.02	R
TMK042 CG8R4□D-W			CG	COG	8.4 p	±0.1pF, ±0.25pF, ±0.5pF	568	200	0.2 ± 0.02	R
TMK042 CG8R5∏D-W		1	CG	COG	8.5 p	±0.1pF, ±0.25pF, ±0.5pF	570	200	0.2 ± 0.02	R
TMK042 CG8R6□D-W		1	CG	COG	8.6 p	±0.1pF, ±0.25pF, ±0.5pF	572	200	0.2 ± 0.02	R
TMK042 CG8R7∏D-W		1	CG	COG	8.7 p	±0.1pF, ±0.25pF, ±0.5pF	574	200	0.2 ± 0.02	R
TMK042 CG8R8□D-W		1	CG	COG	8.8 p	±0.1pF, ±0.25pF, ±0.5pF	576	200	0.2 ± 0.02	R
TMK042 CG8R9□D-W		1	CG	COG	8.9 p	±0.1pF, ±0.25pF, ±0.5pF	578	200	0.2 ± 0.02	R
TMK042 CG090□D-W		1	CG	COG	9 p	±0.1pF, ±0.25pF, ±0.5pF	580	200	0.2±0.02	R
TMK042 CG9R1□D-W		1	CG	COG	9.1 p	±0.1pF, ±0.25pF, ±0.5pF	582	200	0.2±0.02	R
TMK042 CG9R2□D-W		1	CG	COG	9.2 p	±0.1pF, ±0.25pF, ±0.5pF	584	200	0.2±0.02	R
TMK042 CG9R3□D-W		1	CG	COG	9.3 p	±0.1pF, ±0.25pF, ±0.5pF	586	200	0.2±0.02	R
TMK042 CG9R4□D-W		1	CG	COG	9.4 p	±0.1pF, ±0.25pF, ±0.5pF	588	200	0.2±0.02	R
TMK042 CG9R5□D-W		1	CG	COG	9.5 p	±0.1pF, ±0.25pF, ±0.5pF	590	200	0.2 ± 0.02	R
TMK042 CG9R6□D-W		1	CG	COG	9.6 p	±0.1pF, ±0.25pF, ±0.5pF	592	200	0.2 ± 0.02	R
TMK042 CG9R7□D-W		1	CG	COG	9.7 p	±0.1pF, ±0.25pF, ±0.5pF	594	200	0.2±0.02	R
TMK042 CG9R8∏D-W		1	CG	COG	9.8 p	±0.1pF, ±0.25pF, ±0.5pF	596	200	0.2 ± 0.02	R
TMK042 CG9R9∏D-W		25	CG	COG	9.9 p	±0.1pF, ±0.25pF, ±0.5pF	598	200	0.2±0.02	R
TMK042 CG100DD-W		1	CG	COG	10 p	±0.5pF	600	200	0.2±0.02	R
TMK042 CG110JD-W			CG	COG	11 p	±5%	620	200	0.2±0.02	R
TMK042 CG120JD-W		1	CG	COG	12 p	±5%	640	200	0.2 ± 0.02	R
TMK042 CG130JD-W			CG	COG	13 p	±5%	660	200	0.2±0.02	R
TMK042 CG150JD-W		1	CG	COG	15 p	±5%	700	200	0.2±0.02	R
TMK042 CG160JC-W		1	CG	COG	16 p	±5%	720	200	0.2 ± 0.02	R
TMK042 CG180JC-W		1	CG	COG	18 p	±5%	760	200	0.2 ± 0.02	R
TMK042 CG200JC-W		1	CG	COG	20 p	±5%	800	200	0.2 ± 0.02	R
TMK042 CG220JC-W		1	CG	COG	22 p	±5%	840	200	0.2 ± 0.02	R
TMK042 CG240JC-W		1	CG	COG	24 p	±5%	880	200	0.2 ± 0.02	R
TMK042 CG270JC-W			CG	COG	27 p	±5%	940	200	0.2±0.02	R
TMK042 CG300JC-W		1	CG	COG	30 p	±5%	1000	200	0.2 ± 0.02	R
TMK042 CG330JC-W			CG	COG	33 р	±5%	1000	200	0.2±0.02	R
TMK042 CG360JC-W		1	CG	COG	36 p	±5%	1000	200	0.2±0.02	R
TMK042 CG390JC-W		1	CG	COG	39 p	±5%	1000	200	0.2±0.02	R
TMK042 CG430JC-W		1	CG	COG	43 p	±5%	1000	200	0.2±0.02	R
TMK042 CG470JC-W		1	CG	COG	47 p	±5%	1000	200	0.2±0.02	R
TMK042 CG510JC-W		1	CG	COG	51 p	±5%	1000	200	0.2±0.02	R
TMK042 CG560JC-W		1	CG	COG	56 p	±5%	1000	200	0.2±0.02	R
TMK042 CG620JC-W		1	CG	COG	62 p	±5%	1000	200	0.2±0.02	R
TMK042 CG680JC-W		1	CG	COG	68 p	±5%	1000	200	0.2±0.02	R
TMK042 CG750JC-W		┪ !	CG	COG	75 p	±5%	1000	200	0.2±0.02	R
TMK042 CG820JC-W		┪ !	CG	COG	82 p	±5%	1000	200	0.2±0.02	R
TMK042 CG910JC-W		┪ !	CG	COG	91 p	±5%	1000	200	0.2±0.02	R
TMK042 CG101JC-W		1	CG	COG	100 p	±5%	1000	200	0.2±0.02	R

[Temperature Characteristic CG : CG/C0G(-55~+125°C)] 0.2mm thickness(C,D)

Temperature Charac	teristic CG : CG/C	0G(−55 ~ ∃	F125°C)] 0.2m	nm thicknes	s(C,D)				
Part number 1	Part number 2	Rated voltage [V]	Tempe charact		Capacitance [F]	Capacitance tolerance	Q (at 1MHz) min	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
EMK042 CG010[D-W			CG	COG	1 p	±0.05pF, ±0.1pF, ±0.25pF	420	200	0.2±0.02	R
EMK042 CG1R1□D-W			CG	COG	1.1 p	±0.05pF, ±0.1pF, ±0.25pF	422	200	0.2 ± 0.02	R
EMK042 CG1R2□D-W			CG	COG	1.2 p	±0.05pF, ±0.1pF, ±0.25pF	424	200	0.2 ± 0.02	R
EMK042 CG1R3□D-W			CG	COG	1.3 p	±0.05pF, ±0.1pF, ±0.25pF	426	200	0.2±0.02	R
EMK042 CG1R4□D-W		1	CG	COG	1.4 p	±0.05pF, ±0.1pF, ±0.25pF	428	200	0.2 ± 0.02	R
EMK042 CG1R5□D-W] [CG	COG	1.5 p	±0.05pF, ±0.1pF, ±0.25pF	430	200	0.2 ± 0.02	R
EMK042 CG1R6□D-W] [CG	COG	1.6 p	±0.05pF, ±0.1pF, ±0.25pF	432	200	0.2 ± 0.02	R
EMK042 CG1R7□D-W			CG	COG	1.7 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	434	200	0.2 ± 0.02	R
EMK042 CG1R8□D-W			CG	COG	1.8 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	436	200	0.2 ± 0.02	R
EMK042 CG1R9□D-W			CG	COG	1.9 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	438	200	0.2 ± 0.02	R
EMK042 CG020[D-W			CG	COG	2 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	440	200	0.2 ± 0.02	R
EMK042 CG2R1□D-W			CG	COG	2.1 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	442	200	0.2 ± 0.02	R
EMK042 CG2R2□D-W			CG	COG	2.2 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	444	200	0.2 ± 0.02	R
EMK042 CG2R3∏D-W			CG	COG	2.3 p	±0.05pF, ±0.1pF, ±0.25pF	446	200	0.2 ± 0.02	R
EMK042 CG2R4∏D-W		1	CG	COG	2.4 p	±0.05pF, ±0.1pF, ±0.25pF	448	200	0.2 ± 0.02	R
EMK042 CG2R5∏D-W		1	CG	COG	2.5 p	±0.05pF, ±0.1pF, ±0.25pF	450	200	0.2 ± 0.02	R
EMK042 CG2R6□D-W		16	CG	COG	2.6 p	±0.05pF, ±0.1pF, ±0.25pF	452	200	0.2 ± 0.02	R
EMK042 CG2R7∏D-W		1	CG	COG	2.7 p	±0.05pF, ±0.1pF, ±0.25pF	454	200	0.2 ± 0.02	R
EMK042 CG2R8∏D-W		1	CG	COG	2.8 p	±0.05pF, ±0.1pF, ±0.25pF	456	200	0.2 ± 0.02	R
EMK042 CG2R9∏D-W] [CG	COG	2.9 p	±0.05pF, ±0.1pF, ±0.25pF	458	200	0.2 ± 0.02	R
EMK042 CG030[D-W			CG	COG	3 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	460	200	0.2 ± 0.02	R
EMK042 CG3R1□D-W		1	CG	COG	3.1 p	$\pm 0.1 pF$, $\pm 0.25 pF$	462	200	0.2 ± 0.02	R
EMK042 CG3R2□D-W] [CG	COG	3.2 p	±0.1pF, ±0.25pF	464	200	0.2 ± 0.02	R
EMK042 CG3R3∏D-W] [CG	COG	3.3 p	±0.1pF, ±0.25pF	466	200	0.2 ± 0.02	R
EMK042 CG3R4∏D-W		1	CG	COG	3.4 p	$\pm 0.1 pF$, $\pm 0.25 pF$	468	200	0.2 ± 0.02	R
EMK042 CG3R5∏D-W			CG	COG	3.5 p	±0.1pF, ±0.25pF	470	200	0.2 ± 0.02	R
EMK042 CG3R6∏D-W			CG	COG	3.6 p	±0.1pF, ±0.25pF	472	200	0.2 ± 0.02	R
EMK042 CG3R7[]D-W			CG	C0G	3.7 p	$\pm 0.1 pF$, $\pm 0.25 pF$	474	200	0.2 ± 0.02	R
EMK042 CG3R8∏D-W		1	CG	COG	3.8 p	±0.1pF, ±0.25pF	476	200	0.2±0.02	R
EMK042 CG3R9∏D-W		1	CG	COG	3.9 p	±0.1pF, ±0.25pF	478	200	0.2 ± 0.02	R
EMK042 CG040[D-W]	CG	COG	4 p	±0.1pF, ±0.25pF	480	200	0.2 ± 0.02	R
EMK042 CG4R1∏D-W		1	CG	COG	4.1 p	±0.1pF, ±0.25pF	482	200	0.2±0.02	R
EMK042 CG4R2[]D-W		1	CG	COG	4.2 p	±0.1pF, ±0.25pF	484	200	0.2±0.02	R

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

Part number 1	Part number 2	Rated voltage [V]		erature eristics	Capacitance [F]	Capacitance tolerance	Q (at 1MHz) min	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
EMK042 CG4R3∏D-W			CG	COG	4.3 p	±0.1pF, ±0.25pF	486	200	0.2±0.02	R
EMK042 CG4R4 D-W			CG	COG	4.4 p	±0.1pF, ±0.25pF	488	200	0.2±0.02	R
EMK042 CG4R5 D-W		1	CG	COG	4.5 p	±0.1pF, ±0.25pF	490	200	0.2±0.02	R
EMK042 CG4R6 D-W			CG	COG	4.6 p	±0.1pF, ±0.25pF	492	200	0.2±0.02	R
EMK042 CG4R0[]D-W			CG	COG	4.0 p	±0.1pF, ±0.25pF	494	200	0.2±0.02	R
EMK042 CG4R7 D-W		•	CG	COG	4.7 p	±0.1pF, ±0.25pF	496	200	0.2±0.02	R
			CG	COG			498	200	0.2±0.02 0.2±0.02	R
EMK042 CG4R9 D-W			CG	COG	4.9 p	±0.1pF, ±0.25pF	500	200	0.2±0.02	R
EMK042 CG050[]D-W					5 p	±0.1pF, ±0.25pF	502	200	0.2±0.02 0.2±0.02	R
EMK042 CG5R1 D-W EMK042 CG5R2 D-W			CG	C0G C0G	5.1 p 5.2 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	504	200	0.2±0.02	R
EMK042 CG5R3 D-W			CG	COG	5.2 p	±0.1pF, ±0.25pF, ±0.5pF	506	200	0.2±0.02 0.2±0.02	R
EMK042 CG5R4 D-W			CG	COG	5.4 p	±0.1pF, ±0.25pF, ±0.5pF	508	200	0.2±0.02	R
EMK042 CG5R5 D-W			CG	COG	5.5 p	±0.1pF, ±0.25pF, ±0.5pF	510	200	0.2±0.02	R
EMK042 CG5R6 D-W			CG	COG	5.6 p	±0.1pF, ±0.25pF, ±0.5pF	512	200	0.2±0.02 0.2±0.02	R
EMK042 CG5R7 D-W			CG	COG	5.0 p	±0.1pF, ±0.25pF, ±0.5pF	514	200	0.2±0.02 0.2±0.02	R
EMK042 CG5R8 D-W			CG	COG	5.7 p	±0.1pF, ±0.25pF, ±0.5pF	516	200	0.2±0.02 0.2±0.02	R
EMK042 CG5R9 D-W			CG	COG	5.9 p	±0.1pF, ±0.25pF, ±0.5pF	518	200	0.2±0.02 0.2±0.02	R
EMK042 CG060 D-W			CG	COG	6 p	±0.1pF, ±0.25pF, ±0.5pF	520	200	0.2±0.02	R
EMK042 CG6R1 D-W			CG	COG	6.1 p	±0.1pF, ±0.25pF, ±0.5pF	522	200	0.2±0.02	R
EMK042 CG6R2 D-W			CG	COG	6.2 p	±0.1pF, ±0.25pF, ±0.5pF	524	200	0.2±0.02	R
EMK042 CG6R3[]D-W			CG	COG	6.3 p	±0.1pF, ±0.25pF, ±0.5pF	526	200	0.2±0.02	R
EMK042 CG6R4[]D-W			CG	COG	6.4 p	±0.1pF, ±0.25pF, ±0.5pF	528	200	0.2±0.02 0.2±0.02	R
			CG	COG		±0.1pF, ±0.25pF, ±0.5pF	530	200		R
EMK042 CG6R5∏D-W EMK042 CG6R6∏D-W			CG	COG	6.5 p 6.6 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	532	200	0.2±0.02 0.2±0.02	R
EMK042 CG6R6 D-W			CG	COG	6.7 p		532	200	0.2±0.02 0.2±0.02	R
EMK042 CG6R7[]D-W			CG	COG	6.7 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	534	200	0.2±0.02 0.2±0.02	R
EMK042 CG6R8 D-W			CG	COG	6.9 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	538	200	0.2±0.02 0.2±0.02	R
EMK042 CG6R9[]D-W			CG	COG	6.9 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	538	200	0.2±0.02 0.2±0.02	R
EMK042 CG070 D-W			CG	COG	7,1 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	540	200	0.2±0.02 0.2±0.02	R
EMK042 CG/RT[]D-W			CG	COG	7.1 p 7.2 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	542	200	0.2±0.02 0.2±0.02	R
EMK042 CG7R2[]D-W			CG	COG	7.2 p 7.3 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	544	200	0.2±0.02 0.2±0.02	R
EMK042 CG7R3[]D-W			CG	COG	7.3 p	±0.1pF, ±0.25pF, ±0.5pF	548	200	0.2±0.02 0.2±0.02	R
EMK042 CG7R5[]D-W			CG	COG	7.4 p	±0.1pF, ±0.25pF, ±0.5pF	550	200	0.2±0.02 0.2±0.02	R
				COG						
EMK042 CG7R6∏D-W EMK042 CG7R7∏D-W			CG		7.6 p	±0.1pF, ±0.25pF, ±0.5pF	552	200	0.2±0.02	R
			CG	COG	7.7 p	±0.1pF, ±0.25pF, ±0.5pF	554	200	0.2±0.02	R
EMK042 CG7R8[]D-W			CG	COG	7.8 p	±0.1pF, ±0.25pF, ±0.5pF	556	200	0.2±0.02	R
EMK042 CG7R9[]D-W			CG	COG	7.9 p	±0.1pF, ±0.25pF, ±0.5pF	558	200	0.2±0.02	R
EMK042 CG080[]D-W			CG	COG	8 p	±0.1pF, ±0.25pF, ±0.5pF	560	200	0.2±0.02	R
EMK042 CG8R1 D-W			CG	COG	8.1 p	±0.1pF, ±0.25pF, ±0.5pF	562	200	0.2±0.02	R
EMK042 CG8R2[]D-W			CG	COG	8.2 p	±0.1pF, ±0.25pF, ±0.5pF	564	200	0.2±0.02	R
EMK042 CG8R3[D-W			CG	COG	8.3 p	±0.1pF, ±0.25pF, ±0.5pF	566	200	0.2±0.02	R
EMK042 CG8R4[]D-W			CG	COG	8.4 p	±0.1pF, ±0.25pF, ±0.5pF	568	200 200	0.2±0.02	R
EMK042 CG8R5[]D-W		16	CG	COG	8.5 p	±0.1pF, ±0.25pF, ±0.5pF	570	200	0.2±0.02	R R
EMK042 CG8R6[]D-W			CG	COG	8.6 p	±0.1pF, ±0.25pF, ±0.5pF	572		0.2±0.02	
EMK042 CG8R7[]D-W			CG	COG	8.7 p	±0.1pF, ±0.25pF, ±0.5pF	574	200	0.2±0.02	R
EMK042 CG8R8[]D-W			CG	COG	8.8 p	±0.1pF, ±0.25pF, ±0.5pF	576	200	0.2±0.02	R
EMK042 CG8R9[D-W			CG	COG	8.9 p	±0.1pF, ±0.25pF, ±0.5pF	578	200	0.2±0.02	R
EMK042 CG090 D-W			CG	COG	9 p	±0.1pF, ±0.25pF, ±0.5pF	580	200	0.2±0.02	R
EMK042 CG9R1 D-W			CG	COG	9.1 p	±0.1pF, ±0.25pF, ±0.5pF	582	200	0.2±0.02	R
EMK042 CG9R2 D-W			CG	COG	9.2 p	±0.1pF, ±0.25pF, ±0.5pF	584 586	200 200	0.2±0.02	R R
EMK042 CG9R3∏D-W EMK042 CG9R4∏D-W			CG	COG	9.3 p	±0.1pF, ±0.25pF, ±0.5pF	588	200	0.2±0.02	
EMK042 CG9R5 D-W				COG	9.4 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF			0.2±0.02	R
EMK042 CG9R6 D-W			CG	C0G C0G	9.5 p		590 592	200 200	0.2±0.02 0.2±0.02	R
					9.6 p	±0.1pF, ±0.25pF, ±0.5pF				R
EMK042 CG9R7 D-W			CG	C0G	9.7 p 9.8 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	594	200	0.2±0.02	R
EMK042 CG9R8□D-W EMK042 CG9R9□D-W	<u> </u>		CG	C0G C0G			596	200 200	0.2±0.02 0.2±0.02	R R
EMK042 CG9R9[]D-W					9.9 p	±0.1pF, ±0.25pF, ±0.5pF	598	200	0.2±0.02 0.2±0.02	
EMK042 CG100DD-W EMK042 CG110JD-W	<u> </u>		CG	C0G C0G	10 p	±0.5pF +504	600 620	200		R R
EMK042 CG110JD-W EMK042 CG120JD-W				COG	11 p	±5% +5%	640	200	0.2±0.02 0.2±0.02	R
EMK042 CG120JD-W EMK042 CG130JD-W			CG	COG	12 p 13 p	±5% ±5%	660	200	0.2±0.02 0.2±0.02	R
EMK042 CG130JD-W			CG	COG	13 p	±5%	700	200	0.2±0.02 0.2±0.02	R
EMK042 CG150JD-W			CG	COG	16 p	±5%	700	200	0.2±0.02 0.2±0.02	R
EMK042 CG180JC-W			CG	COG	18 p	±5%	760	200	0.2±0.02 0.2±0.02	R
EMK042 CG200JC-W			CG	COG	20 p	±5%	800	200	0.2±0.02 0.2±0.02	R
EMK042 CG200JC-W			CG	COG	20 p 22 p	±5%	840	200	0.2±0.02 0.2±0.02	R
EMK042 CG220JC-W EMK042 CG240JC-W			CG	COG	22 p 24 p	±5%	880	200	0.2±0.02 0.2±0.02	R
EMK042 CG270JC-W			CG	COG	24 p	±5%	940	200	0.2±0.02	R
EMK042 CG270JC-W			CG	COG	27 p 30 p	±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG330JC-W			CG	COG	30 p	±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG330JC-W			CG	COG	36 p	±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG390JC-W			CG	COG	30 p	±5%	1000	200	0.2±0.02	R
EMK042 CG390JC-W EMK042 CG430JC-W			CG	COG	39 p 43 p	±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG430JC-W			CG	COG	43 p 47 p	±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG510JC-W			CG	COG	47 p 51 p	±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG5103C-W			CG	COG	56 p	±5%	1000	200	0.2±0.02	R
EMK042 CG560JC-W			CG	COG	62 p	±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG620JC-W			CG	COG	68 p	±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG750JC-W			CG	COG	75 p	±5%	1000	200	0.2±0.02	R
EMK042 CG750JC-W			CG	COG	75 p 82 p	±5% ±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG820JC-W EMK042 CG910JC-W			CG	COG	82 p 91 p	±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG910JC-W			CG	COG	91 p 100 p		1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG101JC-W			CG	COG	220 p	±5% ±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG221JC-W EMK042 CG241JC-W	<u> </u>		CG	COG	220 p 240 p	±5% ±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG241JC-W			CG	COG	240 p 270 p	±5%	1000	200	0.2±0.02 0.2±0.02	R
EMK042 CG2713C-W			CG	COG	330 p	±5%	1000	200	0.2±0.02	R
	l .	ıl	Ju	JJu	, 500 р	_5/0	1000	200	U.L U.UL	

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PARTS NUMBER 063TYPE

[Temperature Characteristic CG : CG/C0G($-55\sim+125^{\circ}$ C)] 0.3mm thickness(T)

Part number 1	Part number 2	Rated voltage [V]		erature teristics	Capacitance [F]	Capacitance tolerance	Q (at 1MHz)	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow
UMK063 CG200JT-F		2.3	CG	COG	20 p	±5%	min 800	200	0.3±0.03	W:Wave R
UMK063 CG220JT-F		1	CG	COG	20 p	±5%	840	200	0.3±0.03	R
UMK063 CG2203T-F			CG	COG	24 p	±5%	880	200	0.3±0.03	R
UMK063 CG270JT-F			CG	COG	24 p	±5%	940	200	0.3±0.03	R
UMK063 CG2703T-F			CG	COG	27 p	±5%	1000	200	0.3±0.03	R
UMK063 CG330JT-F		1	CG	COG	30 p	±5%	1000	200	0.3±0.03	R
UMK063 CG360JT-F		1	CG	COG	36 p	±5%	1000	200	0.3±0.03	R
UMK063 CG390JT-F		1	CG	COG	30 p	±5%	1000	200	0.3±0.03	R
UMK063 CG3903T-F		1	CG	COG	43 p	±5%	1000	200	0.3±0.03	R
UMK063 CG470JT-F		1	CG	COG	43 p 47 p	±5%	1000	200	0.3±0.03	R
UMK063 CG510JT-F		1	CG	COG	47 p 51 p	±5%	1000	200	0.3±0.03	R
UMK063 CG560JT-F		1	CG	COG	56 p	±5%	1000	200	0.3±0.03	R
UMK063 CG620JT-F		50	CG	COG	62 p	±5%	1000	200	0.3±0.03	R
UMK063 CG680JT-F		- 30	CG	COG	d 20 a 86	±5%	1000	200	0.3±0.03	R
UMK063 CG750JT-F		1	CG	COG	75 p	±5%	1000	200	0.3±0.03	R
UMK063 CG73031 F		1	CG	COG	73 p 82 p	±5%	1000	200	0.3±0.03	R
UMK063 CG910JT-F		1	CG	COG	91 p	±5%	1000	200	0.3±0.03	R
UMK063 CG91031-F		1	CG	COG	g 100 p	±5%	1000	200	0.3±0.03	R
UMK063 CG1013T-F		1	CG	COG	110 p	±5%	1000	200	0.3±0.03	R
UMK063 CG121JT-F		1	CG	COG	110 p	±5%	1000	200	0.3±0.03	R
UMK063 CG12131 T-F		1	CG	COG	120 p	±5%	1000	200	0.3±0.03	R
UMK063 CG151JT-F			CG	COG	150 p	±5%	1000	200	0.3±0.03	R
UMK063 CG181JT-F			CG	COG	180 p	±5%	1000	200	0.3±0.03	R
UMK063 CG201JT-F			CG	COG	200 p	±5%	1000	200	0.3±0.03	R
UMK063 CG221JT-F			CG	COG	220 p	±5%	1000	200	0.3±0.03	R
TMK063 CG241JT-F			CG	COG	240 p	±5%	1000	200	0.3±0.03	R
TMK063 CG271JT-F			CG	COG	270 p	±5%	1000	200	0.3±0.03	R
TMK063 CG301JT-F			CG	COG	300 p	±5%	1000	200	0.3±0.03	R
TMK063 CG331JT-F			CG	COG	330 p	±5%	1000	200	0.3±0.03	R
TMK063 CG361JT-F			CG	COG	360 p	±5%	1000	200	0.3±0.03	R
TMK063 CG391JT-F			CG	COG	390 p	±5%	1000	200	0.3±0.03	R
TMK063 CG431JT-F		1	CG	COG	430 p	±5%	1000	200	0.3±0.03	R
TMK063 CG471JT-F			CG	COG	470 p	±5%	1000	200	0.3±0.03	R
TMK063 CG511JT-F		25	CG	COG	510 p	±5%	1000	200	0.3±0.03	R
TMK063 CG561JT-F			CG	COG	560 p	±5%	1000	200	0.3±0.03	R
TMK063 CG621JT-F		1	CG	COG	620 p	±5%	1000	200	0.3±0.03	R
TMK063 CG681JT-F		1	CG	COG	680 p	±5%	1000	200	0.3±0.03	R
TMK063 CG751JT-F		1	CG	COG	750 p	±5%	1000	200	0.3±0.03	R
TMK063 CG821JT-F		1	CG	COG	820 p	±5%	1000	200	0.3±0.03	R
TMK063 CG911JT-F		1	CG	COG	910 p	±5%	1000	200	0.3±0.03	R
TMK063 CG102JT-F		1	CG	COG	1000 p	±5%	1000	200	0.3±0.03	R

●105TYPE 【Temperature

[Temperature Characteristic U \triangle : U \triangle /U2 \triangle ($-55\sim+125^{\circ}$ C)] 0.5mm thickness(V)

Part number 1	Part number 2	Rated voltage [V]	Tempe charact		Capacitance [F]	Capacitance tolerance	Q (at 1MHz) min	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
UMK105 UK0R5CV-F			UK	U2K	0.5 p	±0.25pF	410	200	0.5±0.05	R
UMK105 UK010CV-F			UK	U2K	1 p	±0.25pF	420	200	0.5 ± 0.05	R
UMK105 UK1R5CV-F			UK	U2K	1.5 p	±0.25pF	430	200	0.5 ± 0.05	R
UMK105 UK020CV-F			UK	U2K	2 p	±0.25pF	440	200	0.5±0.05	R
UMK105 UK030CV-F			UK	U2K	3 p	±0.25pF	460	200	0.5 ± 0.05	R
UMK105 UJ040CV-F			UJ	U2J	4 p	±0.25pF	480	200	0.5±0.05	R
UMK105 UJ050CV-F			UJ	U2J	5 p	±0.25pF	500	200	0.5 ± 0.05	R
UMK105 UJ060DV-F			UJ	U2J	6 p	±0.5pF	520	200	0.5 ± 0.05	R
UMK105 UJ070DV-F			UJ	U2J	7 p	±0.5pF	540	200	0.5 ± 0.05	R
UMK105 UJ080DV-F			UJ	U2J	8 p	±0.5pF	560	200	0.5 ± 0.05	R
UMK105 UJ090DV-F			UJ	U2J	9 p	±0.5pF	580	200	0.5 ± 0.05	R
UMK105 UJ100DV-F			UJ	U2J	10 p	±0.5pF	600	200	0.5 ± 0.05	R
UMK105 UJ120JV-F			UJ	U2J	12 p	±5%	640	200	0.5 ± 0.05	R
UMK105 UJ150JV-F			UJ	U2J	15 p	±5%	700	200	0.5 ± 0.05	R
UMK105 UJ180JV-F		50	UJ	U2J	18 p	±5%	760	200	0.5 ± 0.05	R
UMK105 UJ220JV-F		30	UJ	U2J	22 p	±5%	840	200	0.5 ± 0.05	R
UMK105 UJ270JV-F			UJ	U2J	27 p	±5%	940	200	0.5 ± 0.05	R
UMK105 UJ330JV-F			UJ	U2J	33 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ390JV-F			UJ	U2J	39 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ470JV-F			UJ	U2J	47 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ560JV-F			UJ	U2J	56 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ680JV-F			UJ	U2J	68 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ820JV-F			UJ	U2J	82 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ101JV-F			UJ	U2J	100 p	±5%	1000	200	0.5±0.05	R
UMK105 UJ121JV-F			UJ	U2J	120 p	±5%	1000	200	0.5±0.05	R
UMK105 UJ151JV-F			UJ	U2J	150 p	±5%	1000	200	0.5±0.05	R
UMK105 UJ181JV-F			UJ	U2J	180 p	±5%	1000	200	0.5±0.05	R
UMK105 UJ221JV-F			UJ	U2J	220 p	±5%	1000	200	0.5±0.05	R
UMK105 UJ271JV-F			UJ	U2J	270 р	±5%	1000	200	0.5±0.05	R
UMK105 UJ331JV-F			UJ	U2J	330 p	±5%	1000	200	0.5 ± 0.05	R

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Multilayer Ceramic Capacitors for High Frequency Applications (1GHz+)

021TYPE

[Temperature Characteristic CG: CG/C0G($-55\sim+125^{\circ}$ C)] 0.125mm thickness(K)

Part number 1	Part number 2	Rated voltage [V]	Tempe	erature eristics	5mm thickr Capacitance [F]	Capacitance tolerance	Q (at 1GHz) (min)	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow
TVS021 CH0R9∏K-W			CG	C0G	0.9 p	±0.05pF, ±0.1pF, ±0.25pF	260	200	0.125±0.013	W:Wave R
TVS021 CG010∏K-W			CG	COG	1 p	±0.05pF, ±0.1pF, ±0.25pF	260	200	0.125±0.013	R
TVS021 CG1R1∏K-W			CG	COG	1.1 p	±0.05pF, ±0.1pF, ±0.25pF	260	200	0.125±0.013	R
TVS021 CG1R2[K-W			CG	C0G	1.2 p	±0.05pF, ±0.1pF, ±0.25pF	250	200	0.125±0.013	R
TVS021 CG1R3∏K-W			CG	COG	1.3 p	±0.05pF, ±0.1pF, ±0.25pF	230	200	0.125±0.013	R
TVS021 CG1R4∏K-W			CG	COG	1.4 p	±0.05pF, ±0.1pF, ±0.25pF	220	200	0.125±0.013	R
TVS021 CG1R5∏K-W			CG	COG	1.5 p	±0.05pF, ±0.1pF, ±0.25pF	210	200	0.125±0.013	R
TVS021 CG1R6∏K-W			CG	C0G	1.6 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	190	200	0.125±0.013	R
TVS021 CG1R7∏K-W			CG	C0G	1.7 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	190	200	0.125±0.013	R
TVS021 CG1R8 K-W			CG	C0G	1.8 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	180	200	0.125±0.013	R
TVS021 CG1R9 K-W			CG	C0G	1.9 p	±0.05pF, ±0.1pF, ±0.25pF	170	200	0.125±0.013	R
TVS021 CG020[K-W			CG	COG	2 p	±0.05pF, ±0.1pF, ±0.25pF	160	200	0.125±0.013	R
TVS021 CG2R1[K-W			CG	COG	2.1 p	±0.05pF, ±0.1pF, ±0.25pF	160	200	0.125±0.013	R
TVS021 CG2R2∏K-W TVS021 CG2R3∏K-W		_	CG	COG	2.2 p	±0.05pF, ±0.1pF, ±0.25pF	150	200	0.125±0.013	R
TVS021 CG2R3 K-W		-	CG	C0G	2.3 p	±0.05pF, ±0.1pF, ±0.25pF ±0.05pF, ±0.1pF, ±0.25pF	150 140	200 200	0.125±0.013 0.125±0.013	R R
TVS021 CG2R4[K-W		-	CG	C0G C0G	2.4 p 2.5 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	140	200	0.125±0.013	R
TVS021 CG2R6[K-W		-	CG	COG	2.5 p	±0.05pF, ±0.1pF, ±0.25pF	130	200	0.125±0.013	R
TVS021 CG2R7 K-W		1	CG	COG	2.7 p	±0.05pF, ±0.1pF, ±0.25pF	130	200	0.125±0.013	R
TVS021 CG2R8 K-W		1	CG	COG	2.7 p	±0.05pF, ±0.1pF, ±0.25pF	120	200	0.125±0.013	R
TVS021 CG2R9[K-W		1	CG	COG	2.0 p	±0.05pF, ±0.1pF, ±0.25pF	120	200	0.125±0.013	R
TVS021 CG030[K-W		25	CG	COG	3 p	±0.1pF, ±0.25pF, ±0.5pF	120	200	0.125±0.013	R
TVS021 CG3R1 K-W		20	CG	COG	3.1 p	±0.1pF, ±0.25pF, ±0.5pF	110	200	0.125±0.013	R
TVS021 CG3R2[K-W		1	CG	COG	3.2 p	±0.1pF, ±0.25pF, ±0.5pF	110	200	0.125±0.013	R
TVS021 CG3R3[K-W		1 .	CG	COG	3.3 p	±0.1pF, ±0.25pF, ±0.5pF	110	200	0.125±0.013	R
TVS021 CG3R4[K-W		1	CG	COG	3.4 p	±0.1pF, ±0.25pF, ±0.5pF	110	200	0.125±0.013	R
TVS021 CG3R5[K-W		1	CG	COG	3.5 p	±0.1pF, ±0.25pF, ±0.5pF	100	200	0.125±0.013	R
TVS021 CG3R6□K-W		1	CG	COG	3.6 p	±0.1pF, ±0.25pF, ±0.5pF	100	200	0.125±0.013	R
TVS021 CG3R7[K-W		1	CG	COG	3.7 p	±0.1pF, ±0.25pF, ±0.5pF	100	200	0.125±0.013	R
TVS021 CG3R8□K-W		1	CG	COG	3.8 p	±0.1pF, ±0.25pF, ±0.5pF	100	200	0.125±0.013	R
TVS021 CG3R9∏K-W]	CG	COG	3.9 p	±0.1pF, ±0.25pF, ±0.5pF	90	200	0.125±0.013	R
TVS021 CG040∏K-W			CG	COG	4 p	±0.1pF, ±0.25pF, ±0.5pF	90	200	0.125±0.013	R
TVS021 CG4R1∏K-W			CG	COG	4.1 p	±0.1pF, ±0.25pF, ±0.5pF	90	200	0.125±0.013	R
TVS021 CG4R2∏K-W			CG	C0G	4.2 p	±0.1pF, ±0.25pF, ±0.5pF	90	200	0.125±0.013	R
TVS021 CG4R3∏K-W			CG	COG	4.3 p	±0.1pF, ±0.25pF, ±0.5pF	90	200	0.125±0.013	R
TVS021 CG4R4∏K-W			CG	COG	4.4 p	±0.1pF, ±0.25pF, ±0.5pF	90	200	0.125±0.013	R
TVS021 CG4R5∏K-W			CG	COG	4.5 p	±0.1pF, ±0.25pF, ±0.5pF	80	200	0.125±0.013	R
TVS021 CG4R6∐K-W			CG	COG	4.6 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	80	200	0.125 ± 0.013	R
TVS021 CG4R7∏K-W			CG	C0G	4.7 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	80	200	0.125±0.013	R
TVS021 CG4R8 K-W			CG	COG	4.8 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	80	200	0.125±0.013	R
TVS021 CG4R9[K-W			CG	C0G	4.9 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	80	200	0.125±0.013	R
TVS021 CG050[K-W			CG	COG	5 p	±0.1pF, ±0.25pF, ±0.5pF	80	200	0.125±0.013	R
TVS021 CG5R1 K-W			CG	COG	5.1 p	±0.1pF, ±0.25pF, ±0.5pF	80	200	0.125±0.013	R
EVS021 CG5R2[K-W EVS021 CG5R3[K-W		4	CG	C0G C0G	5.2 p 5.3 p	±0.1pF, ±0.25pF, ±0.5pF	70 70	200 200	0.125±0.013 0.125±0.013	R R
EVS021 CG5R4[K-W		-	CG	COG	5.4 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	70	200	0.125±0.013	R
EVS021 CG5R4[]K-W		-	CG	COG	5.4 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.125±0.013	R
EVS021 CG5R6[]K-W		-	CG	COG	5.6 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.125±0.013	R
EVS021 CG5R7[K-W		1	CG	COG	5.7 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.125±0.013	R
EVS021 CG5R8[K-W			CG	COG	5.8 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.125±0.013	R
EVS021 CG5R9[K-W			CG	COG	5.9 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.125±0.013	R
EVS021 CG060[K-W			CG	COG	6 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.125±0.013	R
EVS021 CG6R1∏K-W			CG	COG	6.1 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.125±0.013	R
EVS021 CG6R2□K-W			CG	COG	6.2 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG6R3∏K-W			CG	COG	6.3 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG6R4[K-W			CG	C0G	6.4 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG6R5[K-W]	CG	C0G	6.5 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG6R6[K-W]	CG	C0G	6.6 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG6R7[K-W		1	CG	C0G	6.7 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG6R8 K-W		4	CG	C0G	6.8 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	60	200	0.125±0.013	R
EVS021 CG6R9[K-W		4	CG	COG	6.9 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG070[K-W	ļ	4	CG	COG	7 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG7R1[K-W		4 .	CG	COG	7.1 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG7R2[K-W		16	CG	COG	7.2 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG7R3[K-W		4	CG	COG	7.3 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG7R4[K-W		4 !	CG	C0G	7.4 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG7R5[K-W		4	CG	C0G	7.5 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.125±0.013	R
EVS021 CG7R6∏K-W EVS021 CG7R7∏K-W		4	CG	COG	7.6 p	±0.1pF, ±0.25pF, ±0.5pF	60 50	200	0.125±0.013	R
		4	CG	COG	7.7 p	±0.1pF, ±0.25pF, ±0.5pF	50		0.125±0.013 0.125±0.013	R
EVS021 CG7R8[K-W		4		COG	7.8 p	±0.1pF, ±0.25pF, ±0.5pF	50	200		R
EVS021 CG7R9∏K-W EVS021 CG080∏K-W		1	CG	C0G C0G	7.9 p 8 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	50	200 200	0.125±0.013 0.125±0.013	R R
EVS021 CG080UK-W EVS021 CG8R1UK-W		1	CG	COG	8.1 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG8R1[]K-W		1 !	CG	COG	8.2 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG8R3[K-W		1	CG	COG	8.3 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG8R4[K-W		1	CG	COG	8.4 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG8R5[K-W		1 !	CG	COG	8.5 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG8R6[K-W		† !	CG	COG	8.6 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG8R7[K-W		1	CG	COG	8.7 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG8R8[K-W		1 !	CG	COG	8.8 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG8R9[K-W		† !	CG	COG	8.9 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG090[K-W		1	CG	COG	9 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG9R1 K-W		1 !	CG	COG	9.1 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG9R1 K-W		1	CG	COG	9.1 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
		-								
EVS021 CG9R3[K-W			CG	COG	9.3 p	$\pm 0.1 pF$, $\pm 0.25 pF$, $\pm 0.5 pF$	50	200	0.125 ± 0.013	R

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Part number 1	Part number 2	Rated voltage [V]		erature eristics	Capacitance [F]	Capacitance tolerance	Q (at 1GHz) (min)	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
EVS021 CG9R4∏K-W			CG	COG	9.4 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	w:wave
										- 1
EVS021 CG9R5∏K-W			CG	COG	9.5 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	50	200	0.125 ± 0.013	R
EVS021 CG9R6∏K-W			CG	COG	9.6 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG9R7∏K-W		16	CG	COG	9.7 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.125±0.013	R
EVS021 CG9R8∏K-W]	CG	COG	9.8 p	±0.1pF, ±0.25pF, ±0.5pF	40	200	0.125±0.013	R
EVS021 CG9R9∏K-W]	CG	COG	9.9 p	±0.1pF, ±0.25pF, ±0.5pF	40	200	0.125±0.013	R
EVS021 CG100[K-W]	CG	COG	10 p	±2%, ±5%	50	200	0.125±0.013	R

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		Rated voltage		erature	Capacitance		Q	HTLT		Soldering
Part number 1	Part number 2	[V]		erature teristics	[F]	Capacitance tolerance	(at 1GHz)	Rated voltage x %	Thickness*3 [mm]	R:Reflow
VS042 CG010∏C-W			CG	COG	1 p	±0.05pF, ±0.1pF, ±0.25pF	(min) 300	200	0.2±0.02	W:Wave R
VS042 CG1R1 C-W		-	CG	COG	1.1 p	±0.05pF, ±0.1pF, ±0.25pF	280	200	0.2±0.02	R
VS042 CG1R2[]C-W		1	CG	COG	1.2 p	±0.05pF, ±0.1pF, ±0.25pF	270	200	0.2±0.02	R
VS042 CG1R3[]C-W			CG	C0G	1.3 p	±0.05pF, ±0.1pF, ±0.25pF	260	200	0.2±0.02	R
VS042 CG1R4[]C-W] [CG	C0G	1.4 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	250	200	0.2±0.02	R
VS042 CG1R5∏C-W		.	CG	COG	1.5 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	240	200	0.2±0.02	R
VS042 CG1R6[]C-W		.	CG	C0G	1.6 p	±0.05pF, ±0.1pF, ±0.25pF	230	200	0.2±0.02	R
VS042 CG1R7[]C-W		-	CG	COG	1.7 p	±0.05pF, ±0.1pF, ±0.25pF	220	200	0.2±0.02	R
TVS042 CG1R8∏C-W TVS042 CG1R9∏C-W		-	CG	C0G C0G	1.8 p 1.9 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF ± 0.05 pF, ± 0.1 pF, ± 0.25 pF	210 200	200 200	0.2±0.02 0.2±0.02	R R
VS042 CG1R9[]C-W		1	CG	COG	1.9 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	190	200	0.2±0.02	R
VS042 CG2R1[]C-W		1	CG	COG	2.1 p	±0.05pF, ±0.1pF, ±0.25pF	185	200	0.2±0.02	R
VS042 CG2R2[]C-W		1	CG	COG	2.2 p	±0.05pF, ±0.1pF, ±0.25pF	180	200	0.2±0.02	R
VS042 CG2R3∏C-W		1	CG	C0G	2.3 p	±0.05pF, ±0.1pF, ±0.25pF	175	200	0.2±0.02	R
VS042 CG2R4[]C-W			CG	C0G	2.4 p	±0.05pF, ±0.1pF, ±0.25pF	170	200	0.2±0.02	R
VS042 CG2R5∏C-W		_	CG	C0G	2.5 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	160	200	0.2±0.02	R
VS042 CG2R6[]C-W		」	CG	COG	2.6 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	155	200	0.2±0.02	R
VS042 CG2R7[]C-W		4	CG	C0G	2.7 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	150	200	0.2±0.02	R
VS042 CG2R8[]C-W		-	CG	COG	2.8 p	±0.05pF, ±0.1pF, ±0.25pF	140	200	0.2±0.02	R
TVS042 CG2R9∏C-W		-{	CG	C0G	2.9 p	±0.05pF, ±0.1pF, ±0.25pF	135 130	200	0.2±0.02	R R
VS042 CG030∏C-W VS042 CG3R1∏C-W		- 	CG	C0G C0G	3 p 3.1 p	±0.05pF, ±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	125	200 200	0.2±0.02 0.2±0.02	R
VS042 CG3R1[]C-W		- 	CG	COG	3.1 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	125	200	0.2±0.02	R
TVS042 CG3R3∏C-W		┥ !	CG	COG	3.3 p	±0.1pF, ±0.25pF	120	200	0.2±0.02	R
TVS042 CG3R4∏C-W		1	CG	COG	3.4 p	±0.1pF, ±0.25pF	120	200	0.2±0.02	R
「VS042 CG3R5∏C-W] [CG	C0G	3.5 p	±0.1pF, ±0.25pF	110	200	0.2±0.02	R
rvs042 cg3R6∏c-w			CG	C0G	3.6 p	±0.1pF, ±0.25pF	110	200	0.2 ± 0.02	R
rvs042 cg3R7∏c-w		_	CG	COG	3.7 p	±0.1pF, ±0.25pF	110	200	0.2 ± 0.02	R
VS042 CG3R8[]C-W		4	CG	C0G	3.8 p	±0.1pF, ±0.25pF	100	200	0.2±0.02	R
VS042 CG3R9[]C-W		-	CG	COG	3.9 p	±0.1pF, ±0.25pF	100	200	0.2±0.02	R
VS042 CG040∏C-W		-	CG	COG	4 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	90	200	0.2±0.02	R
VS042 CG4R1∏C-W VS042 CG4R2∏C-W		-	CG	C0G C0G	4.1 p 4.2 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	90 85	200 200	0.2±0.02 0.2±0.02	R R
VS042 CG4R3[]C-W		 	CG	COG	4.2 p	±0.1pF, ±0.25pF	85	200	0.2±0.02	R
VS042 CG4R4[]C-W		1	CG	COG	4.4 p	±0.1pF, ±0.25pF	85	200	0.2±0.02	R
VS042 CG4R5[]C-W		1	CG	COG	4.5 p	±0.1pF, ±0.25pF	85	200	0.2±0.02	R
VS042 CG4R6∏C-W			CG	C0G	4.6 p	±0.1pF, ±0.25pF	85	200	0.2±0.02	R
TVS042 CG4R7∏C-W		25	CG	C0G	4.7 p	±0.1pF, ±0.25pF	85	200	0.2 ± 0.02	R
VS042 CG4R8[]C-W		」	CG	COG	4.8 p	±0.1pF, ±0.25pF	80	200	0.2±0.02	R
rVS042 CG4R9∏C-W		4	CG	COG	4.9 p	±0.1pF, ±0.25pF	80	200	0.2±0.02	R
TVS042 CG050[]C-W		4	CG	COG	5 p	±0.1pF, ±0.25pF	80	200	0.2±0.02	R
TVS042 CG5R1 ☐ C-W TVS042 CG5R2 ☐ C-W		-	CG	C0G C0G	5.1 p 5.2 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	75 75	200 200	0.2±0.02 0.2±0.02	R R
VS042 CG5R3[]C-W		-	CG	COG	5.2 p	±0.1pF, ±0.25pF, ±0.5pF	75	200	0.2±0.02	R
VS042 CG5R4[]C-W		1	CG	COG	5.4 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.2±0.02	R
VS042 CG5R5[]C-W		1	CG	COG	5.5 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.2±0.02	R
VS042 CG5R6[]C-W		1	CG	COG	5.6 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.2±0.02	R
VS042 CG5R7[]C−W			CG	C0G	5.7 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.2±0.02	R
VS042 CG5R8[]C-W		[CG	C0G	5.8 p	±0.1pF, ±0.25pF, ±0.5pF	70	200	0.2±0.02	R
rVS042 CG5R9∏C−W		<u> </u>	CG	COG	5.9 p	±0.1pF, ±0.25pF, ±0.5pF	65	200	0.2±0.02	R
TVS042 CG060∏C-W		-	CG	COG	6 p	±0.1pF, ±0.25pF, ±0.5pF	65 65	200	0.2±0.02	R
VS042 CG6R1 C-W		-{	CG	C0G	6.1 p	±0.1pF, ±0.25pF, ±0.5pF	65	200	0.2±0.02	R
VS042 CG6R2□C-W VS042 CG6R3□C-W		-{	CG	C0G C0G	6.2 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	65 65	200 200	0.2±0.02 0.2±0.02	R R
VS042 CG6R3∏C-W VS042 CG6R4∏C-W		-	CG	COG	6.3 p 6.4 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	65	200	0.2±0.02 0.2±0.02	R
VS042 CG6R5[]C-W		- 	CG	COG	6.5 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	65	200	0.2±0.02	R
VS042 CG6R6[]C-W		1	CG	COG	6.6 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.2±0.02	R
VS042 CG6R7[]C-W		7 I	CG	COG	6.7 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.2±0.02	R
VS042 CG6R8[]C-W		j l	CG	C0G	6.8 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.2±0.02	R
VS042 CG6R9[]C-W	•] [CG	C0G	6.9 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.2±0.02	R
VS042 CG070∏C-W		_ [CG	C0G	7 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.2±0.02	R
VS042 CG7R1[]C-W		<u> </u>	CG	COG	7.1 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.2±0.02	R
VS042 CG7R2[]C-W		⊣ ∣	CG	COG	7.2 p	±0.1pF, ±0.25pF, ±0.5pF	60	200	0.2±0.02	R
VS042 CG7R3[]C-W		- I	CG	COG	7.3 p	±0.1pF, ±0.25pF, ±0.5pF	55	200	0.2±0.02	R
VS042 CG7R4 C-W		-{	CG	C0G	7.4 p 7.5 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	55 55	200	0.2±0.02	R
VS042 CG/R5∐C-W VS042 CG7R6∐C-W		-{	CG	C0G C0G	7.5 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF ± 0.1 pF, ± 0.25 pF, ± 0.5 pF	55 55	200 200	0.2±0.02 0.2±0.02	R R
VS042 CG7R6[]C-W		-{	CG	COG	7.6 p 7.7 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	55	200	0.2±0.02 0.2±0.02	R
VS042 CG7R7∐C-W VS042 CG7R8∏C-W		-	CG	COG	7.7 p 7.8 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	55	200	0.2±0.02 0.2±0.02	R
VS042 CG7R9[]C-W		- 	CG	COG	7.8 p	±0.1pF, ±0.25pF, ±0.5pF	55	200	0.2±0.02	R
VS042 CG080∏C-W		┥ ト	CG	COG	7.5 p	±0.1pF, ±0.25pF, ±0.5pF	55	200	0.2±0.02	R
VS042 CG8R1[]C-W		┥ !	CG	COG	8.1 p	±0.1pF, ±0.25pF, ±0.5pF	55	200	0.2±0.02	R
VS042 CG8R2[]C-W		1	CG	COG	8.2 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.2±0.02	R
VS042 CG8R3[]C-W]	CG	C0G	8.3 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.2±0.02	R
VS042 CG8R4∏C-W			CG	COG	8.4 p	±0.1pF, ±0.25pF, ±0.5pF	50	200	0.2±0.02	R

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Part number 1	Part number 2	Rated voltage [V]		erature eristics	Capacitance [F]	Capacitance tolerance	Q (at 1GHz) (min)	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
TVS042 CG8R5[]C-W			CG	COG	8.5 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	50	200	0.2 ± 0.02	R
TVS042 CG8R6∏C-W			CG	C0G	8.6 p	$\pm 0.1 pF$, $\pm 0.25 pF$, $\pm 0.5 pF$	50	200	0.2 ± 0.02	R
TVS042 CG8R7[]C-W			CG	COG	8.7 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	50	200	0.2 ± 0.02	R
TVS042 CG8R8[]C-W			CG	COG	8.8 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	50	200	0.2 ± 0.02	R
TVS042 CG8R9[]C-W			CG	COG	8.9 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	50	200	0.2 ± 0.02	R
TVS042 CG090[]C-W			CG	COG	9 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	50	200	0.2 ± 0.02	R
TVS042 CG9R1∏C-W			CG	COG	9.1 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	45	200	0.2 ± 0.02	R
TVS042 CG9R2∏C-W			CG	COG	9.2 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	45	200	0.2 ± 0.02	R
TVS042 CG9R3∏C-W			CG	COG	9.3 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	45	200	0.2 ± 0.02	R
TVS042 CG9R4[]C-W			CG	COG	9.4 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	45	200	0.2 ± 0.02	R
TVS042 CG9R5∏C-W			CG	COG	9.5 p	±0.1pF, ±0.25pF, ±0.5pF	45	200	0.2 ± 0.02	R
TVS042 CG9R6∏C-W		25	CG	COG	9.6 p	±0.1pF, ±0.25pF, ±0.5pF	45	200	0.2 ± 0.02	R
TVS042 CG9R7∏C-W			CG	COG	9.7 p	±0.1pF, ±0.25pF, ±0.5pF	45	200	0.2 ± 0.02	R
TVS042 CG9R8∏C-W			CG	COG	9.8 p	±0.1pF, ±0.25pF, ±0.5pF	45	200	0.2 ± 0.02	R
TVS042 CG9R9∏C-W			CG	COG	9.9 p	±0.1pF, ±0.25pF, ±0.5pF	45	200	0.2 ± 0.02	R
TVS042 CG100[]C-W			CG	COG	10 p	±2%, ±5%	45	200	0.2 ± 0.02	R
TVS042 CG110JC-W			CG	COG	11 p	±5%	40	200	0.2 ± 0.02	R
TVS042 CG120JC-W			CG	COG	12 p	±5%	40	200	0.2 ± 0.02	R
TVS042 CG130JC-W			CG	C0G	13 p	±5%	40	200	0.2 ± 0.02	R
TVS042 CG150JC-W			CG	C0G	15 p	±5%	40	200	0.2±0.02	R
TVS042 CG160JC-W			CG	C0G	16 p	±5%	40	200	0.2±0.02	R
TVS042 CG180JC-W			CG	C0G	18 p	±5%	40	200	0.2±0.02	R
TVS042 CG220JC-W			CG	C0G	22 p	±5%	30	200	0.2±0.02	R

●105TYPE

【Temperature Characteristic CG : CG/C0G(−55~+125°C)】 0.5mm thickness(W)

Temperature onarac				, , 0.0		3(1.)	Q			Soldering
Part number 1	Part number 2	Rated voltage	Tempe		Capacitance	Capacitance tolerance	(at 1GHz)	HTLT	Thickness*3 [mm]	R:Reflow
T die Hamber 1	Ture number 2	[V]	charact	eristics	[F]	oupuoitarioo toiorarioo	(min)	Rated voltage x %	THICKNESS [IIIII]	W:Wave
EVK105 CG0R3BW-F			CG	COG	0.3 p	±0.1pF	300	200	0.5 ± 0.05	R
EVK105 CG0R4BW-F			CG	COG	0.4 p	±0.1pF	300	200	0.5 ± 0.05	R
EVK105 CG0R5BW-F			CG	COG	0.5 p	±0.1pF	300	200	0.5 ± 0.05	R
EVK105 CG0R6BW-F			CG	COG	0.6 p	±0.1pF	300	200	0.5 ± 0.05	R
EVK105 CG0R7BW-F			CG	COG	0.7 p	±0.1pF	300	200	0.5 ± 0.05	R
EVK105 CG0R8BW-F			CG	COG	0.8 p	±0.1pF	300	200	0.5 ± 0.05	R
EVK105 CG0R9BW-F			CG	COG	0.9 p	±0.1pF	300	200	0.5 ± 0.05	R
EVK105 CG010BW-F			CG	COG	1 p	±0.1pF	300	200	0.5 ± 0.05	R
EVK105 CG1R1BW-F			CG	COG	1.1 p	±0.1pF	280	200	0.5 ± 0.05	R
EVK105 CG1R2BW-F			CG	C0G	1.2 p	±0.1pF	270	200	0.5 ± 0.05	R
EVK105 CG1R3BW-F			CG	C0G	1.3 p	±0.1pF	260	200	0.5 ± 0.05	R
EVK105 CG1R5BW-F			CG	COG	1.5 p	±0.1pF	240	200	0.5 ± 0.05	R
EVK105 CG1R6BW-F		16	CG	COG	1.6 p	±0.1pF	230	200	0.5 ± 0.05	R
EVK105 CG1R8BW-F			CG	COG	1.8 p	±0.1pF	210	200	0.5 ± 0.05	R
EVK105 CG020BW-F			CG	COG	2 p	±0.1pF	190	200	0.5 ± 0.05	R
EVK105 CG2R2JW-F			CG	COG	2.2 p	±5%	180	200	0.5 ± 0.05	R
EVK105 CG2R4JW-F			CG	COG	2.4 p	±5%	170	200	0.5 ± 0.05	R
EVK105 CG2R7JW-F			CG	COG	2.7 p	±5%	150	200	0.5 ± 0.05	R
EVK105 CG030JW-F			CG	COG	3 p	±5%	130	200	0.5 ± 0.05	R
EVK105 CG3R3JW-F			CG	C0G	3.3 p	±5%	120	200	0.5 ± 0.05	R
EVK105 CG3R6JW-F			CG	C0G	3.6 p	±5%	110	200	0.5±0.05	R
EVK105 CG3R9JW-F			CG	C0G	3.9 p	±5%	99	200	0.5±0.05	R
EVK105 CG4R3JW-F			CG	COG	4.3 p	±5%	84	200	0.5±0.05	R
EVK105 CG4R7JW-F			CG	COG	4.7 p	±5%	84	200	0.5±0.05	R
EVK105 CG5R1JW-F			CG	COG	5.1 p	±5%	84	200	0.5±0.05	R

[Temperature Characteristic CG : $CG/COG(-55 \sim +125^{\circ}C)$] 0.5mm thickness(W)

Part number 1	Part number 2	Rated voltage	Tempe		Capacitance		Q (at 1GHz)	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Part number 1	Part number 2	[V]	charact	eristics	[F]	Capacitance tolerance		Rated voltage x %	Thickness [mm]	W:Wave
UVK105 CG0R3BW-F			CG	COG	0.3 p	±0.1pF	300	200	0.5 ± 0.05	R
UVK105 CG0R4BW-F			CG	C0G	0.4 p	±0.1pF	300	200	0.5 ± 0.05	R
UVK105 CG0R5BW-F			CG	COG	0.5 p	±0.1pF	300	200	0.5 ± 0.05	R
UVK105 CG0R6BW-F			CG	COG	0.6 p	±0.1pF	300	200	0.5 ± 0.05	R
UVK105 CG0R7BW-F			CG	COG	0.7 p	±0.1pF	300	200	0.5 ± 0.05	R
UVK105 CG0R8BW-F			CG	COG	0.8 p	±0.1pF	300	200	0.5 ± 0.05	R
UVK105 CG0R9BW-F			CG	COG	0.9 p	±0.1pF	300	200	0.5 ± 0.05	R
UVK105 CG010BW-F			CG	COG	1 p	±0.1pF	300	200	0.5 ± 0.05	R
UVK105 CG1R1BW-F			CG	COG	1.1 p	±0.1pF	280	200	0.5 ± 0.05	R
UVK105 CG1R2BW-F			CG	COG	1.2 p	±0.1pF	270	200	0.5 ± 0.05	R
UVK105 CG1R3BW-F			CG	COG	1.3 p	±0.1pF	260	200	0.5 ± 0.05	R
UVK105 CG1R5BW-F			CG	COG	1.5 p	±0.1pF	240	200	0.5 ± 0.05	R
UVK105 CG1R6BW-F		50	CG	COG	1.6 p	±0.1pF	230	200	0.5 ± 0.05	R
UVK105 CG1R8BW-F			CG	COG	1.8 p	±0.1pF	210	200	0.5 ± 0.05	R
UVK105 CG020BW-F			CG	COG	2 p	±0.1pF	190	200	0.5 ± 0.05	R
UVK105 CG2R2JW-F			CG	COG	2.2 p	±5%	180	200	0.5 ± 0.05	R
UVK105 CG2R4JW-F			CG	COG	2.4 p	±5%	170	200	0.5 ± 0.05	R
UVK105 CG2R7JW-F			CG	COG	2.7 p	±5%	150	200	0.5 ± 0.05	R
UVK105 CG030JW-F			CG	COG	3 р	±5%	130	200	0.5 ± 0.05	R
UVK105 CG3R3JW-F			CG	C0G	3.3 p	±5%	120	200	0.5 ± 0.05	R
UVK105 CG3R6JW-F			CG	C0G	3.6 p	±5%	110	200	0.5 ± 0.05	R
UVK105 CG3R9JW-F			CG	COG	3.9 p	±5%	99	200	0.5 ± 0.05	R
UVK105 CG4R3JW-F			CG	COG	4.3 p	±5%	84	200	0.5 ± 0.05	R
UVK105 CG4R7JW-F			CG	COG	4.7 p	±5%	84	200	0.5 ± 0.05	R
UVK105 CG5R1JW-F	·		CG	COG	5.1 p	±5%	84	200	0.5 ± 0.05	R

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Super Low Distortion Multilayer Ceramic Capacitors

■105TYPE

[Temperature Characteristic SD : Standard($-55\sim+125^{\circ}$ C)] 0.5mm thickness(V)

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Fart number 1	Fart number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Triickriess [mm]	W:Wave
UMK105 SD391KV-F				390 p	±10	0.1	200	0.5±0.05	R
UMK105 SD471KV-F		50		470 p	±10	0.1	200	0.5±0.05	R
UMK105 SD561KV-F			-	560 p	±10	0.1	200	0.5±0.05	R
TMK105 SD681KV-F				680 p	±10	0.1	200	0.5±0.05	R
TMK105 SD821KV-F		25		820 p	±10	0.1	200	0.5±0.05	R
TMK105 SD102KV-F		2.5		1000 p	±10	0.1	200	0.5±0.05	R
TMK105 SD122KV-F			Standard Type	1200 p	±10	0.1	200	0.5±0.05	R
EMK105 SD152KV-F			Standard Type	1500 p	±10	0.1	200	0.5±0.05	R
EMK105 SD182KV-F		16		1800 p	±10	0.1	200	0.5±0.05	R
EMK105 SD222KV-F		10		2200 p	±10	0.1	200	0.5±0.05	R
EMK105 SD272KV-F				2700 p	±10	0.1	200	0.5 ± 0.05	R
LMK105 SD332KV-F				3300 p	±10	0.1	200	0.5±0.05	R
LMK105 SD392KV-F		10		3900 p	±10	0.1	200	0.5±0.05	R
LMK105 SD472KV-F				4700 p	±10	0.1	200	0.5 ± 0.05	R

[Temperature Characteristic SD : Standard($-55 \sim +125 ^{\circ}$ C)] 0.3mm thickness(P)

Pa	rt number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
LMK105	SD152KP-F		10 Standard T	Chandrad Tax	1500 p	±10	0.1	200	0.3 ± 0.03	R
JMK105	SD272KP-F			Standard Type	2700 p	±10	0.1	200	0.3 ± 0.03	R

●107TYPE

【Temperature Characteristic SD : Standard(−55~+125°C)】 0.8mm thickness(A)

Tremperature Gharac	CLETISTIC OD . Stariua	iru (JJ - i	123 0/1 0.011	IIII UIICKIICS	5 (A)				
Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Part number 1	Part number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Inickness [mm]	W:Wave
UMK107 SD102KA-T				1000 p	±10	0.1	200	0.8 ± 0.10	R
UMK107 SD122KA-T				1200 p	±10	0.1	200	0.8±0.10	R
UMK107 SD152KA-T				1500 p	±10	0.1	200	0.8 ± 0.10	R
UMK107 SD182KA-T		50		1800 p	±10	0.1	200	0.8 ± 0.10	R
UMK107 SD222KA-T				2200 p	±10	0.1	200	0.8 ± 0.10	R
UMK107 SD272KA-T				2700 p	±10	0.1	200	0.8 ± 0.10	R
UMK107 SD332KA-T				3300 p	±10	0.1	200	0.8 ± 0.10	R
TMK107 SD392KA-T		25		3900 p	±10	0.1	200	0.8±0.10	R
TMK107 SD472KA-T		25	Standard Type	4700 p	±10	0.1	200	0.8±0.10	R
EMK107 SD562KA-T				5600 p	±10	0.1	200	0.8 ± 0.10	R
EMK107 SD682KA-T		16		6800 p	±10	0.1	200	0.8 ± 0.10	R
EMK107 SD822KA-T		10		8200 p	±10	0.1	200	0.8 ± 0.10	R
EMK107 SD103KA-T				0.01 μ	±10	0.1	200	0.8 ± 0.10	R
LMK107 SD123KA-T				0.012 μ	±10	0.1	200	0.8 ± 0.10	R
LMK107 SD153KA-T		10		0.015 μ	±10	0.1	200	0.8 ± 0.10	R
LMK107 SD183KA-T		10		0.018 μ	±10	0.1	200	0.8±0.10	R
LMK107 SD223KA-T				0.022 μ	±10	0.1	200	0.8 ± 0.10	R

■212TYPE

【Temperature Characteristic SD : Standard(−55~+125°C)】 1.25mm thickness(G)

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Fart number 1	Fart number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	THICKINGS [IIIII]	W:Wave
GMK212 SD183KG-T				0.018 μ	±10	0.1	200	1.25±0.10	R
GMK212 SD223KG-T		35		0.022 μ	±10	0.1	200	1.25±0.10	R
GMK212 SD273KG-T			Chandaud Tona	0.027 μ	±10	0.1	200	1.25±0.10	R
LMK212 SD683KG-T			Standard Type	0.068 μ	±10	0.1	200	1.25±0.10	R
LMK212 SD823KG-T		10		0.082 μ	±10	0.1	200	1.25±0.10	R
LMK212 SD104KG-T				0.1 μ	±10	0.1	200	1.25±0.10	R

【Temperature Characteristic SD : Standard(−55~+125°C)】 0.85mm thickness(D)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
UMK212 SD392KD-T				3900 p	±10	0.1	200	0.85±0.10	R
UMK212 SD472KD-T				4700 p	±10	0.1	200	0.85±0.10	R
UMK212 SD562KD-T		50	-	5600 p	±10	0.1	200	0.85±0.10	R
UMK212 SD682KD-T		50		6800 p	±10	0.1	200	0.85±0.10	R
UMK212 SD822KD-T			Standard Type	8200 p	±10	0.1	200	0.85±0.10	R
UMK212 SD103KD-T			Standard Type	0.01 μ	±10	0.1	200	0.85±0.10	R
GMK212 SD123KD-T		35		0.012 μ	±10	0.1	200	0.85±0.10	R
GMK212 SD153KD-T		35		0.015 μ	±10	0.1	200	0.85 ± 0.10	R
EMK212 SD333KD-T		16		0.033 μ	±10	0.1	200	0.85±0.10	R
LMK212 SD473KD-T		10		0.047 μ	±10	0.1	200	0.85±0.10	R

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316TYPE

[Temperature Characteristic SD : Standard $(-55 \sim +125 ^{\circ}\text{C})$] 1.6mm thickness (L)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
TMK316 SD823KL-T		25	Standard Type	0.082 μ	±10	0.1	200	1.6±0.20	R
TMK316 SD104KL-T		25	Standard Type	0.1 μ	±10	0.1	200	1.6±0.20	R

[Temperature Characteristic SD : Standard($-55 \sim +125 ^{\circ}$ C)] 1.15mm thickness(F)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	R:Reflow W:Wave
GMK316 SD333KF-T		35		0.033μ	±10	0.1	200	1.15±0.10	R
GMK316 SD393KF-T		33		0.039μ	±10	0.1	200	1.15±0.10	R
TMK316 SD473KF-T			Standard Type	0.047μ	±10	0.1	200	1.15±0.10	R
TMK316 SD563KF-T		25		0.056μ	±10	0.1	200	1.15±0.10	R
TMK316 SD683KF-T				0.068 μ	±10	0.1	200	1.15±0.10	R

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Low Distortion High Value Multilayer Ceramic Capacitors(CF_LD)

107TYPE

[Temperature Characteristic LD: X5R(-55~+85°C)] 0.8mm thickness(A)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
UMK107BLD224 A-T		50	X5R	0.22 μ	±10, ±20	10	150	0.8+0.20/-0	R
TMK107BLD474∏A-T		25	X5R	0.47 μ	±10, ±20	10	150	0.8+0.20/-0	R
TMK107BLD105[]A-T		25	X5R	1 μ	±10, ±20	10	150	0.8+0.20/-0	R

212TYPE

[Temperature Characteristic LD : $X5R(-55 \sim +85 ^{\circ}C)$] 1.25mm thickness(G)

Part number 1	Part number 2	Rated voltage [V]	Temper characte		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
GMK212 LD105∏G-T		O.F.		X5R	1 μ	±10, ±20	10	150	1.25±0.10	R
GMK212BLD225[]G-T		35		X5R	2.2 μ	±10, ±20	10	150	1.25+0.20/-0	R

316TYPE

【Temperature Characteristic LD : X5R(−55~+85°C)】 1.6mm thickness(L)

Part number 1	Part number 2	Rated voltage [V]	Tempe charact	erature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
UMK316 LD105□L-T		50		X5R	1 μ	±10, ±20	10	150	1.6±0.20	R
GMK316BLD475[]L-T		35		X5R	4.7 μ	±10, ±20	10	150	1.6±0.30	R
TMK316BLD106□L-T		25		X5R	10 μ	±10, ±20	10	150	1.6±0.30	R

325TYPE

[Temperature Characteristic LD : $X5R(-55 \sim +85^{\circ}C)$] 1.9mm thickness(N)

Part number 1	Part number 2	Rated voltage [V]	Tempe charact	erature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
UMK325 LD105∏N-T		50		X5R	1 μ	±10, ±20	10	200	1.9±0.20	R

[Temperature Characteristic LD : $X5R(-55 \sim +85 ^{\circ}C)$] 2.5mm thickness(M)

Part number 1	Part number 2	Rated voltage [V]	 erature teristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
UMK325 LD475∏M-P		50	X5R	4.7 μ	±10, ±20	10	200	2.5±0.20	R

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Medium-High Voltage Multilayer Ceramic Capacitors

105TYPE

[Temperature Characteristic B7 : X7R($-55\sim+125^{\circ}$ C)] 0.5mm thickness(V)

Part number 1	Part number 2	Rated voltage		rature	Capacitance	Capacitance tolerance	tan δ	HTLT	Thickness*3 [mm]	Soldering R:Reflow
T di c Hamboi T	T di c Hamboi 2	[V]	charact	eristics	[F]	[%]	[%]	Rated voltage x %	THIORIESS [HIII]	W:Wave
HMK105 B7221 ŪV-F				X7R	220 p	±10, ±20	2.5	200	0.5 ± 0.05	R
HMK105 B7331∏V-F				X7R	330 p	±10, ±20	2.5	200	0.5 ± 0.05	R
HMK105 B7471∏V-F				X7R	470 p	±10, ±20	2.5	200	0.5 ± 0.05	R
HMK105 B7681∏V-F				X7R	680 p	±10, ±20	2.5	200	0.5±0.05	R
HMK105 B7102□V-F		100		X7R	1000 p	±10, ±20	2.5	200	0.5 ± 0.05	R
HMK105 B7152□V-F				X7R	1500 p	±10, ±20	2.5	200	0.5 ± 0.05	R
HMK105 B7222□V-F				X7R	2200 p	±10, ±20	2.5	200	0.5 ± 0.05	R
HMK105 B7332□V-F				X7R	3300 p	±10, ±20	2.5	200	0.5 ± 0.05	R
HMK105 B7472∏V-F				X7R	4700 p	±10, ±20	2.5	200	0.5 ± 0.05	R

[Temperature Characteristic CG : CG/C0G($-55\sim+125^{\circ}$ C)] 0.5mm thickness(V)

Dont words on 1	Dont words on 0	Rated voltage	Tempe	rature	Capacitance	0	Q (-+ 1MII-)	HTLT	*3 5 3	Soldering
Part number 1	Part number 2	[V]	charact	eristics	[F]	Capacitance tolerance	(at 1MHz) min	Rated voltage x %	Thickness*3 [mm]	R:Reflow W:Wave
HMK105 CG080DV-F			CG	COG	8 p	±0.5pF	560	200	0.5 ± 0.05	R
HMK105 CG090DV-F			CG	COG	9 p	±0.5pF	580	200	0.5 ± 0.05	R
HMK105 CG100DV-F			CG	COG	10 p	±0.5pF	600	200	0.5 ± 0.05	R
HMK105 CG120JV-F			CG	COG	12 p	±5%	640	200	0.5 ± 0.05	R
HMK105 CG150JV-F			CG	COG	15 p	±5%	700	200	0.5±0.05	R
HMK105 CG180JV-F			CG	COG	18 p	±5%	760	200	0.5 ± 0.05	R
HMK105 CG220JV-F			CG	COG	22 p	±5%	840	200	0.5 ± 0.05	R
HMK105 CG240JV-F		100	CG	COG	24 p	±5%	880	200	0.5 ± 0.05	R
HMK105 CG270JV-F		100	CG	COG	27 p	±5%	940	200	0.5 ± 0.05	R
HMK105 CG330JV-F			CG	COG	33 p	±5%	1000	200	0.5 ± 0.05	R
HMK105 CG390JV-F			CG	COG	39 p	±5%	1000	200	0.5 ± 0.05	R
HMK105 CG470JV-F			CG	COG	47 p	±5%	1000	200	0.5 ± 0.05	R
HMK105 CG560JV-F			CG	COG	56 p	±5%	1000	200	0.5 ± 0.05	R
HMK105 CG680JV-F			CG	COG	68 p	±5%	1000	200	0.5 ± 0.05	R
HMK105 CG820JV-F]	CG	COG	82 p	±5%	1000	200	0.5 ± 0.05	R
HMK105 CG101JV-F			CG	COG	100 p	±5%	1000	200	0.5±0.05	R

●107TYPE

[Temperature Characteristic BJ : $B(-25 \sim +85^{\circ}C)/X5R(-55 \sim +85^{\circ}C)$] 0.8mm thickness(A)

Part number 1	Part number 2	Rated voltage [V]		erature	Capacitance	Capacitance tolerance	tan δ	HTLT	Thickness*3 [mm]	Soldering R:Reflow
		[V]	charact	teristics	[F]	[%]	[%]	Rated voltage x %	THIS WAS ELLING	W:Wave
HMK107 BJ102∏A-T			В	X5R*1	1000 p	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ152[]A-T			В	X5R*1	1500 p	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ222□A-T			В	X5R*1	2200 p	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ332∏A-T			В	X5R*1	3300 p	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ472∏A-T			В	X5R*1	4700 p	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ682∏A-T			В	X5R*1	6800 p	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ103∏A-T		100	В	X5R*1	0.01 μ	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ153∏A-T			В	X5R*1	0.015 μ	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ223∏A-T			В	X5R*1	0.022 μ	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ333∏A-T			В	X5R*1	0.033 μ	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ473∏A-T			В	X5R*1	0.047 μ	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ104[]A-T			В	X5R*1	0.1 μ	±10, ±20	3.5	200	0.8±0.10	R
HMK107 BJ224∏A-TE			В	X5R*1	0.22 μ	±10, ±20	3.5	150	0.8±0.10	R

[Temperature Characteristic C7 : X7S($-55\sim+125^{\circ}$ C)] 0.8mm thickness(A)

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Part number 1	Part number 2	Rated voltage [V]		erature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
HMK107 C7224□A-TE		100		X7S	0.22 μ	$\pm 10, \pm 20$	3.5	150	0.8 ± 0.10	. R

[Temperature Characteristic B7 : $X7R(-55 \sim +125 ^{\circ}C)$] 0.8mm thickness(A)

Tremperature Oriarac	Soldering Soldering												
Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow				
Fart number 1	Part number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Trickness [mm]	W:Wave				
HMK107 B7102[]A-T			X7R	1000 p	±10, ±20	3.5	200	0.8±0.10	R				
HMK107 B7152[]A-T			X7R	1500 p	±10, ±20	3.5	200	0.8±0.10	R				
HMK107 B7222∏A-T			X7R	2200 p	±10, ±20	3.5	200	0.8±0.10	R				
HMK107 B7332∏A-T			X7R	3300 p	±10, ±20	3.5	200	0.8±0.10	R				
HMK107 B7472∏A-T			X7R	4700 p	±10, ±20	3.5	200	0.8±0.10	R				
HMK107 B7682∏A-T		100	X7R	6800 p	±10, ±20	3.5	200	0.8±0.10	R				
HMK107 B7103∏A-T		100	X7R	0.01 μ	±10, ±20	3.5	200	0.8±0.10	R				
HMK107 B7153∏A-T			X7R	0.015 μ	±10, ±20	3.5	200	0.8±0.10	R				
HMK107 B7223∏A-T			X7R	0.022 μ	±10, ±20	3.5	200	0.8±0.10	R				
HMK107 B7333∏A-T			X7R	0.033 μ	±10, ±20	3.5	200	0.8±0.10	R				
HMK107 B7473[]A-T			X7R	0.047 μ	±10, ±20	3.5	200	0.8±0.10	R				
HMK107 B7104□A-T			X7R	0.1 μ	±10, ±20	3.5	200	0.8±0.10	R				

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

MULTILAYER CERAMIC CAPACITORS

[Temperature Characteristic SD : Standard $(-55 \sim +125^{\circ}C)$] 0.8mm thickness (A)

Part number 1	Part number 2	Rated voltage		Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Fart number 1	Part Humber 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Thickness [mm]	W:Wave
HMK107 SD101KA-T				100 p	±10	0.1	200	0.8±0.10	R
HMK107 SD121KA-T				120 p	±10	0.1	200	0.8±0.10	R
HMK107 SD151KA-T				150 p	±10	0.1	200	0.8±0.10	R
HMK107 SD181KA-T				180 p	±10	0.1	200	0.8±0.10	R
HMK107 SD221KA-T				220 p	±10	0.1	200	0.8±0.10	R
HMK107 SD271KA-T				270 p	±10	0.1	200	0.8±0.10	R
HMK107 SD331KA-T		100	Standard Type	330 p	±10	0.1	200	0.8±0.10	R
HMK107 SD391KA-T				390 p	±10	0.1	200	0.8±0.10	R
HMK107 SD471KA-T				470 p	±10	0.1	200	0.8±0.10	R
HMK107 SD561KA-T				560 p	±10	0.1	200	0.8±0.10	R
HMK107 SD681KA-T				680 p	±10	0.1	200	0.8±0.10	R
HMK107 SD821KA-T				820 p	±10	0.1	200	0.8±0.10	R
HMK107 SD102KA-T				1000 p	±10	0.1	200	0.8±0.10	R

212TYPE

[Temperature Characteristic BJ : $B(-25 \sim +85^{\circ}C)/X5R(-55 \sim +85^{\circ}C)$] 1.25mm thickness(G)

Part number 1	Part number 2	Rated voltage	Tempe	erature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
i ai c ilumber i	Tart Humber 2	[V]	charact	eristics	[F]	[%]	[%]	Rated voltage x %	Thickness [mm]	W:Wave
HMK212 BJ103∏G-T			В	X5R*1	0.01 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 BJ153∏G-T			В	X5R*1	0.015 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 BJ223∏G-T			В	X5R*1	0.022 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 BJ333∏G-T			В	X5R*1	0.033 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 BJ473∏G-T		100	В	X5R*1	0.047 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 BJ683∏G-T		100	В	X5R*1	0.068 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 BJ104∏G-T			В	X5R*1	0.1 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 BJ224∏G-T			В	X5R*1	0.22 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 BJ474∏G-TE]	В	X5R*1	0.47 μ	±10, ±20	3.5	150	1.25±0.10	R
HMK212BBJ105∏G-TE]	В	X5R*1	1 μ	±10, ±20	3.5	150	1.25+0.20/-0	R
QMK212 BJ472 G-T			В	X5R*1	4700 p	±10, ±20	2.5	150	1.25±0.10	R
QMK212 BJ682[]G-T			В	X5R*1	6800 p	±10, ±20	2.5	150	1.25±0.10	R
QMK212 BJ103[]G-T		250	В	X5R*1	0.01 μ	±10, ±20	2.5	150	1.25±0.10	R
QMK212 BJ153[]G-T] [В	X5R*1	0.015 μ	±10, ±20	2.5	150	1.25±0.10	R
QMK212 BJ223[]G-T			В	X5R*1	0.022 μ	±10, ±20	2.5	150	1.25±0.10	R

[Temperature Characteristic BJ : $B(-25 \sim +85^{\circ}C)/X5R(-55 \sim +85^{\circ}C)$] 0.85mm thickness(D)

Part number 1	Part number 2	Rated voltage [V]		erature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
QMK212 BJ102[]D-T			В	X5R*1	1000 p	±10, ±20	2.5	150	0.85±0.10	R
QMK212 BJ152[]D-T		250	В	X5R*1	1500 p	±10, ±20	2.5	150	0.85±0.10	R
QMK212 BJ222∏D-T		230	В	X5R*1	2200 p	±10, ±20	2.5	150	0.85±0.10	R
QMK212 BJ332∏D-T			В	X5R*1	3300 р	±10, ±20	2.5	150	0.85±0.10	R

[Temperature Characteristic C7 : X7S ($-55 \sim +125 ^{\circ}$ C)] 1.25mm thickness(G)

Part number 1	Part number 2	Rated voltage [V]	Temper characte		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
HMK212 C7474∏G-TE		100		X7S	0.47 μ	±10, ±20	3.5	150	1.25±0.10	R
HMK212BC7105[]G-TE		100		X7S	1 μ	±10, ±20	3.5	150	1.25+0.20/-0	R

[Temperature Characteristic B7 : $X7R(-55\sim+125^{\circ}C)$] 1.25mm thickness(G)

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	tan δ	HTLT	*3 - 3	Soldering R:Reflow
Part number I	Part number 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Thickness*3 [mm]	W:Wave
HMK212 B7103[]G-T			X7R	0.01 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 B7153[]G-T			X7R	0.015 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 B7223[]G-T			X7R	0.022 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 B7333∏G-T		100	X7R	0.033 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 B7473[]G-T		100	X7R	0.047 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 B7683∏G-T			X7R	0.068 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 B7104[]G-T			X7R	0.1 μ	±10, ±20	3.5	200	1.25±0.10	R
HMK212 B7224∏G-T			X7R	0.22 μ	±10, ±20	3.5	200	1.25±0.10	R
QMK212 B7472 G-T			X7R	4700 p	±10, ±20	2.5	150	1.25±0.10	R
QMK212 B7682 G-T			X7R	6800 p	±10, ±20	2.5	150	1.25±0.10	R
QMK212 B7103[]G-T		250	X7R	0.01 μ	±10, ±20	2.5	150	1.25±0.10	R
QMK212 B7153[]G-T			X7R	0.015 μ	±10, ±20	2.5	150	1.25±0.10	R
QMK212 B7223[]G-T			X7R	0.022 μ	±10, ±20	2.5	150	1.25±0.10	R

[Temperature Characteristic B7 : $X7R(-55 \sim +125 ^{\circ}C)$] 0.85mm thickness(D)

Part number 1	Part number 2	Rated voltage [V]	Temper characte		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
QMK212 B7102[]D-T				X7R	1000 p	±10, ±20	2.5	150	0.85 ± 0.10	R
QMK212 B7152□D-T		250		X7R	1500 p	±10, ±20	2.5	150	0.85 ± 0.10	R
QMK212 B7222 D-T		230		X7R	2200 p	±10, ±20	2.5	150	0.85±0.10	R
QMK212 B7332[]D-T				X7R	3300 р	±10, ±20	2.5	150	0.85±0.10	R

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[Temperature Characteristic SD : Standard ($-55 \sim +125 ^{\circ}$ C)] 0.85mm thickness(D)

		Rated voltage	Temperature	Capacitance	Capacitance tolerance	tan δ	HTLT	42	Soldering
Part number 1	Part number 2	[V]	characteristics	[F]	[%]	Fo/ 1	Rated voltage x %	Thickness*3 [mm]	R:Reflow W:Wave
HMK212 SD222KD-T		100		2200 p	±10	0.1	200	0.85 ± 0.10	R
HMK212 SD472KD-T		100		4700 p	±10	0.1	200	0.85 ± 0.10	R
QMK212 SD101KD-T				100 p	±10	0.1	150	0.85 ± 0.10	R
QMK212 SD121KD-T			Standard Type	120 p	±10	0.1	150	0.85 ± 0.10	R
QMK212 SD151KD-T				150 p	±10	0.1	150	0.85 ± 0.10	R
QMK212 SD181KD-T				180 p	±10	0.1	150	0.85 ± 0.10	R
QMK212 SD221KD-T				220 p	±10	0.1	150	0.85 ± 0.10	R
QMK212 SD331KD-T		250	Standard Type	330 p	±10	0.1	150	0.85 ± 0.10	R
QMK212 SD391KD-T		230		390 p	±10	0.1	150	0.85 ± 0.10	R
QMK212 SD471KD-T				470 p	±10	0.1	150	0.85 ± 0.10	R
QMK212 SD561KD-T				560 p	±10	0.1	150	0.85 ± 0.10	R
QMK212 SD681KD-T				680 p	±10	0.1	150	0.85 ± 0.10	R
QMK212 SD821KD-T			_	820 p	±10	0.1	150	0.85 ± 0.10	R
QMK212 SD102KD-T				1000 p	±10	0.1	150	0.85 ± 0.10	R

[Temperature Characteristic SD : Standard $(-55 \sim +125 ^{\circ}\text{C})$] 1.25mm thickness (G)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave	
HMK212 SD392KG-T		100	Standard Type	3900 р	±10	0.1	200	1.25±0.10	R	

316TYPE

[Temperature Characteristic BJ : $B(-25 \sim +85^{\circ}C)/X5R(-55 \sim +85^{\circ}C)$] 1.6mm thickness(L)

Part number 1	Part number 2	Rated voltage		rature	Capacitance	Capacitance tolerance	tan δ	HTLT	Thickness*3 [mm]	Soldering R:Reflow
		[V]	charact	eristics	[F]	[%]	[%]	Rated voltage x %		W:Wave
HMK316 BJ473[]L-T			В	X5R*1	0.047 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 BJ683[]L-T			В	X5R*1	0.068 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 BJ104□L-T			В	X5R*1	0.1 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 BJ154[]L-T			В	X5R*1	0.15 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 BJ224[]L-T		100	В	X5R*1	0.22 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 BJ334[]L-T			В	X5R*1	0.33 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 BJ474[]L-T			В	X5R*1	0.47 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 BJ105[]L-T			В	X5R*1	1 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316ABJ225□L-TE			В	X5R*1	2.2 μ	±10, ±20	3.5	150	1.6±0.20	R
QMK316 BJ333[]L-T			В	X5R*1	0.033 μ	±10, ±20	2.5	150	1.6±0.20	R
QMK316 BJ473[L-T		250	В	X5R*1	0.047 μ	±10, ±20	2.5	150	1.6±0.20	R
QMK316 BJ683[L-T		230	В	X5R*1	0.068 μ	±10, ±20	2.5	150	1.6±0.20	R
QMK316 BJ104[]L-T			В	X5R*1	0.1 μ	±10, ±20	2.5	150	1.6±0.20	R
SMK316 BJ153□L-T		630	В	X5R*1	0.015 μ	±10, ±20	2.5	120	1.6±0.20	R
SMK316 BJ223□L-T		030	В	X5R*1	0.022 μ	±10, ±20	2.5	120	1.6±0.20	R

$\begin{tabular}{l} \textbf{[} Temperature Characteristic BJ: B(-25 \sim +85 ^{\circ}C)/X5R(-55 \sim +85 ^{\circ}C) \end{tabular} \begin{tabular}{l} 1.15mm thickness(F) \end{tabular} \label{tabular}$

Part number 1	Part number 2	Rated voltage	Tempe	erature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Fart number 1	Fart number 2	[V]	charact	teristics	[F]	[%]	[%]	Rated voltage x %	Inickness [mm]	W:Wave
SMK316 BJ102∏F-T			В	X5R*1	1000 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 BJ152∏F-T			В	X5R*1	1500 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 BJ222∏F-T			В	X5R*1	2200 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 BJ332∏F-T		630	В	X5R*1	3300 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 BJ472∏F-T			В	X5R*1	4700 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 BJ682∏F-T			В	X5R*1	6800 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 BJ103∏F-T			В	X5R*1	0.01 μ	±10, ±20	2.5	120	1.15±0.10	R

[Temperature Characteristic C7 : X7S($-55 \sim +125 ^{\circ}$ C)] 1.6mm thickness(L)

Part number 1	Part number 2	Rated voltage [V]	Tempe charact		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
HMK316AC7225□L-TE		100		X7S	2.2 μ	±10, ±20	3.5	150	1.6±0.20	R

[Temperature Characteristic B7 : X7R($-55 \sim +125 ^{\circ} C$)] 1.6mm thickness(L)

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
T di t Humber 1	T art Humber 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	inickness [mm]	W:Wave
HMK316 B7473[]L-T			X7R	0.047 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 B7683[]L-T			X7R	0.068 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 B7104[]L-T			X7R	0.1 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 B7154[]L-T		100	X7R	0.15 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 B7224[]L-T		100	X7R	0.22 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 B7334[]L-T			X7R	0.33 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 B7474∏L-T			X7R	0.47 μ	±10, ±20	3.5	200	1.6±0.20	R
HMK316 B7105[]L-T			X7R	1 μ	±10, ±20	3.5	200	1.6±0.20	R
QMK316 B7333∏L-T			X7R	0.033 μ	±10, ±20	2.5	150	1.6±0.20	R
QMK316 B7473□L-T		250	X7R	0.047 μ	±10, ±20	2.5	150	1.6±0.20	R
QMK316 B7683□L-T		230	X7R	0.068 μ	±10, ±20	2.5	150	1.6±0.20	R
QMK316 B7104 L-T			X7R	0.1 μ	±10, ±20	2.5	150	1.6±0.20	R
SMK316 B7153[]L-T			X7R	0.015 μ	±10, ±20	2.5	120	1.6±0.20	R
SMK316 B7223[]L-T		630	X7R	0.022 μ	±10, ±20	2.5	120	1.6±0.20	R
SMK316AB7333[L-T		030	X7R	0.033 μ	±10, ±20	2.5	120	1.6±0.20	R
SMK316AB7473[]L-T			X7R	0.047 μ	±10, ±20	2.5	120	1.6±0.20	R

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[Temperature Characteristic B7 : $X7R(-55 \sim +125^{\circ}C)$] 1.15mm thickness(F)

D : 1 1	D	Rated voltage	Tempe	rature	Capacitance	Capacitance tolerance	tan δ	HTLT	*3 = 3	Soldering
Part number 1	Part number 2	[V]	charact	eristics	[F]	[%]	[%]	Rated voltage x %	Thickness*3 [mm]	R:Reflow W:Wave
SMK316 B7102[F-T				X7R	1000 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 B7152∏F-T				X7R	1500 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 B7222[F-T				X7R	2200 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 B7332∏F-T		630		X7R	3300 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 B7472[F-T				X7R	4700 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 B7682[F-T				X7R	6800 p	±10, ±20	2.5	120	1.15±0.10	R
SMK316 B7103[F-T				X7R	0.01 μ	±10, ±20	2.5	120	1.15±0.10	R

[Temperature Characteristic SD : Standard $(-55 \sim +125 ^{\circ}\text{C})$] 1.6mm thickness (L)

Part	number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
HMK316 SE	D223KL-T		100	Standard Type	0.022 μ	±10	0.1	200	1.6±0.20	R
QMK316 SE	D103KL-T		250	Standard Type	0.01 μ	±10	0.1	150	1.6±0.20	R

■325TYPE

[Temperature Characteristic BJ : $B(-25 \sim +85^{\circ}C)/X5R(-55 \sim +85^{\circ}C)$] 2.5mm thickness(M)

Part number 1	Part number 2	Rated voltage [V]		erature teristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
HMK325 BJ225∏M-P		100	В	X5R*1	2.2 μ	±10, ±20	3.5	200	2.5±0.20	R
HMK325 BJ475∏M-PE		100	В	X5R*1	4.7 μ	±10, ±20	3.5	150	2.5±0.20	R

[Temperature Characteristic BJ : $B(-25 \sim +85^{\circ}C)/X5R(-55 \sim +85^{\circ}C)$] 1.9mm thickness(N)

B		Rated voltage	Tempe	erature	Capacitance	Capacitance tolerance	tan δ	HTLT	*3 = 3	Soldering
Part number 1	Part number 2	[V]	charact	teristics	[F]	[%]	[%]	Rated voltage x %	Thickness*3 [mm]	R:Reflow W:Wave
HMK325 BJ154□N-T			В	X5R*1	0.15 μ	±10, ±20	3.5	200	1.9±0.20	R
HMK325 BJ224□N-T			В	X5R*1	0.22 μ	±10, ±20	3.5	200	1.9±0.20	R
HMK325 BJ334∏N-T			В	X5R*1	0.33 μ	±10, ±20	3.5	200	1.9±0.20	R
HMK325 BJ474□N-T		100	В	X5R*1	0.47 μ	±10, ±20	3.5	200	1.9±0.20	R
HMK325 BJ684∏N-T			В	X5R*1	0.68 μ	±10, ±20	3.5	200	1.9±0.20	R
HMK325 BJ105∏N-T			В	X5R*1	1 μ	±10, ±20	3.5	200	1.9±0.20	R
HMK325 BJ475□N-TE			В	X5R*1	4.7 μ	±10, ±20	3.5	150	1.9±0.20	R
QMK325 BJ473[N-T			В	X5R*1	0.047 μ	±10, ±20	2.5	150	1.9±0.20	R
QMK325 BJ104[]N-T		250	В	X5R*1	0.1 μ	±10, ±20	2.5	150	1.9±0.20	R
QMK325 BJ154[]N-T		250	В	X5R*1	0.15 μ	±10, ±20	2.5	150	1.9±0.20	R
QMK325 BJ224[]N-T			В	X5R*1	0.22 μ	±10, ±20	2.5	150	1.9±0.20	R
SMK325 BJ223∏N-T			В	X5R*1	0.022 μ	±10, ±20	2.5	120	1.9±0.20	R
SMK325 BJ333∏N-T		630	В	X5R*1	0.033 μ	±10, ±20	2.5	120	1.9±0.20	R
SMK325 BJ473[]N-T			В	X5R*1	0.047 μ	±10, ±20	2.5	120	1.9±0.20	R

$\begin{tabular}{l} \textbf{[} Temperature Characteristic BJ : B($-25$$$\sim$+85$$°C)/X5R($-55$$\sim$+85$$°C) \begin{tabular}{l} 1.15mm thickness(F) \end{tabular} \label{table_eq:energy_eq} \end{tabular}$

Part number 1	Part number 2	Rated voltage [V]	Tempe charact	erature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave	
HMK325 BJ104∏F-T	•	100	В	X5R*1	0.1 μ	±10, ±20	3.5	200	1.15±0.10	R	

[Temperature Characteristic B7 : $X7R(-55 \sim +125^{\circ}C)$] 2.5mm thickness(M)

Part number 1	Part number 2	Rated voltage [V]	Temperatu characterist		Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
HMK325 B7225[]M-P		100	X	7R 2.2 μ	±10, ±20	3.5	200	2.5±0.20	R

[Temperature Characteristic B7 : X7R($-55\sim+125^{\circ}$ C)] 1.9mm thickness(N)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
HMK325 B7154□N-T			X7R	0.15 μ	±10, ±20	3.5	200	1.9±0.20	R R
HMK325 B7224[]N-T			X7R	0.22 μ	±10, ±20	3.5	200	1.9±0.20	R
HMK325 B7334[]N-T		100	X7R	0.33 μ	±10, ±20	3.5	200	1.9±0.20	R
HMK325 B7474[]N-T		100	X7R	0.47 μ	±10, ±20	3.5	200	1.9±0.20	R
HMK325 B7684[]N-T]	X7R	0.68 μ	±10, ±20	3.5	200	1.9±0.20	R
HMK325 B7105[]N-T			X7R	1 μ	±10, ±20	3.5	200	1.9±0.20	R
QMK325 B7473[]N-T			X7R	0.047 μ	±10, ±20	2.5	150	1.9±0.20	R
QMK325 B7104[]N-T		250	X7R	0.1 μ	±10, ±20	2.5	150	1.9±0.20	R
QMK325 B7154[]N-T		230	X7R	0.15 μ	±10, ±20	2.5	150	1.9±0.20	R
QMK325 B7224[N-T			X7R	0.22 μ	±10, ±20	2.5	150	1.9±0.20	R
SMK325 B7223∏N-T			X7R	0.022 μ	±10, ±20	2.5	120	1.9±0.20	R
SMK325 B7333∏N-T		630	X7R	0.033 μ	±10, ±20	2.5	120	1.9±0.20	R
SMK325 B7473∏N-T			X7R	0.047 μ	±10, ±20	2.5	120	1.9±0.20	R

【Temperature Characteristic C7: X7S(−55~+125°C)】 2.5mm thickness(M)

L Tomporacaro onarac	700110010 07 . 7070 (00 1120	O/1 L.	OIIIIII CIII	101(11000 (111)					
Part number 1	Part number 2	Rated voltage [V]	Tempe charact		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
HMK325 C7475∏M-PE		100		X7S	4.7 μ	±10, ±20	3.5	150	2.5±0.20	R

[Temperature Characteristic C7 : X7S($-55\sim+125^{\circ}$ C)] 1.9mm thickness(N)

Part number 1	Part number 2	Rated voltage [V]	Temperatu characterist		Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
HMK325 C7475∏N-TE		100	Х	7S 4.7 μ	±10, ±20	3.5	150	1.9±0.20	R

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MULTILAYER CERAMIC CAPACITORS

[Temperature Characteristic B7 : X7R($-55\sim+125^{\circ}$ C)] 1.15mm thickness(F)

Part number 1	Part number 2	Rated voltage [V]		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
HMK325 B7104∏F-T		100	X7R	0.1 μ	±10, ±20	3.5	200	1.15±0.10	R

432TYPE

[Temperature Characteristic BJ : $B(-25\sim+85^{\circ}C)/X5R(-55\sim+85^{\circ}C)$] 2.5mm thickness(M)

	Part number 1	Part number 2	Rated voltage	Tempe	erature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	R:Reflow
	Part number 1	Part number 2	[V]	charact	eristics	[F]	[%]	[%]	Rated voltage x %	Thickness [mm]	W:Wave
Н	IMK432 BJ474[]M-T			В	X5R*1	0.47 μ	±10, ±20	3.5	200	2.5±0.20	R
Н	IMK432 BJ105[]M−T		100	В	X5R*1	1 μ	±10, ±20	3.5	200	2.5±0.20	R
Н	IMK432 BJ155[]M−T		100	В	X5R*1	1.5 μ	±10, ±20	3.5	200	2.5±0.20	R
Н	IMK432 BJ225[]M−T			В	X5R*1	2.2 μ	±10, ±20	3.5	200	2.5±0.20	R
G	MK432 BJ104∏M-T			В	X5R*1	0.1 μ	±10, ±20	2.5	150	2.5±0.20	R
G	MK432 BJ224∏M-T		250	В	X5R*1	0.22 μ	±10, ±20	2.5	150	2.5±0.20	R
G	MK432 BJ334∏M-T		230	В	X5R*1	0.33 μ	±10, ±20	2.5	150	2.5±0.20	R
G	MK432 BJ474∏M-T			В	X5R*1	0.47 μ	±10, ±20	2.5	150	2.5±0.20	R
S	MK432 BJ473∏M-T			В	X5R*1	0.047 μ	±10, ±20	2.5	120	2.5±0.20	R
S	MK432 BJ683∏M-T		630	В	X5R*1	0.068 μ	±10, ±20	2.5	120	2.5±0.20	R
S	MK432 BJ104[M-T			В	X5R*1	0.1 μ	±10, ±20	2.5	120	2.5±0.20	R

[Temperature Characteristic B7 : X7R($-55\sim+125^{\circ}$ C)] 2.5mm thickness(M)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance	tan δ [%]	HTLT	Thickness*3 [mm]	Soldering R:Reflow
		[4]	Criaracteristics	0.1	[70]	[70]	Rated voltage x %		W:Wave
HMK432 B7474[]M-T			X7R	0.47 μ	±10, ±20	3.5	200	2.5 ± 0.20	R
HMK432 B7105[]M-T		100	X7R	1 μ	±10, ±20	3.5	200	2.5 ± 0.20	R
HMK432 B7155∏M-T		100	X7R	1.5 μ	±10, ±20	3.5	200	2.5 ± 0.20	R
HMK432 B7225∏M-T			X7R	2.2 μ	±10, ±20	3.5	200	2.5 ± 0.20	R
QMK432 B7104[]M-T			X7R	0.1 μ	±10, ±20	2.5	150	2.5 ± 0.20	R
QMK432 B7224□M-T		250	X7R	0.22 μ	±10, ±20	2.5	150	2.5 ± 0.20	R
QMK432 B7334∏M-T		230	X7R	0.33 μ	±10, ±20	2.5	150	2.5 ± 0.20	R
QMK432 B7474□M-T			X7R	0.47 μ	±10, ±20	2.5	150	2.5 ± 0.20	R
SMK432 B7473 M-T			X7R	0.047 μ	±10, ±20	2.5	120	2.5 ± 0.20	R
SMK432 B7683[]M-T		630	X7R	0.068 μ	±10, ±20	2.5	120	2.5±0.20	R
SMK432 B7104[]M-T			X7R	0.1 μ	±10, ±20	2.5	120	2.5±0.20	R

[Temperature Characteristic B7 : $X7R(-55 \sim +125^{\circ}C)$] 2.0mm thickness(Y)

•										
Part number 1	Part number 2	Rated voltage [V]	Temperat characteri		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
XMK432 B7472KY-TE		2000		X7R	4700 p	±10	2.5	110	2.0+0/-0.30	R

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LW Reversal Decoupling Capacitors (LWDCTM)

■ 105TYPI

[Temperature Characteristic BJ : $X5R(-55 \sim +85^{\circ}C)$] 0.3mm thickness(P)

Don't words on 1	Part number 2	Rated voltage	Temperat	ure	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	*3 r n	Soldering
Part number 1	Part number 2	[V]	characteris	stics	[F]	[%]	[%]	Rated voltage x %	Thickness*3 [mm]	R:Reflow W:Wave
TWK105 BJ104MP-F		25		X5R	0.1 μ	±20	5	150	0.3 ± 0.05	R
EWK105 BJ224MP-F		16		X5R	0.22 μ	±20	10	150	0.3 ± 0.05	R
LWK105 BJ474MP-F		10		X5R	0.47 μ	±20	10	150	0.3 ± 0.05	R
JWK105 BJ104MP-F			×	(5R*1	0.1 μ	±20	5	150	0.3 ± 0.05	R
JWK105 BJ474MP-F		6.3	Х	(5R*1	0.47 μ	±20	10	150	0.3 ± 0.05	R
JWK105 BJ105MP-F		0.3		X5R	1 μ	±20	10	150	0.3 ± 0.05	R
JWK105 BJ225MP-F				X5R	2.2 μ	±20	10	150	0.3 ± 0.05	R

[Temperature Characteristic C6 : X6S ($-55 \sim +105 ^{\circ}$ C), C7 : X7S ($-55 \sim +125 ^{\circ}$ C)] 0.3mm thickness (P)

Part number 1	Part number 2	Rated voltage	Tempera		Capacitance	Capacitance tolerance	tan δ	HTLT	Thickness*3 [mm]	Soldering R:Reflow
		[V]	characte	ristics	[F]	[%]	[%]	Rated voltage x %		W:Wave
EWK105 C6104MP-F		16		X6S	0.1 μ	±20	5	150	0.3 ± 0.05	R
LWK105 C7104MP-F		10		X7S	0.1 μ	±20	5	150	0.3 ± 0.05	R
LWK105 C6224MP-F		10		X6S	0.22 μ	±20	10	150	0.3 ± 0.05	R
JWK105 C7104MP-F				X7S	0.1 μ	±20	5	150	0.3 ± 0.05	R
JWK105 C7224MP-F		6.3		X7S	0.22 μ	±20	10	150	0.3 ± 0.05	R
JWK105 C6474MP-F				X6S	0.47 μ	±20	10	150	0.3 ± 0.05	R
AWK105 C6224MP-F				X6S	0.22 μ	±20	10	150	0.3 ± 0.05	R
AWK105 C6474MP-F		4		X6S	0.47 μ	±20	10	150	0.3 ± 0.05	R
AWK105 C6105MP-F		4		X6S	1 μ	±20	10	150	0.3 ± 0.05	R
AWK105 C6225MP-F				X6S	2.2 μ	±20	10	150	0.3 ± 0.05	R

107TYPE

[Temperature Characteristic BJ : X5R(-55~+85°C)] 0.5mm thickness(V)

Part number 1	Part number 2	Rated voltage [V]	erature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
TWK107 BJ104MV-T		25	X5R*1	0.1 μ	±20	5	150	0.5±0.05	R
EWK107 BJ224MV-T		16	X5R*1	0.22 μ	±20	5	150	0.5±0.05	R
EWK107 BJ474MV-T		10	X5R*1	0.47 μ	±20	5	150	0.5±0.05	R
LWK107 BJ105MV-T		10	X5R	1 μ	±20	10	150	0.5 ± 0.05	R
LWK107 BJ225MV-T		10	X5R	2.2 μ	±20	10	150	0.5 ± 0.05	R
JWK107 BJ105MV-T			X5R*1	1 μ	±20	10	150	0.5±0.05	R
JWK107 BJ225MV-T		6.3	X5R	2.2 μ	±20	10	150	0.5±0.05	R
JWK107 BJ475MV-T		1	X5R	4.7 μ	±20	10	150	0.5 ± 0.05	R
AWK107 BJ106MV-T		4	X5R	10 μ	±20	10	150	0.5 ± 0.05	R

[Temperature Characteristic B7 : X7R(-55~+125°C), C6 : X6S(-55~+105°C), C7 : X7S(-55~+125°C)] 0.5mm thickness(V)

Li ciliperature Oriarat	Ceristic D7 . X/II(00 1120	O), OU . NOO	33 110	0 0), 01 . X/O(00	1 120 07	1 0.5Hilli tillekii	C33(V)	
Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance tolerance	$ an\delta$	HTLT	Thickness*3 [mm]	Soldering R:Reflow
Fart Humber 1	Fart Humber 2	[V]	characteristics	[F]	[%]	[%]	Rated voltage x %	Thickness [mm]	W:Wave
TWK107 B7104MV-T		25	X7R	0.1 μ	±20	5	150	0.5 ± 0.05	R
EWK107 B7224MV-T		16	X7R	0.22 μ	±20	5	150	0.5 ± 0.05	R
EWK107 B7474MV-T		10	X7R	0.47 μ	±20	5	150	0.5 ± 0.05	R
JWK107 C7105MV-T		6.3	X7S	1 μ	±20	10	150	0.5 ± 0.05	R
AWK107 C7225MV-T		4	X7S	2.2 μ	±20	10	150	0.5 ± 0.05	R
AWK107 C6475MV-T		4	X6S	4.7 μ	±20	10	150	0.5 ± 0.05	R
PWK107 C6106MV-T		2.5	X6S	10 μ	±20	10	150	0.5 ± 0.05	R

■212TYPE

[Temperature Characteristic BJ : X5R(-55~+85°C)] 0.85mm thickness(D)

Part number 1	Part number 2	Rated voltage [V]	Tempe charact		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
TWK212 BJ475[]D-T		25		X5R	4.7 μ	±10, ±20	10	150	0.85 ± 0.10	R
EWK212 BJ106MD-T		16		X5R	10 μ	±20	10	150	0.85 ± 0.10	R
LWK212 BJ475[]D-T		10		X5R	4.7 μ	±10, ±20	10	150	0.85 ± 0.10	R
LWK212 BJ106MD-T		10		X5R	10 μ	±20	10	150	0.85 ± 0.10	R
JWK212 BJ226MD-T		6.3		X5R	22 μ	±20	10	150	0.85 ± 0.10	R

[Temperature Characteristic B7 : $X7R(-55 \sim +125^{\circ}C)$, C6 : $X6S(-55 \sim +105^{\circ}C)$] 0.85mm thickness(D)

Tremperature Onarac	Steristic D7 . A/II(33 1 123	C), O0	. 703(33 1 10	3 C/ T 0.03HIIII triicknes	3(D)			
Part number 1	Part number 2	Rated voltage [V]		erature eristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
TWK212 B7225[]D-T		25		X7R	2.2 μ	±10, ±20	5	150	0.85 ± 0.10	R
EWK212 C6475 D-T		16		X6S	4.7 μ	±10, ±20	10	150	0.85 ± 0.10	R
LWK212 C6106MD-T		10		X6S	10 μ	±20	10	150	0.85±0.10	R
AWK212 C6226MD-T		4		X6S	22 μ	±20	10	150	0.85 ± 0.10	R

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Multilayer Ceramic Capacitors

■PACKAGING

1)Minimum Quantity

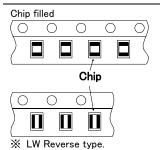
T (514)	Thick	ness	Standard of	quantity [pcs]
Type(EIA)	mm	code	Paper tape	Embossed tape
□MK021(008004)	0.105	V		F0000
□VS021(008004)	0.125	К	_	50000
☐MK042(01005)	0.2	C, D		40000
□VS042(01005)	0.2	С		40000
☐MK063(0201)	0.3	P,T	15000	_
□WK105(0204) ※	0.3	Р	10000	_
	0.13	Н	_	20000
Thu(105(0400)	0.18	E	_	15000
☐MK105(0402)	0.2	С	20000	_
□MF105(0402)	0.3	Р	15000	_
	0.5	٧	10000	_
□VK105(0402)	0.5	W	10000	_
□MK107(0603)	0.45	K	4000	_
□WK107(0306) ※	0.5	V	_	4000
□MF107(0603)	0.8	Α	4000	_
□VS107(0603)	0.7	С	4000	_
□MJ107(0603)	0.8	Α	3000	3000
□MK212(0805)	0.45	K	4000	
□WK212(0508) ※	0.85	D	4000	_
□MF212(0805)	1.25	G	_	3000
□VS212(0805)	0.85	D	4000	_
[] N. 104.0(0.005)	0.85	D	4000	_
□MJ212(0805)	1.25	G	_	2000
DM (040(4000)	0.85	D	4000	_
☐MK316(1206)	1.15	F	_	3000
□MF316(1206)	1.6	L	_	2000
The 1040(4000)	1.15	F	_	3000
□MJ316(1206)	1.6	L	_	2000
	0.85	D		
DM/205(1010)	1.15	F		2000
□MK325(1210) □MF325(1210)	1.9	N		2000
□ML252(1510)	2.0max.	Υ		
	2.5	М	_	1000
□MJ325(1210)	1.9	N	_	2000
□INIO9520(1510)	2.5	М	_	500(T), 1000(P)
□MK432(1812)	2.5	М	_	500

Note:

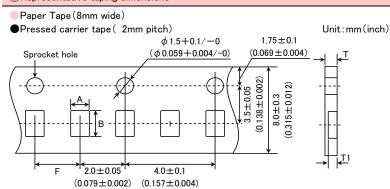
K LW Reverse type.

**No bottom tape for pressed carrier tape Card board carrier tape Top tape Base tape Sprocket hole Chip cavity Base tape Chip cavity

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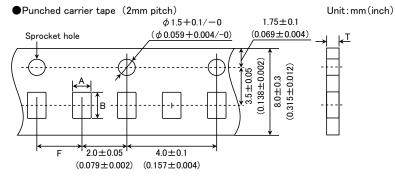
3 Representative taping dimensions



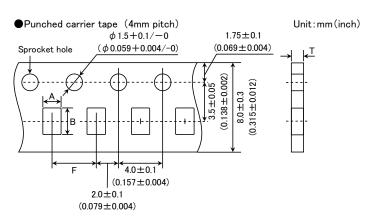
Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
Type(EIA)	Α	В	F	Т	T1
□MK063(0201)	0.37	0.67		0.45max.	0.42
□WK105(0204) ※			2.0±0.05	0.45max.	0.42max.
□MK105(0402) (*1 C)	0.65	1.15	2.0±0.05	0.4max.	0.3max.
□MK105(0402) (*1 P)				0.45max.	0.42max.

Note *1 Thickness, C:0.2mm ,P:0.3mm. * LW Reverse type.

Unit:mm



Type(EIA)	Chip	Cavity	Insertion Pitch	Tape Thickness
Type(EIA)	Α	В	F	Т
☐MK105 (0402)				
☐MF105 (0402)	0.65	1.15	2.0 ± 0.05	0.8max.
□VK105 (0402)				
	•			Unit:mm

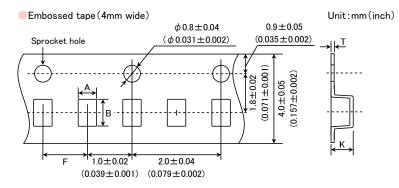


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Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness
Type(EIA)	A B		F T	
☐MK107(0603)				
□WK107(0306) ※	1.0	1.8		1.1max.
☐MF107(0603)			40+01	
☐MK212(0805)	1.65	0.4	4.0±0.1	
□WK212(0508) ※	1.65	2.4		1.1max.
☐MK316(1206)	2.0	3.6		

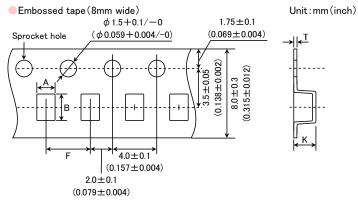
Note: Taping size might be different depending on the size of the product. X LW Reverse type.

Unit:mm



Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness		
Type(EIA)	Α	В	F	K	Т	
☐MK021(008004)	0.135	0.27			0.25max.	
□VS021(008004)	0.135		1.0±0.02	0.5max.		
☐MK042(01005)	0.23	0.40	1.0 ± 0.02			
□VS042(01005)	0.23	0.43				

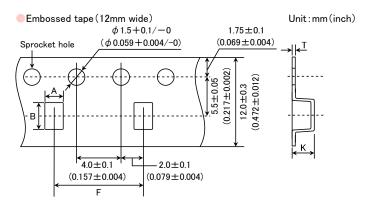
Unit:mm



Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness	
Type(EIA)	Α	В	F	K	Т
☐MK105(0402)	0.6	1.1	2.0±0.1	0.6max	0.2±0.1
□WK107(0306) ※	1.0	1.8		1.3max.	0.25±0.1
☐MK212(0805) ☐MF212(0805)	1.65	2.4			0.6max.
☐MK316(1206) ☐MF316(1206)	2.0	3.6	4.0±0.1	3.4max.	
☐MK325(1210) ☐MF325(1210)	2.8	3.6]		

Note: ※ LW Reverse type. Unit:mm

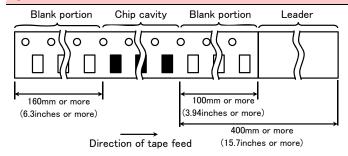
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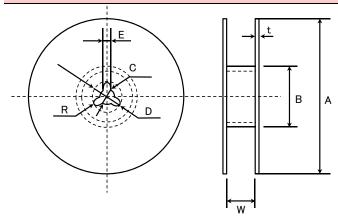
Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness	
Type(EIA)	Α	В	F	K	Т
☐MK325(1210)	3.1	4.0	8.0±0.1	4.0max.	0.6max.
☐MK432(1812)	3.7	4.9	8.0±0.1	4.0max.	0.6max.

Unit:mm

4 Trailer and Leader



⑤Reel size



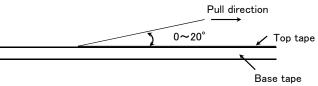
Α	В	С	D	E	R
ϕ 178 ± 2.0	<i>ф</i> 50min.	ϕ 13.0 \pm 0.2	ϕ 21.0 ± 0.8	2.0±0.5	1.0

	T	W
4mm wide tape	1.5max.	5±1.0
8mm wide tape	2.5max.	10±1.5
12mm wide tape	2.5max.	14±1.5

Unit:mm

6Top Tape Strength

The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.



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Multilayer Ceramic Capacitors

■RELIABILITY DATA

1.Operating T		1	1				
	Temperature Compensating (Class 1)	Standard	—55 to -	+125°C			
Compensating	Compensating(Class1)	High Frequency Type	30 10	1 120 0			
				Specification	Temperature Range	1	
			BJ	В	−25 to +85°C		
Specified			В	X5R	−55 to +85°C		
Value	High Permittivity (Class2	1	B7	X7R	−55 to +125°C		
	nigh Permittivity (Glassz)	C6	X6S	−55 to +105°C		
			C7	X7S	−55 to +125°C		
			LD(※)	X5R	−55 to +85°C		
			Note: >	LD Low distortion h	iigh value multilayer ceramic cap	acitor	
	•						
2. Storage Co	onditions						
	Temperature	Standard		0 -			
	Temperature Compensating(Class1)	Standard High Frequency Type	—55 to -	⊢125°C			
	•		—55 to -	+125°C	Temperature Range	1	
	•				Temperature Range -25 to +85°C]	
•	•		-55 to -	Specification		-	
	Compensating(Class1)	High Frequency Type		Specification B	−25 to +85°C		
Specified Value	•	High Frequency Type	BJ	Specification B X5R	-25 to +85°C -55 to +85°C		
	Compensating(Class1)	High Frequency Type	BJ B7	Specification B X5R X7R	-25 to +85°C -55 to +85°C -55 to +125°C	-	
•	Compensating(Class1)	High Frequency Type	BJ B7 C6 C7 LD(%)	Specification B X5R X7R X6S X7S X5R	-25 to +85°C -55 to +85°C -55 to +125°C -55 to +105°C -55 to +125°C -55 to +85°C		
•	Compensating(Class1)	High Frequency Type	BJ B7 C6 C7 LD(%)	Specification B X5R X7R X6S X7S X5R	-25 to +85°C -55 to +85°C -55 to +125°C -55 to +105°C -55 to +125°C	- - - - - - acitor	
•	Compensating(Class1)	High Frequency Type	BJ B7 C6 C7 LD(%)	Specification B X5R X7R X6S X7S X5R	-25 to +85°C -55 to +85°C -55 to +125°C -55 to +105°C -55 to +125°C -55 to +85°C	acitor	
•	Compensating(Class1) High Permittivity (Class2	High Frequency Type	BJ B7 C6 C7 LD(%)	Specification B X5R X7R X6S X7S X5R	-25 to +85°C -55 to +85°C -55 to +125°C -55 to +105°C -55 to +125°C -55 to +85°C	acitor	
Value 3. Rated Volt	Compensating(Class1) High Permittivity (Class2	High Frequency Type	BJ B7 C6 C7 LD(%) Note: \$	Specification B X5R X7R X6S X7S X5R	-25 to +85°C -55 to +85°C -55 to +125°C -55 to +105°C -55 to +125°C -55 to +85°C	acitor	
Value	Compensating(Class1) High Permittivity (Class2	High Frequency Type	BJ B7 C6 C7 LD(※) Note: >	Specification B X5R X7R X6S X7S X5R XLD Low distortion in	-25 to +85°C -55 to +85°C -55 to +125°C -55 to +105°C -55 to +125°C -55 to +85°C	acitor	

4. Withstanding	Voltage (Between terminal	s)				
C:E1	Temperature	Standard				
•	Value Compensating (Class1) High Permittivity (Class2)		equency Type	No breakdown o	r damage	
value						
T		CI		ass 1 Class 2		
	Test Methods and Remarks Applied voltage Duration		Rated v	oltage × 3	Rated voltage × 2.5	
			1 to 5 sec.			
i terriar NS	Charge/discharge currer	nt	50mA max.			

5. Insulation Re	5. Insulation Resistance						
	Temperature	Standard	10000 MΩ min.				
Specified	Compensating(Class1)	High Frequency Type	10000 M SZ min.				
Value	High Permittivity (Class2)) Note 1	$C \le 0.047$ F: 10000 MΩ min. C>0.047 μ F: 500MΩ • μ F				
Test	Applied voltage	: Rated voltage					
Methods and	Duration	: 60±5 sec.					
Remarks	Charge/discharge current	: 50mA max.					

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6. Capacitance	(Tolerance)					
Temperature Specified Occurrent in (Class 1)	Standard	C D	0.2pF≦C≦5pF 0.2pF≦C≦10pF C>10pF	: ±0.25pF : ±0.5pF : ±5% or ±10%		
Value	Compensating(Class1) High	High Frequency Type	CG	0.2pF≦C≦2pF C>2pF	: ±0.1pF : ±5%	
	High Permittivity (Class2)	±10%	or ±20%		
			Class 1		Class 2	
- .		Standard	Standard High Frequency Type		C≦10 <i>μ</i> F	C>10 μ F
	Test Preconditioning		No	one	Thermal treatment (a	t 150°C for 1hr) Note 2
Remarks	Measuring frequency		1MHz±10%		1kHz±10%	120±10Hz
	Measuring voltage Nte		0.5 to	5Vrms	1±0.2Vrms	0.5±0.1Vrms
	Bias application				None	•

Specified Value	Temperature		Standard		$C < 30pF : Q \ge 400 + 20C$ $C \ge 30pF : Q \ge 1000$ (C:Nominal capacitance)			
	Compensating(Class1)	High Frequency Type		Refer to detailed specification				
	High Permittivity (Class2) Note 1			BJ, B7, C6, C7:2.5% max.				
			Class 1		Class 2			
			Standard		High Frequency Type	C≦10 <i>μ</i> F	C>10 μ F	
	Preconditioning		None		Thermal treatment (at 150°C for 1hr) Note 2			
Test	Measuring frequency		1MHz±10%		1GHz	1kHz±10%	120±10Hz	
Methods and	Measuring voltage Note 1			0.5 to	5Vrms	1±0.2Vrms	0.5±0.1Vrms	
Remarks	Bias application			None				
	High Frequency Type							
	Measuring equipment : HP4291A							
	Measuring jig : HP16192A							

8. Temperature	Characteristic (Without vo	ltage application)							
		Standard	Temperature Characteristic [ppm/°C] Tolerance [ppm/°C]						
	Temperature Compensating(Class1)		C□: 0		CG		G: ±30		
			U□: -750		UJ, UK		J:±120 K:±250		
		High Frequency Type							
Specified Value				Specification	Capacitance change	Refere tempera		Temperature Range	
			BJ	В	±10%	20°0	С	−25 to +85°C	l
		БО	X5R	±15%	25°0	С	−55 to +85°C		
	High Permittivity (Class2)	В7	X7R	±15%	25°0	С	−55 to +125°C		
			C6	XS	±22%	25°0	С	-55 to +105°C	
			C7	X7S	±22%	25°0	С	−55 to +125°C	
			LD(※)	X5R	±15%	25°0	С	-55 to +85°C	l
			Note:	LOW disto	ortion high value i	multilayer	cerami	c capacitor	

Class 1

Capacitance at 20° C and 85° C shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

$$\frac{-\frac{(C_{85}-C_{20})}{C_{20}\times\Delta T}\times 10^{6}(\text{ppm/°C})}{\Delta T\!=\!65}$$

Test Methods and

Remarks

Class 2

Capacitance at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

Step	В	X5R, X7R, X6S, X7S			
1	Minimum operat	ing temperature			
2	20°C	25°C			
3	Maximum operating temperature				

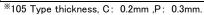
 $\begin{array}{c|c} \hline (C-C_2) & C & : Capacitance in Step 1 or Step 3 \\ \hline C_2 & C_2 & : Capacitance in Step 2 \\ \end{array}$

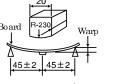
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Specified Value	Temperature Compensating(Class1)		Standard Appearance Capacitance chan		: No abnormality ge : Within $\pm 5\%$ or ± 0.5 pF, whichever is larger.		
			High Frequency Type	Appearance : No abnormality Capacitance change : Within±0.5 pF			
	High Permittivity (Class2)			Appearance Capacitance change	: No abnormality : Within ±12.5%		
		021 0	Multilayer Ceram 42, 063, *105 Type	·	20		
Test Methods and	Board Thickness		Glass epoxy-res	The other types sin substrate	Bo and R-230 Warp		
			0.8mm 1.6mm				

Remarks

	Multilayer Ceramic Capacitors				
	021, 042, 063, *105 Type	The other types			
Board	Glass epoxy-r	esin substrate			
Thickness	0.8mm 1.6mm				
Warp	1mm				
Duration	10 sec.				





Capacitance measurement shall be conducted with the board bent

10. Body Stren	0. Body Strength						
	Temperature	Standard	_				
Specified Value	Compensating(Class1)	High Frequency Type	No mechanical damage.				
valuo	High Permittivity (Class2)						
Test Methods and Remarks	High Frequency 105Type Applied force : 5N Duraton : 10 sec.	Pres ← A →	R0.5 Pressing Jig Chip O.6A A				

11. Adhesive St	trength of Terminal Elec	trodes			
	Temperature	Standard		No terminal separation or its indication.	
Specified Value	Compensating(Class1) High Frequency Type	No terminal separati		
value	High Permittivity (CI	ass2)			
T4		Multilayer Ceran	nic Capacitors		
Test Methods and		021, 042, 063 Type	105 Type or more		
Remarks	Applied force	2N	5N		
I Ciliai NS	Duration	30±5	sec.		

1					
Temperature	Standard				
Compensating(Class1)	High Frequency Type	y Type At least 95% of terminal electrode is covered by		by new solder.	
High Permittivity (Class2)					
	Eutectic so	older	Lead-free solder		
Solder type	H60A or H63A		Sn-3.0Ag-0.5Cu		
Solder temperature	230±5°	C 245±3°C			
Duration		4±1 sec.			
	Temperature Compensating(Class1) High Permittivity (Class2) Solder type Solder temperature	Temperature Compensating(Class1) High Frequency Type High Permittivity (Class2) Eutectic so Solder type H60A or H Solder temperature 230±5°	Temperature	Temperature	

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3. Resistance	to Soldering				
Specified Value	Temperature	Standard	Appearance Capacitance change Q Insulation resistance Withstanding voltage	: No abnormality : Within ±2.5% or ±0 : Initial value : Initial value (between terminals)	0.25pF, whichever is larger. : No abnormality
	Compensating(Class	High Frequency Type	Appearance : No abnormality Capacitance change : Within ±2.5% Q : Initial value Insulation resistance : Initial value Withstanding voltage (between termi		: No abnormality
	High Permittivity (Class2) Note 1		Appearance Capacitance change Dissipation factor Insulation resistance Withstanding voltage	: No abnormality : Within ±7.5% : Initial value : Initial value (between terminals):	No abnormality
			Class 1		
		021, 042, 063 Type			
	Preconditioning		None		
	Preheating	150°C, 1 to 2 min.		00°C, 2 to 5 min. 00°C, 2 to 5 min.	
	Solder temp.		270±5°C		
	Duration		3±0.5 sec.		
Test	Recovery	6 to 24 hrs	6 to 24 hrs (Standard condition) Note 5		
Methods and Remarks				Class 2	
		021, 042, 063 Type	105, 1	07, 212 Type	316, 325, 432 Type
	Preconditioning		Thermal treatment	(at 150°C for 1 hr) No	ote 2
	Preheating	150°C, 1 to 2 min.		00°C, 2 to 5 min. 00°C, 2 to 5 min.	80 to 100°C, 5 to 10 min. 150 to 200°C, 5 to 10 min.
	Solder temp.			270±5°C	,
	Duration			±0.5 sec.	
	Recovery		21+2 brs (Star	ndard condition) Note	5

14. Temperatur	re Cycle (Thermal Shock)				
Specified Value	Temperature	Standard	Capacitance change : 1 Q : 1 Insulation resistance : 1	No abnormality Within ±2.5% or ±0.25 Initial value Initial value between terminals): N	-
	Compensating(Class1)	High Frequency Type	Capacitance change : 1 Q : 1 Insulation resistance : 1	No abnormality Within ±0.25pF Initial value Initial value between terminals): N	o abnormality
	High Permittivity (Class2) Note 1	Capacitance change : \ Dissipation factor : I Insulation resistance : I	No abnormality Within ±7.5% Initial value Initial value between terminals):No	o abnormality
			Class 1		Class 2
	Preconditioning		None	Thermal treat	tment (at 150°C for 1 hr) Note 2
Test Methods and Remarks	1 cycle	Step 1 2 3 4	Temperatu Minimum operatin; Normal temp Maximum operatin; Normal temp	g temperature perature g temperature perature	Time (min.) 30±3 2 to 3 30±3 2 to 3
	Number of cycles		5	times	
	Recovery	6 to 24 hrs (Star	ndard condition)Note 5	24±2 hrs (S	Standard condition)Note 5

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15. Humidity (Steady State)				
	Temperature Compensating(Class1	Standard)	Capacitance change Q	: No abnormality : Within $\pm 5\%$ or ± 0.5 pF, whichever is larger. : $C < 10$ pF : $Q \ge 200 + 10$ C $10 \le C < 30$ pF : $Q \ge 275 + 2.5$ C $C \ge 30$ pF: $Q \ge 350$ (C: Nominal capacitance) : $1000 \ M\Omega$ min.	
Specified Value		High Frequency Type	Capacitance change	: No abnormality : Within ±0.5pF, : 1000 MΩ min.	
	High Permittivity (Class2) Note 1		Capacitance change Dissipation factor	: No abnormality : Within $\pm 12.5\%$: 5.0% max. : 50 M Ω μ F or 1000 M Ω whichever is smaller.	
		Cla	ass 1	Class 2	
		Standard	High Frequency Type	All items	
Test	Preconditioning	N	lone	Thermal treatment (at 150°C for 1 hr) Note 2	
Methods and	Temperature	40±2°C	60±2°C	40±2°C	
Remarks	Humidity	90 to	95%RH	90 to 95%RH	
	Duration	500+2	4/-0 hrs	500+24/-0 hrs	
	Recovery	6 to 24 hrs (Stand	ard condition)Note 5	24±2 hrs (Standard condition) Note 5	

16. Humidity Lo	pading				
Specified Value	Temperature	Standard	Appearance Capacitance change Q Insulation resistance	: Wit : C < C≧	abnormality thin $\pm 7.5\%$ or ± 0.75 pF, whichever is larger. 30 pF: $Q \ge 100 + 10$ C/3 ≥ 30 pF: $Q \ge 200$ (C: Nominal capacitance) 0 M Ω min.
	Compensating (Class1)	High Frequency Type	$\begin{array}{lll} \mbox{Appearance} & : \mbox{No abnormality} \\ \mbox{Capacitance change} & : \mbox{C} \leq 2 \mbox{pF} : \mbox{Within } \pm 0.4 \mbox{ pF} \\ \mbox{C} > 2 \mbox{pF} : \mbox{Within } \pm 0.75 \mbox{ pF} \\ \mbox{(C: Nominal capacitance)} \\ \mbox{Insulation resistance} & : 500 \mbox{ M} \mbox{min.} \end{array}$		
	High Permittivity (Class2) Note 1		Appearance Capacitance change Dissipation factor Insulation resistance	: Wit : 5.0	abnormality thin \pm 12.5% max. M Ω μ F or 500 M Ω , whichever is smaller.
		C	Class 1		Class 2
		Standard	High Frequency Ty	ре	All items
	Preconditioning		None		Voltage treatment (Rated voltage are applied for 1 hour at 40°C) Note 3
Test	Temperature	40±2°C	60±2°C		40±2°C
Methods and	Humidity	90 t	to 95%RH		90 to 95%RH
Remarks	Duration	500+	├24/一0 hrs		500+24/-0 hrs
	Applied voltage	Rate	ed voltage		Rated voltage
	Charge/discharge current	50r	mA max.		50mA max.
	Recovery	6 to 24 hrs (Stan	dard condition)Note 5		24±2 hrs(Standard condition) Note 5

			Appearance	: No abnormality	,	
			Capacitance change	: Within $\pm 3\%$ or ± 0.3 pF, whichever is larger.		
			Q	:C<10pF: Q≧	• •	J
		Standard		10≦C<30pF:	Q≧275+2.5C	
	Temperature			C≧30pF: Q≧	≧350 (C∶Nominal cap	oacitance)
Specified	Compensating(Class1)		Insulation resistance	: 1000 MΩ min.		
Specified Value			Appearance	: No abnormality	/	
value -		High Frequency Type	Capacitance change		±0.3pF, whichever	is larger.
			Insulation resistance	: 1000 MΩ min.		
			Appearance	: No abnormality		
	High Permittivity (Class2) Note 1		Capacitance change		ó	
			Dissipation factor	: 5.0% max.		
			Insulation resistance	: 50 M Ω <i>μ</i> F or	1000 MΩ, whicheve	r is smaller.
		Clas	ss 1	Class 2		
		Standard I	High Frequency Type	BJ, LD(※)	C6	B7, C7
	Preconditioning	No	ne	•		tage shall be applied for
					85°C, 105°C or 125	
Test	Temperature	Maximum operati	• '	Maximum operating temperature		
Methods and	Duration	1000+48	/-0 hrs	1000 + 48 / -0 hrs		
Remarks	Applied voltage	Rated voltage	e×2 Note 4	Rated voltage × 2 Note 4		
	Charge/discharge	50mA	may		50mA max.	
	current	JUIIA	IIIax.	50mA max.		
	Recovery	6 to 24hr (Standard	condition) Note 5	24±2 hrs(Standard condition)Note 5		

Note 1 The figures indicate typical specifications. Please refer to individual specifications in detail.

- Note 2 Thermal treatment : Initial value shall be measured after test sample is heat-treated at $150 \pm 0/-10^{\circ}$ C for an hour and kept at room temperature for 24 ± 2 hours.
- Note 3 Voltage treatment: Initial value shall be measured after test sample is voltage-treated for an hour at both the temperature and voltage specified in the test conditions, and kept at room temperature for 24±2hours.
- Note 4 150% of rated voltage is applicable to some items. Please refer to their specifications for further information.
- Note 5 Standard condition: Temperature: 5 to 35°C, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.
 - Temperature: $20\pm2^{\circ}$ C, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa Unless otherwise specified, all the tests are conducted under the "standard condition".

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Super Low Distortion Multilayer Ceramic Capacitors

RELIABILITY DATA

Duration

Test Methods and

Remarks

Test board

Thickness

: 10 seconds

: 1.6mm

: glass epoxy resin substrate

Capacitance measurement shall be conducted with the board bent.

1. Operating Tempe	ratura Ranga				
Specified Value	−55 to +125°C				
2. Storage Tempera	ture Range				
Specified Value	−55 to +125°C				
3. Rated Voltage					
Specified Value	6.3VDC, 10VDC, 16VDC, 25VDC	C, 35VDC, 50VDC			
4. Dielectric Withsta	anding Voltage (Between termina	ls)			
Specified Value	No breakdown or damage				
openiou value		Rated voltage × 3			
Test Methods and	=	to 5 sec.			
Remarks		50mA max.			
	3				
5. Insulation Resist	ance				
Specified Value	10000 M Ω or 500M Ω μ F, whic	haver is smaller			
Specified Value					
Test Methods and	=	Rated voltage 60±5 sec.			
Remarks		50mA max.			
	onargo, arosnargo carrone				
6. Capacitance (To	ularanaa)				
Specified Value	±10%				
Specified value					
Test Methods and	• , ,	IkHz±10% I±0.2Vrms			
Remarks	0 0	i ±0.2√rms None			
	Dias application . 1	10110			
7. Dissipation Fact					
•					
Specified Value	0.1%max				
Test Methods and	0 ,	lkHz±10%			
Remarks	0 0	I ±0.2Vrms None			
	Bias application : I	vone			
0.0. "					
8. Bending Strength					
Specified Value	• •	No abnormality			
-		± 5%			
	Warp : 1mm		l ← 20		
	Speed : 0.5mm/secon	ıd			

9. Adhesive Force	9. Adhesive Force of Terminal Electrodes				
Specified Value	Terminal electro	Terminal electrodes shall be no exfoliation or a sign of exfoliation.			
Test Methods and Remarks	Applied force Duration	: 5N : 30 ±5 seconds			

(Unit: mm)

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10. Solderability					
Specified Value	At least 95% of terminal electrode is covered by new solder.				
		Eutectic solder	Lead-free solder		
Test Methods and	Solder type	H60A or H63A	Sn-3.0Ag-0.5Cu		
Remarks	Solder temperature	230±5°C	245±3℃		
	Duration	4±1 sec.			

11. Resistance to S	Soldering Heat	
Specified Value	Capacitance change : ± Dissipation factor : Ir Insulation resistance : Ir	lo abnormality E2.5% max. nitial value nitial value etween terminals): No abnormality
Test Methods and Remarks	Solder temp. Duration Preheating conditions Measurement shall be conducted	: 270 ±5°C : 3 ±0.5 sec. : 80 to 100°C, 2 to 5 min. or 5 to 10 min. 150 to 200°C, 2 to 5 min. or 5 to 10 min. d : 24±2hrs under the standard condition Note1

12. Temperature Cy	cle (Therm	nal Shock)			
	Appearance		: No abnormality		
	Capacitano	ce change	: ±2.5% max		
Specified Value	Dissipation	n factor	: Initial value		
	Insulation	resistance	: Initial value		
	Withstandi	ng voltage	(between terminals): No abnormali	ty	
	Conditions	for 1 cycle			
	Step	temperature (°C)		Time (min.)	
Test Methods and	1	Minimum operating temperature		30±3 min.	
Remarks	2	Normal temperature		2 to 3 min.	
Remarks	3	Maximum operating temperature		30±3 min.	
	4	Normal temperature		2 to 3 min.	
	Number of	cycles: 5 time:	5		
	Measurem	ent shall be co	nducted : 24 ± 2 hrs under the standard	condition Note1	

13. Humidity (Stea	dy state)	
Specified Value	Capacitance change : ± Dissipation factor : 0.5	abnormality 5% max 5% max M Ω F or 1000M Ω , whichever is smaller
Test Methods and Remarks	Temperature Humidity Duration Measurement shall be conducted	: $40\pm2^{\circ}$ C : 90 to 95% RH : $500 + 24/-0$ hrs : 24 ±2 hrs under the standard condition Note1

14. Humidity Loadin	g	
Specified Value	Capacitance change : Dissipation factor : 0	No abnormality ± 7.5 % max 0.5% max 25M Ω μ F or 500M Ω , whichever is smaller
Test Methods and Remarks	According to JIS C 5101-1. Temperature Humidity Duration Applied voltage Charge/discharge current Measurement shall be conducted	: $40\pm2^{\circ}\text{C}$: 90 to 95% RH : 500 $\pm24/-0$ hrs : Rated voltage : 50mA max ed : 24 ±2 hrs under the standard condition Note1

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15. High Temperatu	re Loading	
	* *	o abnormality .3% max
Specified Value	Dissipation factor : 0.3	35% max $M\Omega$ μ F or $1000M\Omega$, whichever is smaller
Test Methods and Remarks	According to JIS C 5101-1. Temperature Duration Applied voltage Charge/discharge current Measurement shall be conducted	: Maximum operating temperature : 1000 +48/-0 hrs : Rated voltage x 2 : 50mA max : 24 ±2hrs under the standard condition Note1

Note1 Standard condition: Temperature: 5 to 35°C, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa

When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.

Temperature: $20\pm2^{\circ}$ C, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa Unless otherwise specified, all the tests are conducted under the "standard condition".

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Medium-High Voltage Multilayer Ceramic Capacitor

■RELIABILITY DATA

1. Operating Tempe	rature Range			
	Temperature Compensating(Class1)	CG : -55 to +125°C		
		X7R, X7S : -55 to +125°C		
Specified Value	High Permittivity (Class2)	X5R : -55 to +85°C		
	(e.ass_/	B : -25 to +85°C		
		SD : −55 to +125°C		
2. Storage Tempera	ture Range			
	Temperature Compensating(Class1)	CG : -55 to +125°C		
		X7R, X7S : −55 to +125°C		
Specified Value	High Permittivity (Class2)	X5R : −55 to +85°C		
	, (B : -25 to +85°C		
		SD : −55 to +125°C		
3. Rated Voltage				
Specified Value	Temperature Compensating(Class1)	100VDC(HMK)		
Specified value	High Permittivity (Class2)	100VDC(HMK), 250VDC(QMK), 630VDC(SMK), 2000VDC(XMK)		
4 Withstanding Volt	age (Between terminals)			
Specified Value	No breakdown or damage			
		×2.5(HMK), Rated voltage ×2(QMK), Rated voltage ×1.2(SMK)(XMK)		
Test Methods and	Duration : 1 to 5sec.			
Remarks	Charge/discharge current : 50mA max.			
5. Insulation Resista		-		
Specified Value	Temperature Compensating(Class1)	10000 MΩ min.		
·	High Permittivity (Class2)	100M Ω • μ F or 10G Ω , whichever is smaller.		
Test Methods and	Applied voltage : Rated voltage (HMK, QMK), 500V(SMK,XMK)			
Remarks	Duration : 60±5sec. Charge/discharge current : 50mA max.			
	Onarge/ discharge current . John max.			
6. Capacitance(To	lerance)			
		0.2pF≦C≦5pF : ±0.25pF		
Specified Value	Temperature Compensating(Class1)	0.2pF≦C≦10pF : ±0.5pF		
opcomed value		C>10pF : ±5% or ±10%		
	High Permittivity (Class2)	±10%, ±20%		
	Temperature Compensating(Class1)	Measuring frequency : 1MHz±10% Measuring voltage : 0.5∼5Vrms		
Test Methods and	Temperature Compensating (Class I)	Measuring voltage : 0.5∼5Vrms Bias application : None		
Remarks		Measuring frequency : 1kHz±10%		
	High Permittivity (Class2)	Measuring voltage : 1±0.2Vrms		
		Bias application : None		
7. Q or Dissipation	Factor			
		C<30pF: Q≧400+20C		
Specified Value	Temperature Compensating(Class1)	C≧30pF : Q≧1000 (C:Nominal capacitance)		
	High Permittivity (Class2)	3.5%max(HMK),2.5%max(QMK, SMK)		
	T	Measuring frequency : 1MHz±10%		
Took Made and	Temperature Compensating(Class1)	Measuring voltage : 0.5∼5Vrms Bias application : None		
Test Methods and				
Remarks		I Measuring frequency : 1kHz ± 10%		
Remarks	High Permittivity (Class2)	Measuring frequency : 1kHz±10% Measuring voltage : 1±0.2Vrms		

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8. Temperature Ch	Temperature Compensating (Class1)	CG :0±30ppm/°C(-55 to +125°C)
Specified Value	High Permittivity (Class2)	B : $\pm 10\%(-25 \text{ to } +85^{\circ}\text{C})$ X5R : $\pm 15\%(-55 \text{ to } +85^{\circ}\text{C})$ X7R : $\pm 15\%(-55 \text{ to } +125^{\circ}\text{C})$ X7S : $\pm 22\%(-55 \text{ to } +125^{\circ}\text{C})$ SD : $-(-55 \text{ to } +125^{\circ}\text{C})$
	Class 1 Capacitance at 20°C and 85°C shall be mediately following equation. $\frac{(C_{85}-C_{20})}{C_{20}\times\Delta T} \times 10^6 (\text{ppm/°C})$	easured in thermal equilibrium, and the temperature characteristic shall be calculated from the $\Delta T {=} 65$

Test Methods and Remarks

Capacitance at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

0 1				
Step	В	X5R, X7R, X6S, X7S		
1	Minimum operating temperature			
2	20°C 25°C			
3	Maximum operating temperature			

$$\frac{(C-C_2)}{C_2} \times 100(\%)$$

C : Capacitance value in Step 1 or Step 3

Capacitance measurement shall be conducted with the board bent.

C2: Capacitance value in Step 2

9. Deflection	
Specified Value	Temperature Compensating(Class1) Appearance : No abnormality Capacitance change : Within ±5% or ±0.5 pF, whichever is larger.
opeomed value	High Permittivity (Class2) Appearance : No abnormality Capacitance change : Within±10%
Test Methods and Remarks	Warp : 1mm Duration : 10sec. Test board : Glass epoxy-resin substrate Thickness : 1.6mm Board Warp Warp Warp (Unit: mm)

10. Adhesive Strength of Terminal Electrodes

Specified Value

Temperature Compensating(Class1)
High Permittivity (Class2)

No terminal separation or its indication.

Applied force : 5N

Test Methods and	Applied force : 5N				
Remarks	Duration : 30±5sec.				
11. Solderability					
C :C 17/1	Temperature Compensating(Class1)		At least 95% of terminal electrode is covered by new solder		
Specified Value	High Permittivity (Class2)				
		Eutecti	c solder	Lead-free solder	7
Test Methods and Remarks	Solder type	H60A d	or H63A	Sn-3.0Ag-0.5Cu	
	Solder temperature	230	±5°C	245±3°C	
	Duration		4±1	sec.	

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12. Resistance to S	oldering				
	Temperature Compensating(Class1)		Appearance Capacitance change Q Insulation resistance Withstanding voltage	: Within : Initial : Initial	
Specified Value	High Permittivity(Class)			n±15%(HMK), ±10%(QMK, SMK,XMK) value value	
		Temperature Compensating(Class1)			
	Preconditioning	None			
	Solder temperature	270±5°C			
	Duration	3±0.5sec.			
	Preheating conditions	80 to 100°C, 2 to 5 min. 150 to 200°C, 2 to 5min.			
Test Methods and	Recovery	24±2hrs under the standard condition Note3			
Remarks		1	2 '11' '1 (01 0)		1
	D 1911		Permittivity (Class2)		
	Preconditioning		(at 150°C for 1hr) Note1		
	Solder temperature	270±5°C			
	Duration	3±0.5sec.			
	Preheating conditions	80 to 100°C, 2 to 5			
		150 to 200°C, 2 to			
	Recovery	24±2hrs under the	e standard condition Note	3	

13. Temperature Cy	cle (Thermal Shock)					
Specified Value	Temperature Compen	sating(Class1)	Appearance Capacitance change Q Insulation resistance Withstanding voltage	: No abnormality : Within $\pm 2.5\%$ or ± 0.25 pF, whichever is larger.(HMK) : Initial value : Initial value (between terminals) : No abnormality		•
	High Permittivity(Cla	ass2)	Appearance Capacitance change Dissipation facto Insulation resistance Withstanding voltage	: No abnormality : Within±15%(HMK), ±10%(QMK, SMK,XMK) : Initial value : Initial value (between terminals): No abnormality		
			Class 1		Class 2	
	Preconditioning		None	Thermal treat	ment (at 150°C fo	or 1 hr) Note 1
		Step	Step Temperatur		Time (min.)	
T . M .! ! !		1	Minimum operatir	ng temperature	30±3	
Test Methods and	1 cycle	2	Normal tem	perature	2 to 3	
Remarks		3	Maximum operatin	g temperature	30±3	
		4	Normal tem	Normal temperature		
	Number of cycles		5	times		-
	Recovery	6 to 24 hrs (Sta	ndard condition) Note 3	24±2 hrs	Standard conditi	on) Note 3

14. Humidity (Stea	dy state)			
Specified Value	Temperature Compensating(Class1)		Appearance Capacitance chang Q Insulation resistance	: $C < 10pF$: $Q \ge 200 + 10C$ $10 \le C < 30pF$: $Q \ge 275 + 2.5C$ $C \ge 30pF$: $Q \ge 350$ (C: Nominal capacitance)
	High Permittivity (Class2)		Appearance Capacitance chang Dissipation factor Insulation resistance	: 7%max(HMK), 5%max(QMK, SMK, XMK).
		Class 1		Class 2
	Preconditioning	None		Thermal treatment(at 150°C for 1 hr) Note 1
Test Methods and	Temperature	40±2°	С	40±2°C
Remarks	Humidity	90 to 95%	6RH	90 to 95%RH
	Duration	500+24/-	-0 hrs	500+24/-0 hrs
	Recovery	6 to 24 hrs (Standard	condition) Note 3	24±2 hrs (Standard condition) Note 3

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15. Humidity Loadin	g			
Specified Value	Temperature Compensating(Class1)		Appearance Capacitance change Q Insulation resistance	: No abnormality : Within $\pm 7.5\%$ or ± 0.75 pF, whichever is larger (HMK). : $C < 30$ pF: $Q \ge 100 + 10$ C/3 $C \ge 30$ pF: $Q \ge 200$ (C: Nominal capacitance) : $500 \text{ M}\Omega$ min.
	High Permittivity (Class2)		Appearance Capacitance change Dissipation factor Insulation resistance	: No abnormality : Within \pm 15% : 7%max (HMK), 5%max (QMK, SMK, XMK). : 10M Ω μ F or 500M Ω , whichever is smaller.
	According to JIS 510	1-1.		
		Class 1		Class 2
	Preconditioning	N	lone	Voltage treatment (Rated voltage are applied for 1 hour at 40°C) Note 2
	Temperature	40±2°C		40±2°C
Test Methods and	Humidity	90 to	95%RH	90 to 95%RH
Remarks	Duration	500+2	4/-0 hrs	500+24/-0 hrs
	Applied voltage	Rated	l voltage	Rated voltage
	Charge/discharge current	50m	A max.	50mA max.
	Recovery	6 to 24 hrs (Stand	ard condition)Note 3	24±2 hrs(Standard condition) Note 3

16. High Temperature Loading						
Specified Value	Temperature Compensating(Class1)		Appearance Capacitance cha Q Insulation resista	: $C < 30pF: Q \ge 100 + 10C/3$ $C \ge 30pF: Q \ge 200$ (C:Nominal capacitance)		
	High Permittivity(Class2)		Appearance Capacitance cha Dissipation facto Insulation resista	tor : 7%max(HMK), 5%max(QMK, SMK, XMK).		
	According to JIS 5101-1.					
		Class 1		Class 2		
	Preconditioning	None		Voltage treatment Note 2		
	Temperature	Maximum operating temperature		Maximum operating temperature		
Test Methods and	Duration	1000+48/-	·0 hrs	1000+48/-0 hrs		
Remarks	Applied voltage	Rated voltage × 2(HMK)		Rated voltage × 2(HMK), Rated voltage × 1.5 (QMK), Rated voltage × 1.2 (SMK,XMK)		
	Charge/discharge current	50mA ma	ıx.	50mA max.		
	Recovery	6 to 24hr (Standard co	ondition) Note 3	24±2 hrs (Standard condition) Note 3		

Note1 Thermal treatment : Initial value shall be measured after test sample is heat-treated at $150 \pm 0/-10^{\circ}$ C for an hour and kept at room temperature for 24 ± 2 hours.

Note2 Voltage treatment: Initial value shall be measured after test sample is voltage—treated for an hour at both the temperature and voltage specified in the test conditions, and kept at room temperature for 24±2hours.

Note3 Standard condition : Temperature: 5 to 35° C, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa

When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.

Temperature: $20\pm2^{\circ}$ C, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa Unless otherwise specified, all the tests are conducted under the "standard condition".

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Precautions on the use of Multilayer Ceramic Capacitors

■PRECAUTIONS

1. Circuit Design

- ◆Verification of operating environment, electrical rating and performance
- 1. A malfunction of equipment in fields such as medical, aerospace, nuclear control, etc. may cause serious harm to human life or have severe social ramifications.

Therefore, any capacitors to be used in such equipment may require higher safety and reliability, and shall be clearly differentiated from them used in general purpose applications.

Precautions

- ◆Operating Voltage (Verification of Rated voltage)
 - 1. The operating voltage for capacitors must always be their rated voltage or less.
 - If an AC voltage is loaded on a DC voltage, the sum of the two peak voltages shall be the rated voltage or less.
 - For a circuit where an AC or a pulse voltage may be used, the sum of their peak voltages shall also be the rated voltage or less.
 - 2. Even if an applied voltage is the rated voltage or less reliability of capacitors may be deteriorated in case that either a high frequency AC voltage or a pulse voltage having rapid rise time is used in a circuit.

2. PCB Design

Precautions

- ◆Pattern configurations (Design of Land-patterns)
- 1. When capacitors are mounted on PCBs, the amount of solder used (size of fillet) can directly affect the capacitor performance. Therefore, the following items must be carefully considered in the design of land patterns:
 - (1) Excessive solder applied can cause mechanical stresses which lead to chip breaking or cracking. Therefore, please consider appropriate land-patterns for proper amount of solder.
 - (2) When more than one component are jointly soldered onto the same land, each component's soldering point shall be separated by solder-resist.
- ◆Pattern configurations (Capacitor layout on PCBs)

After capacitors are mounted on boards, they can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering of the boards, etc.). For this reason, land pattern configurations and positions of capacitors shall be carefully considered to minimize stresses.

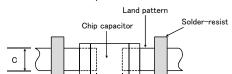
◆Pattern configurations (Design of Land-patterns)

The following diagrams and tables show some examples of recommended land patterns to prevent excessive solder amounts.

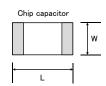
- (1) Recommended land dimensions for typical chip capacitors
- Multilayer Ceramic Capacitors : Recommended land dimensions (unit: mm)

Wave-soldering

	That's seriasing							
Type		107	212	316	325			
٥.	┙	1.6	2.0	3.2	3.2			
Size	W	0.8	1.25	1.6	2.5			
Α		0.8 to 1.0	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5			
В		0.5 to 0.8	0.8 to 1.5	0.8 to 1.7	0.8 to 1.7			
С		0.6 to 0.8	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5			



Land patterns for PCBs



Technical considerations

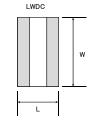
Reflow-soldering

Tenew Soldering										
Туре		021	042	063	105	107	212	316	325	432
Size	L	0.25	0.4	0.6	1.0	1.6	2.0	3.2	3.2	4.5
	W	0.125	0.2	0.3	0.5	0.8	1.25	1.6	2.5	3.2
Α		0.095~0.135	0.15~0.25	0.20~0.30	0.45~0.55	0.6~0.8	0.8~1.2	1.8~2.5	1.8~2.5	2.5~3.5
В		0.085~0.125	0.10~0.20	0.20~0.30	0.40~0.50	0.6~0.8	0.8~1.2	1.0~1.5	1.0~1.5	1.5~1.8
С		0.110~0.150	0.15~0.30	0.25~0.40	0.45~0.55	0.6~0.8	0.9~1.6	1.2~2.0	1.8~3.2	2.3~3.5

 $Note: Recommended \ land \ size \ might be \ different \ according \ to \ the \ allowance \ of \ the \ size \ of \ the \ product.$

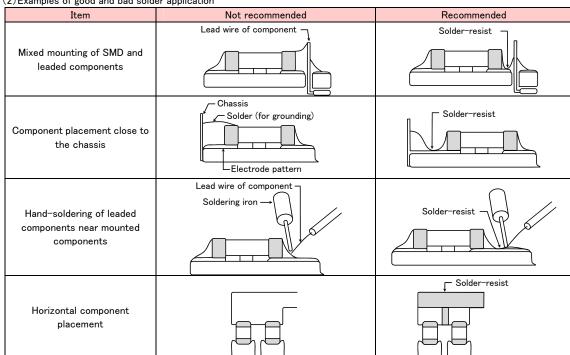
●LWDC: Recommended land dimensions for reflow-soldering (unit: mm)

Туре		105	107	212	
C:	L	0.52	0.8	1.25	
Size	W	1.0	1.6	2.0	
Α		0.18~0.22	0.25~0.3	0.5~0.7	
В		0.2~0.25	0.3~0.4	0.4~0.5	
С		0.9~1.1	1.5~1.7	1.9~2.1	



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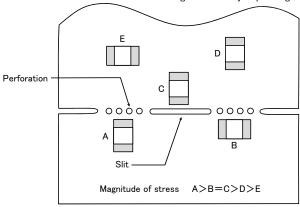
(2) Examples of good and bad solder application



- ◆Pattern configurations (Capacitor layout on PCBs)
 - 1-1. The following is examples of good and bad capacitor layouts; capacitors shall be located to minimize any possible mechanical stresses from board warp or deflection.

Items	Not recommended	Recommended			
Deflection of board		Place the product at a right angle to the direction of the anticipated mechanical stress.			

1-2. The amount of mechanical stresses given will vary depending on capacitor layout. Please refer to diagram below.



1-3. When PCB is split, the amount of mechanical stress on the capacitors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, please consider the PCB, split methods as well as chip location.

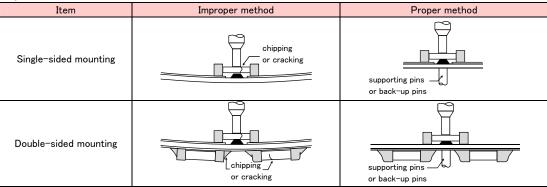
3. Mounting

- ◆Adjustment of mounting machine
 - 1. When capacitors are mounted on PCB, excessive impact load shall not be imposed on them.
 - 2. Maintenance and inspection of mounting machines shall be conducted periodically.
- ◆Selection of Adhesives Precautions
 - 1. When chips are attached on PCBs with adhesives prior to soldering, it may cause capacitor characteristics degradation unless the following factors are appropriately checked: size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, please contact us for further information.

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◆Adjustment of mounting machine

- 1. When the bottom dead center of a pick-up nozzle is too low, excessive force is imposed on capacitors and causes damages. To avoid this, the following points shall be considerable.
 - (1) The bottom dead center of the pick-up nozzle shall be adjusted to the surface level of PCB without the board deflection.
 - (2) The pressure of nozzle shall be adjusted between 1 and 3 N static loads.
 - (3) To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins shall be used on the other side of the PCB. The following diagrams show some typical examples of good and bad pick-up nozzle placement:



Technical considerations

2. As the alignment pin is worn out, adjustment of the nozzle height can cause chipping or cracking of capacitors because of mechanical impact on the capacitors.

To avoid this, the monitoring of the width between the alignment pins in the stopped position, maintenance, check and replacement of the pin shall be conducted periodically.

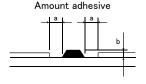
◆Selection of Adhesives

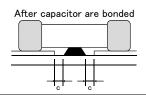
Some adhesives may cause IR deterioration. The different shrinkage percentage of between the adhesive and the capacitors may result in stresses on the capacitors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect components. Therefore, the following precautions shall be noted in the application of adhesives.

- (1) Required adhesive characteristics
 - a. The adhesive shall be strong enough to hold parts on the board during the mounting & solder process.
 - b. The adhesive shall have sufficient strength at high temperatures.
 - c. The adhesive shall have good coating and thickness consistency.
 - d. The adhesive shall be used during its prescribed shelf life.
 - e. The adhesive shall harden rapidly.
 - f. The adhesive shall have corrosion resistance.
 - g. The adhesive shall have excellent insulation characteristics.
 - h. The adhesive shall have no emission of toxic gasses and no effect on the human body.
- (2) The recommended amount of adhesives is as follows;

[Recommended condition]

a 0.3mm min b 100 to 120 μ m c Adhesives shall not contact land	Figure	212/316 case sizes as examples
	а	0.3mm min
c Adhesives shall not contact land	b	100 to 120 μ m
	С	Adhesives shall not contact land





4. Soldering

Precautions

Technical

considerations

◆Selection of Flux

Since flux may have a significant effect on the performance of capacitors, it is necessary to verify the following conditions prior to use;

- (1) Flux used shall be less than or equal to 0.1 wt%(in CI equivalent) of halogenated content. Flux having a strong acidity content shall not be applied.
- (2) When shall capacitors are soldered on boards, the amount of flux applied shall be controlled at the optimum level.
- (3) When water-soluble flux is used, special care shall be taken to properly clean the boards.

♦Soldering

Temperature, time, amount of solder, etc. shall be set in accordance with their recommended conditions.

Sn-Zn solder paste can adversely affect MLCC reliability.

For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/) .

Please contact us prior to usage of Sn-Zn solder.

◆Selection of Flux

- 1-1. When too much halogenated substance (Chlorine, etc.) content is used to activate flux, or highly acidic flux is used, it may lead to corrosion of terminal electrodes or degradation of insulation resistance on the surfaces of the capacitors.
- 1-2. Flux is used to increase solderability in wave soldering. However if too much flux is applied, a large amount of flux gas may be emitted and may adversely affect the solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.
- 1-3. Since the residue of water-soluble flux is easily dissolved in moisture in the air, the residues on the surfaces of capacitors in high humidity conditions may cause a degradation of insulation resistance and reliability of the capacitors. Therefore, the cleaning methods and the capability of the machines used shall also be considered carefully when water-soluble flux is used.

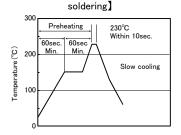
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♦Soldering

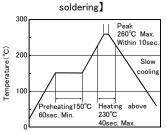
- · Ceramic chip capacitors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling.
- · Therefore, the soldering must be conducted with great care so as to prevent malfunction of the components due to excessive thermal shock
- Preheating: Capacitors shall be preheated sufficiently, and the temperature difference between the capacitors and solder shall be within 130°C.
- · Cooling: The temperature difference between the capacitors and cleaning process shall not be greater than 100°C.

[Reflow soldering]

[Recommended conditions for eutectic

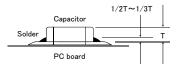


[Recommended condition for Pb-free



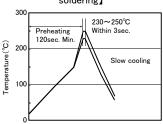
Caution

- 1The ideal condition is to have solder mass(fillet)controlled to 1/2 to 1/3 of the thickness of a capacitor.
- ②Because excessive dwell times can adversely affect solderability, soldering duration shall be kept as close to recommended times as possible. soldering for 2 times.

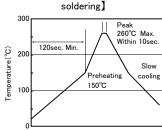


[Wave soldering]

[Recommended conditions for eutectic soldering]



[Recommended condition for Pb-free

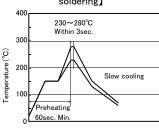


Caution

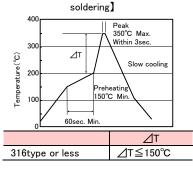
①Wave soldering must not be applied to capacitors designated as for reflow soldering only. soldering for 1 times.

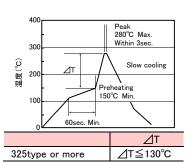
[Hand soldering]

【Recommended conditions for eutectic soldering】



[Recommended condition for Pb-free





Caution

- ①Use a 50W soldering iron with a maximum tip diameter of 1.0 mm.
- 2The soldering iron shall not directly touch capacitors. soldering for 1 times.

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5. Cleaning Cleaning conditions 1. When PCBs are cleaned after capacitors mounting, please select the appropriate cleaning solution in accordance with the intended use Precautions of the cleaning. (e.g. to remove soldering flux or other materials from the production process.) 2. Cleaning condition shall be determined after it is verified by using actual cleaning machine that the cleaning process does not affect capacitor's characteristics. 1. The use of inappropriate cleaning solutions can cause foreign substances such as flux residue to adhere to capacitors or deteriorate their outer coating, resulting in a degradation of the capacitor's electrical properties (especially insulation resistance). 2. Inappropriate cleaning conditions (insufficient or excessive cleaning) may adversely affect the performance of the capacitors. In the case of ultrasonic cleaning, too much power output can cause excessive vibration of PCBs which may lead to the cracking of Technical considerations capacitors or the soldered portion, or decrease the terminal electrodes' strength. Therefore, the following conditions shall be carefully checked: 40 kHz or less Ultrasonic output: 20 W/Q or les Ultrasonic frequency: Ultrasonic washing period: 5 min. or less

6. Resin coating and mold

Precautions

- 1. With some type of resins, decomposition gas or chemical reaction vapor may remain inside the resin during the hardening period or while left under normal storage conditions resulting in the deterioration of the capacitor's performance.
- 2. When a resin's hardening temperature is higher than capacitor's operating temperature, the stresses generated by the excessive heat may lead to damage or destruction of capacitors.

1. When PCBs are split after components mounting, care shall be taken so as not to give any stresses of deflection or twisting to the board.

The use of such resins, molding materials etc. is not recommended.

7. Handling

♦Splitting of PCB

Precautions

◆Mechanical considerations

Be careful not to subject capacitors to excessive mechanical shocks.

(1) If ceramic capacitors are dropped onto a floor or a hard surface, they shall not be used.

2. Board separation shall not be done manually, but by using the appropriate devices.

(2) Please be careful that the mounted components do not come in contact with or bump against other boards or components.

8. Storage conditions

♦Storage

- 1. To maintain the solderability of terminal electrodes and to keep packaging materials in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible.
 - Recommended conditions

Precautions

Ambient temperature : Below 30°C Humidity : Below 70% RH

The ambient temperature must be kept below 40° C. Even under ideal storage conditions, solderability of capacitor is deteriorated as time passes, so capacitors shall be used within 6 months from the time of delivery.

- ·Ceramic chip capacitors shall be kept where no chlorine or sulfur exists in the air.
- The capacitance values of high dielectric constant capacitors will gradually decrease with the passage of time, so care shall be taken to
 design circuits. Even if capacitance value decreases as time passes, it will get back to the initial value by a heat treatment at 150°C for
 1hour.

Technical considerations

If capacitors are stored in a high temperature and humidity environment, it might rapidly cause poor solderability due to terminal oxidation and quality loss of taping/packaging materials. For this reason, capacitors shall be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the capacitors.

**RCR-2335B(Safety Application Guide for fixed ceramic capacitors for use in electronic equipment) is published by JEITA.

Please check the guide regarding precautions for deflection test, soldering by spot heat, and so on.

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